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New 8FX 8-bit Microcontrollers

The CY95630H Series is a series of general-purpose, single-chip microcontrollers. In addition to a compact instruction set, the microcontrollers of this series contain a variety of peripheral functions.

Features

- F²MC-8FX CPU core
 - Instruction set optimized for controllers
 - Multiplication and division instructions
 - 16-bit arithmetic operations
 - Bit test branch instructions
 - Bit manipulation instructions, etc.
- Clock
 - Selectable main clock source
 - Main oscillation clock (up to 16.25 MHz, maximum machine clock frequency: 8.125 MHz)
 - External clock (up to 32.5 MHz, maximum machine clock frequency: 16.25 MHz)
 - Main CR clock (4 MHz ±2%)
 - Main CR PLL clock
 - The main CR PLL clock frequency becomes 8 MHz ±2% when the PLL multiplication rate is 2.
 - The main CR PLL clock frequency becomes 10 MHz ±2% when the PLL multiplication rate is 2.5.
 - The main CR PLL clock frequency becomes 12 MHz ±2% when the PLL multiplication rate is 3.
 - The main CR PLL clock frequency becomes 16 MHz ±2% when the PLL multiplication rate is 4.
 - Selectable subclock source
 - Suboscillation clock (32.768 kHz)
 - External clock (32.768 kHz)
 - Sub-CR clock (Typ: 100 kHz, Min: 50 kHz, Max: 150 kHz)
- Timer
 - 8/16-bit composite timer × 2 channels
 - 8/16-bit PPG × 3 channels
 - 16-bit PPG timer × 1 channel (can work independently or together with the multi-pulse generator)
 - 16-bit reload timer × 1 channel (can work independently or together with the multi-pulse generator)
 - Time-base timer × 1 channel
 - Watch prescaler × 1 channel
- UART/SIO × 1 channel
 - Full duplex double buffer
 - Capable of clock asynchronous (UART) serial data transfer and clock synchronous (SIO) serial data transfer
- I²C bus interface × 1 channel
 - Built-in wake-up function
- Multi-pulse generator (MPG) (for DC motor control) × 1 channel
 - 16-bit reload timer × 1 channel
 - 16-bit PPG timer × 1 channel
 - Waveform sequencer (including a 16-bit timer equipped with a buffer and a compare clear function)
- LIN-UART
 - Full duplex double buffer
- Capable of clock asynchronous serial data transfer and clock synchronous serial data transfer
- External interrupt × 10 channels
 - Interrupt by edge detection (rising edge, falling edge, and both edges can be selected)
 - Can be used to wake up the device from different low power consumption (standby) modes
- 8/10-bit A/D converter × 8 channels
 - 8-bit or 10-bit resolution can be selected.
- Low power consumption (standby) modes
 - There are four standby modes as follows:
 - Stop mode
 - Sleep mode
 - Watch mode
 - Time-base timer mode
 - In standby mode, two further options can be selected: normal standby mode and deep standby mode.
- I/O port
 - CY95F632H/F633H/F634H/F636H (number of I/O ports: 28)
 - General-purpose I/O ports (CMOS I/O): 25
 - General-purpose I/O ports (N-ch open drain): 3
 - CY95F632K/F633K/F634K/F636K (number of I/O ports: 29)
 - General-purpose I/O ports (CMOS I/O): 25
 - General-purpose I/O ports (N-ch open drain): 4
- On-chip debug
 - 1-wire serial control
 - Serial writing supported (asynchronous mode)
- Hardware/software watchdog timer
 - Built-in hardware watchdog timer
 - Built-in software watchdog timer
- Power-on reset
 - A power-on reset is generated when the power is switched on.
- Low-voltage detection reset circuit (only available on CY95F632K/F633K/F634K/F636K)
 - Built-in low-voltage detection function (The combination of detection voltage and release voltage can be selected from four options.)
- Comparator
- Clock supervisor counter
 - Built-in clock supervisor counter
- Dual operation Flash memory
 - The program/erase operation and the read operation can be executed in different banks (upper bank/lower bank) simultaneously.
- Flash memory security function
 - Protects the content of the Flash memory.

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1. Product Line-up

| Part number | CY95F632H | CY95F633H | CY95F634H | CY95F636H | CY95F632K | CY95F633K | CY95F634K | CY95F636K |
|----------------------------------|---|-----------|------------|------------|---|-----------|------------|------------|
| Parameter | | | | | | | | |
| Type | Flash memory product | | | | | | | |
| Clock supervisor counter | It supervises the main clock oscillation and the subclock oscillation. | | | | | | | |
| Flash memory capacity | 8 Kbyte | 12 Kbyte | 20 Kbyte | 36 Kbyte | 8 Kbyte | 12 Kbyte | 20 Kbyte | 36 Kbyte |
| RAM capacity | 256 bytes | 512 bytes | 1024 bytes | 1024 bytes | 256 bytes | 512 bytes | 1024 bytes | 1024 bytes |
| Power-on reset | Yes | | | | | | | |
| Low-voltage detection reset | No | | | | Yes | | | |
| Reset input | Dedicated | | | | Selected through software | | | |
| CPU functions | <ul style="list-style-type: none"> • Number of basic instructions : 136 • Instruction bit length : 8 bits • Instruction length : 1 to 3 bytes • Data bit length : 1, 8 and 16 bits • Minimum instruction execution time : 61.5 ns (machine clock frequency = 16.25 MHz) • Interrupt processing time : 0.6 μs (machine clock frequency = 16.25 MHz) | | | | | | | |
| General-purpose I/O | <ul style="list-style-type: none"> • I/O port : 28 • CMOS I/O : 25 • N-ch open drain : 3 | | | | <ul style="list-style-type: none"> • I/O port : 29 • CMOS I/O : 25 • N-ch open drain : 4 | | | |
| Time-base timer | Interval time: 0.256 ms to 8.3 s (external clock frequency = 4 MHz) | | | | | | | |
| Hardware/software watchdog timer | <ul style="list-style-type: none"> • Reset generation cycle Main oscillation clock at 10 MHz: 105 ms (Min) • The sub-CR clock can be used as the source clock of the software watchdog timer. | | | | | | | |
| Wild register | It can be used to replace 3 bytes of data. | | | | | | | |
| LIN-UART | <ul style="list-style-type: none"> • A wide range of communication speed can be selected by a dedicated reload timer. • It has a full duplex double buffer. • Both clock synchronous serial data transfer and clock asynchronous serial data transfer are enabled. • The LIN function can be used as a LIN master or a LIN slave. | | | | | | | |
| 8/10-bit A/D converter | 8 channels | | | | | | | |
| | 8-bit or 10-bit resolution can be selected. | | | | | | | |
| 8/16-bit composite timer | 2 channels | | | | | | | |
| | <ul style="list-style-type: none"> • The timer can be configured as an “8-bit timer × 2 channels” or a “16-bit timer × 1 channel”. • It has the following functions: interval timer function, PWC function, PWM function and input capture function. • Count clock: it can be selected from internal clocks (seven types) and external clocks. • It can output square wave. | | | | | | | |

| Part number | CY95F632H | CY95F633H | CY95F634H | CY95F636H | CY95F632K | CY95F633K | CY95F634K | CY95F636K |
|--|---|-----------|-----------|-----------|-----------|-----------|-----------|-----------|
| Parameter | | | | | | | | |
| External interrupt | 10 channels <ul style="list-style-type: none"> Interrupt by edge detection (The rising edge, falling edge, and both edges can be selected.) It can be used to wake up the device from different standby modes. | | | | | | | |
| On-chip debug | <ul style="list-style-type: none"> 1-wire serial control It supports serial writing (asynchronous mode). | | | | | | | |
| UART/SIO | 1 channel <ul style="list-style-type: none"> Data transfer with UART/SIO is enabled. It has a full duplex double buffer, variable data length (5/6/7/8 bits), an internal baud rate generator and an error detection function. It uses the NRZ type transfer format. LSB-first data transfer and MSB-first data transfer are available to use. Both clock asynchronous (UART) serial data transfer and clock synchronous (SIO) serial data transfer are enabled. | | | | | | | |
| I ² C bus interface | 1 channel <ul style="list-style-type: none"> Master/slave transmission and reception It has the following functions: bus error function, arbitration function, transfer direction detection function, wake-up function, and functions of generating and detecting repeated START conditions. | | | | | | | |
| 8/16-bit PPG | 3 channels <ul style="list-style-type: none"> Each channel can be used as an “8-bit timer × 2 channels” or a “16-bit timer × 1 channel”. The counter operating clock can be selected from eight clock sources. | | | | | | | |
| 16-bit PPG timer | 1 channel <ul style="list-style-type: none"> PWM mode and one-shot mode are available to use. The counter operating clock can be selected from eight clock sources. It supports external trigger start. It can work independently or together with the multi-pulse generator. | | | | | | | |
| 16-bit reload timer | 1 channel <ul style="list-style-type: none"> Two clock modes and two counter operating modes are available to use. It can output square wave. Count clock: it can be selected from internal clocks (seven types) and external clocks. Two counter operating modes: reload mode and one-shot mode It can work independently or together with the multi-pulse generator. | | | | | | | |
| Multi-pulse generator (for DC motor control) | <ul style="list-style-type: none"> 16-bit PPG timer: 1 channel 16-bit reload timer operations: toggle output, one-shot output Event counter: 1 channel Waveform sequencer (including a 16-bit timer equipped with a buffer and a compare clear function) | | | | | | | |
| Watch prescaler | Eight different time intervals can be selected. | | | | | | | |
| Comparator | 1 channel | | | | | | | |

| Part number | CY95F632H | CY95F633H | CY95F634H | CY95F636H | CY95F632K | CY95F633K | CY95F634K | CY95F636K | | | | | | | | |
|--------------------------------|---|-----------|-----------|-----------|-----------|-----------|-----------|-----------|--------------------------------|------|-------|--------|---------------------|----------|----------|---------|
| Parameter | | | | | | | | | | | | | | | | |
| Flash memory | <ul style="list-style-type: none"> It supports automatic programming (Embedded Algorithm), and program/erase/erase-suspend/erase-resume commands. It has a flag indicating the completion of the operation of Embedded Algorithm. Flash security feature for protecting the content of the Flash memory <table border="1"> <tr> <td>Number of program/erase cycles</td> <td>1000</td> <td>10000</td> <td>100000</td> </tr> <tr> <td>Data retention time</td> <td>20 years</td> <td>10 years</td> <td>5 years</td> </tr> </table> | | | | | | | | Number of program/erase cycles | 1000 | 10000 | 100000 | Data retention time | 20 years | 10 years | 5 years |
| Number of program/erase cycles | 1000 | 10000 | 100000 | | | | | | | | | | | | | |
| Data retention time | 20 years | 10 years | 5 years | | | | | | | | | | | | | |
| Standby mode | <p>There are four standby modes as follows:</p> <ul style="list-style-type: none"> Stop mode Sleep mode Watch mode Time-base timer mode <p>In standby mode, two further options can be selected: normal standby mode and deep standby mode.</p> | | | | | | | | | | | | | | | |
| Package | LQB032 PDS032 WNP032 | | | | | | | | | | | | | | | |

2. Packages And Corresponding Products

| Part number | CY95F632H | CY95F633H | CY95F634H | CY95F636H | CY95F632K | CY95F633K | CY95F634K | CY95F636K |
|-------------|-----------|-----------|-----------|-----------|-----------|-----------|-----------|-----------|
| Package | | | | | | | | |
| LQB032 | O | O | O | O | O | O | O | O |
| PDS032 | O | O | O | O | O | O | O | O |
| WNP032 | O | O | O | O | O | O | O | O |

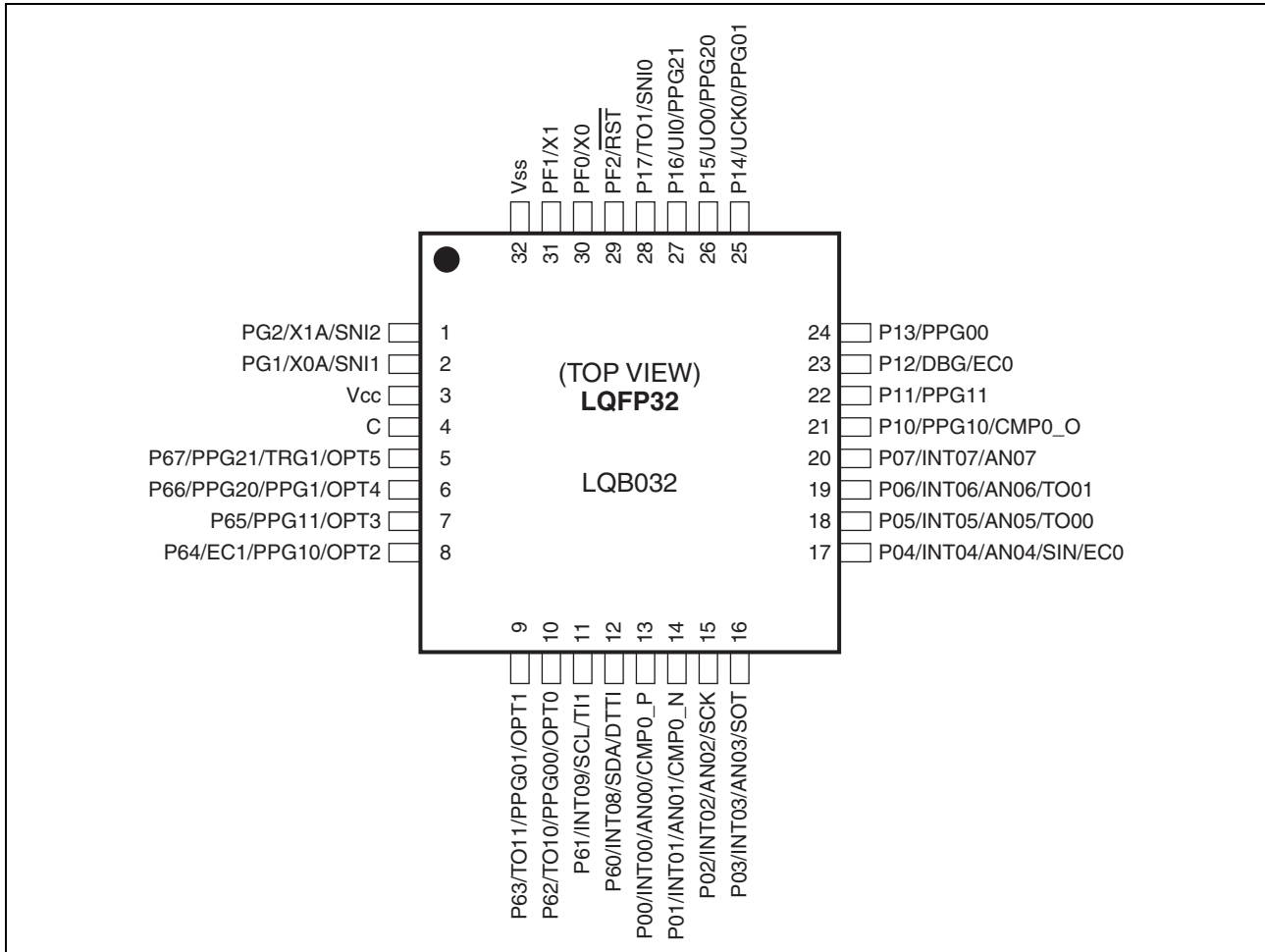
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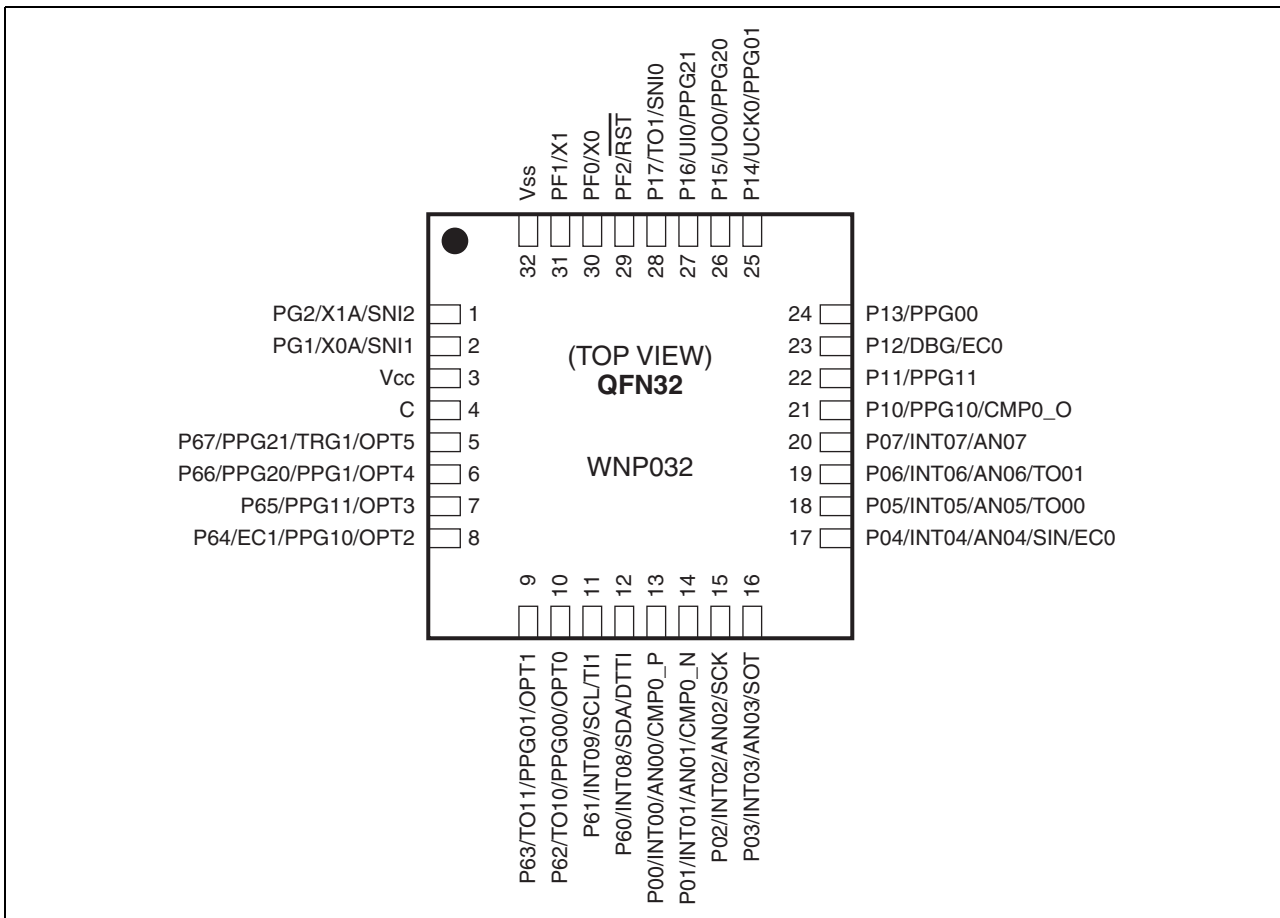
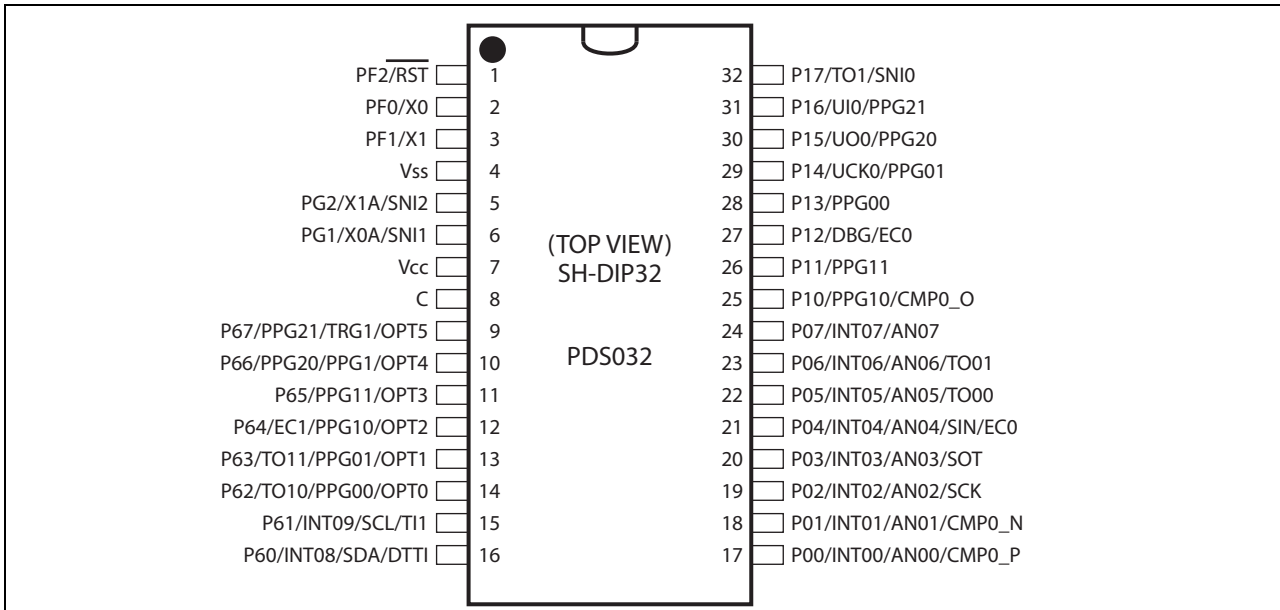
3. Differences Among Products And Notes On Product Selection

- Current consumption
When using the on-chip debug function, take account of the current consumption of Flash memory program/erase. For details of current consumption, see “Electrical Characteristics”.
- Package
For details of information on each package, see “Packages And Corresponding Products” and “Package Dimension”.
- Operating voltage
The operating voltage varies, depending on whether the on-chip debug function is used or not. For details of operating voltage, see “Electrical Characteristics”.
- On-chip debug function

The on-chip debug function requires that V_{cc}, V_{ss} and one serial wire be connected to an evaluation tool. For details of the connection method, refer to “CHAPTER 25 EXAMPLE OF SERIAL PROGRAMMING CONNECTION” in “New 8FX CY95630H Series Hardware Manual”.

4. Pin Assignment





5. Pin Functions

| Pin no. | | Pin name | I/O circuit type*4 | Function | I/O type | | | |
|----------------------|------------|----------|--------------------|---|------------|--------|------|------|
| LQFP32*1, QFN32*2 | SH-DIP32*3 | | | | Input | Output | OD*5 | PU*6 |
| 1 | 5 | PG2 | C | General-purpose I/O port | Hysteresis | CMOS | — | 0 |
| | | X1A | | Subclock I/O oscillation pin | | | | |
| | | SNI2 | | Trigger input pin for the position detection function of the MPG waveform sequencer | | | | |
| 2 | 6 | PG1 | C | General-purpose I/O port | Hysteresis | CMOS | — | 0 |
| | | X0A | | Subclock input oscillation pin | | | | |
| | | SNI1 | | Trigger input pin for the position detection function of the MPG waveform sequencer | | | | |
| 3 | 7 | Vcc | — | Power supply pin | — | — | — | — |
| 4 | 8 | C | — | Decoupling capacitor connection pin | — | — | — | — |
| 5 | 9 | P67 | D | General-purpose I/O port High-current pin | Hysteresis | CMOS | — | 0 |
| | | PPG21 | | 8/16-bit PPG ch. 2 output pin | | | | |
| | | TRG1 | | 16-bit PPG timer ch. 1 trigger input pin | | | | |
| | | OPT5 | | MPG waveform sequencer output pin | | | | |
| 6 | 10 | P66 | D | General-purpose I/O port High-current pin | Hysteresis | CMOS | — | 0 |
| | | PPG20 | | 8/16-bit PPG ch. 2 output pin | | | | |
| | | PPG1 | | 16-bit PPG timer ch. 1 output pin | | | | |
| | | OPT4 | | MPG waveform sequencer output pin | | | | |
| 7 | 11 | P65 | D | General-purpose I/O port High-current pin | Hysteresis | CMOS | — | 0 |
| | | PPG11 | | 8/16-bit PPG ch. 1 output pin | | | | |
| | | OPT3 | | MPG waveform sequencer output pin | | | | |
| 8 | 12 | P64 | D | General-purpose I/O port High-current pin | Hysteresis | CMOS | — | 0 |
| | | EC1 | | 8/16-bit composite timer ch. 1 clock input pin | | | | |
| | | PPG10 | | 8/16-bit PPG ch. 1 output pin | | | | |
| | | OPT2 | | MPG waveform sequencer output pin | | | | |

| Pin no. | | Pin name | I/O circuit type*4 | Function | I/O type | | | |
|----------------------|------------|----------|--------------------|---|-----------------------|--------|------|------|
| LQFP32*1, QFN32*2 | SH-DIP32*3 | | | | Input | Output | OD*5 | PU*6 |
| 9 | 13 | P63 | D | General-purpose I/O port High-current pin | Hysteresis | CMOS | — | O |
| | | TO11 | | 8/16-bit composite timer ch. 1 output pin | | | | |
| | | PPG01 | | 8/16-bit PPG ch. 0 output pin | | | | |
| | | OPT1 | | MPG waveform sequencer output pin | | | | |
| 10 | 14 | P62 | D | General-purpose I/O port High-current pin | Hysteresis | CMOS | — | O |
| | | TO10 | | 8/16-bit composite timer ch. 1 output pin | | | | |
| | | PPG00 | | 8/16-bit PPG ch. 0 output pin | | | | |
| | | OPT0 | | MPG waveform sequencer output pin | | | | |
| 11 | 15 | P61 | I | General-purpose I/O port | CMOS | CMOS | O | — |
| | | INT09 | | External interrupt input pin | | | | |
| | | SCL | | I ² C bus interface ch. 0 clock I/O pin | | | | |
| | | TI1 | | 16-bit reload timer ch. 1 input pin | | | | |
| 12 | 16 | P60 | I | General-purpose I/O port | CMOS | CMOS | O | — |
| | | INT08 | | External interrupt input pin | | | | |
| | | SDA | | I ² C bus interface ch. 0 data I/O pin | | | | |
| | | DTTI | | MPG waveform sequencer input pin | | | | |
| 13 | 17 | P00 | E | General-purpose I/O port | Hysteresis/ analog | CMOS | — | O |
| | | INT00 | | External interrupt input pin | | | | |
| | | AN00 | | 8/10-bit A/D converter analog input pin | | | | |
| | | CMP0_P | | Comparator non-inverting analog input (positive input) pin | | | | |
| 14 | 18 | P01 | E | General-purpose I/O port | Hysteresis/ analog | CMOS | — | O |
| | | INT01 | | External interrupt input pin | | | | |
| | | AN01 | | 8/10-bit A/D converter analog input pin | | | | |
| | | CMP0_N | | Comparator inverting analog input (negative input) pin | | | | |

| Pin no. | | Pin name | I/O circuit type*4 | Function | I/O type | | | |
|----------------------|------------|----------|--------------------|--|-----------------------|--------|------|------|
| LQFP32*1, QFN32*2 | SH-DIP32*3 | | | | Input | Output | OD*5 | PU*6 |
| 15 | 19 | P02 | E | General-purpose I/O port | Hysteresis/ analog | CMOS | — | O |
| | | INT02 | | External interrupt input pin | | | | |
| | | AN02 | | 8/10-bit A/D converter analog input pin | | | | |
| | | SCK | | LIN-UART clock I/O pin | | | | |
| 16 | 20 | P03 | E | General-purpose I/O port | Hysteresis/ analog | CMOS | — | O |
| | | INT03 | | External interrupt input pin | | | | |
| | | AN03 | | 8/10-bit A/D converter analog input pin | | | | |
| | | SOT | | LIN-UART data output pin | | | | |
| 17 | 21 | P04 | F | General-purpose I/O port | CMOS/ analog | CMOS | — | O |
| | | INT04 | | External interrupt input pin | | | | |
| | | AN04 | | 8/10-bit A/D converter analog input pin | | | | |
| | | SIN | | LIN-UART data input pin | | | | |
| | | EC0 | | 8/16-bit composite timer ch. 0 clock input pin | | | | |
| 18 | 22 | P05 | E | General-purpose I/O port | Hysteresis/ analog | CMOS | — | O |
| | | INT05 | | External interrupt input pin | | | | |
| | | AN05 | | 8/10-bit A/D converter analog input pin | | | | |
| | | TO00 | | 8/16-bit composite timer ch. 0 output pin | | | | |
| 19 | 23 | P06 | E | General-purpose I/O port | Hysteresis/ analog | CMOS | — | O |
| | | INT06 | | External interrupt input pin | | | | |
| | | AN06 | | 8/10-bit A/D converter analog input pin | | | | |
| | | TO01 | | 8/16-bit composite timer ch. 0 output pin | | | | |
| 20 | 24 | P07 | E | General-purpose I/O port | Hysteresis/ analog | CMOS | — | O |
| | | INT07 | | External interrupt input pin | | | | |
| | | AN07 | | 8/10-bit A/D converter analog input pin | | | | |
| 21 | 25 | P10 | G | General-purpose I/O port | Hysteresis | CMOS | — | O |
| | | PPG10 | | 8/16-bit PPG ch. 1 output pin | | | | |
| | | CMP0_O | | Comparator digital output pin | | | | |

| Pin no. | | Pin name | I/O circuit type*4 | Function | I/O type | | | |
|----------------------|------------|-------------------------|--------------------|---|------------|--------|------|------|
| LQFP32*1, QFN32*2 | SH-DIP32*3 | | | | Input | Output | OD*5 | PU*6 |
| 22 | 26 | P11 | G | General-purpose I/O port | Hysteresis | CMOS | — | O |
| | | PPG11 | | 8/16-bit PPG ch. 1 output pin | | | | |
| 23 | 27 | P12 | H | General-purpose I/O port | Hysteresis | CMOS | O | — |
| | | DBG | | DBG input pin | | | | |
| | | EC0 | | 8/16-bit composite timer ch. 0 clock input pin | | | | |
| 24 | 28 | P13 | G | General-purpose I/O port | Hysteresis | CMOS | — | O |
| | | PPG00 | | 8/16-bit PPG ch. 0 output pin | | | | |
| 25 | 29 | P14 | G | General-purpose I/O port | Hysteresis | CMOS | — | O |
| | | UCK0 | | UART/SIO ch. 0 clock I/O pin | | | | |
| | | PPG01 | | 8/16-bit PPG ch. 0 output pin | | | | |
| 26 | 30 | P15 | G | General-purpose I/O port | Hysteresis | CMOS | — | O |
| | | UO0 | | UART/SIO ch. 0 data output pin | | | | |
| | | PPG20 | | 8/16-bit PPG ch. 2 output pin | | | | |
| 27 | 31 | P16 | J | General-purpose I/O port | CMOS | CMOS | — | O |
| | | UI0 | | UART/SIO ch. 0 data input pin | | | | |
| | | PPG21 | | 8/16-bit PPG ch. 2 output pin | | | | |
| 28 | 32 | P17 | G | General-purpose I/O port | Hysteresis | CMOS | — | O |
| | | TO1 | | 16-bit reload timer ch. 1 output pin | | | | |
| | | SNIO | | Trigger input pin for the position detection function of the MPG waveform sequencer | | | | |
| 29 | 1 | PF2 | A | General-purpose I/O port | Hysteresis | CMOS | O | — |
| | | $\overline{\text{RST}}$ | | Reset pin Dedicated reset pin on CY95F632H/F633H/F634H/ F636H | | | | |
| 30 | 2 | PF0 | B | General-purpose I/O port | Hysteresis | CMOS | — | — |
| | | X0 | | Main clock input oscillation pin | | | | |
| 31 | 3 | PF1 | B | General-purpose I/O port | Hysteresis | CMOS | — | — |
| | | X1 | | Main clock I/O oscillation pin | | | | |
| 32 | 4 | V _{SS} | — | Power supply pin (GND) | — | — | — | — |

O: Available

*4: For the I/O circuit types, see "I/O Circuit Type".

*5: N-ch open drain

*6: Pull-up

*1: LQB032

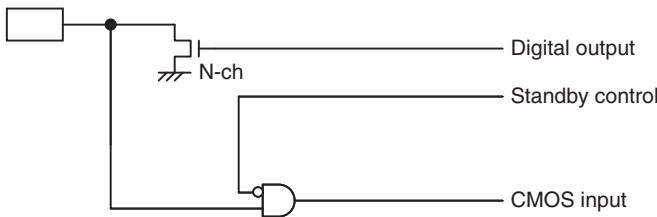
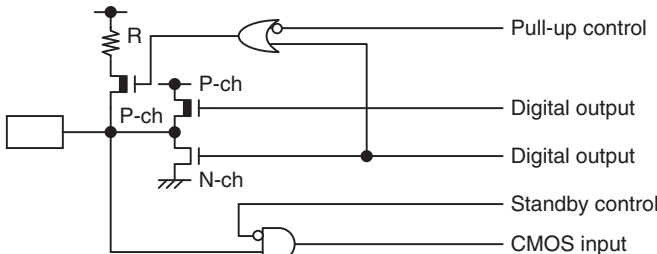
*2: WNP032

*3: PDS032

6. I/O Circuit Type

| Type | Circuit | Remarks |
|------|---------|---|
| A | | <ul style="list-style-type: none"> • N-ch open drain output • Hysteresis input • Reset output |
| B | | <ul style="list-style-type: none"> • Oscillation circuit • High-speed side Feedback resistance: approx. 1 MΩ • CMOS output • Hysteresis input |
| C | | <ul style="list-style-type: none"> • Oscillation circuit • Low-speed side Feedback resistance: approx. 5 MΩ • CMOS output • Hysteresis input • Pull-up control |

| Type | Circuit | Remarks |
|------|---------|---|
| D | | <ul style="list-style-type: none"> • CMOS output • Hysteresis input • Pull-up control • High current output |
| E | | <ul style="list-style-type: none"> • CMOS output • Hysteresis input • Pull-up control • Analog input |
| F | | <ul style="list-style-type: none"> • CMOS output • CMOS input • Pull-up control • Analog input |
| G | | <ul style="list-style-type: none"> • CMOS output • Hysteresis input • Pull-up control |
| H | | <ul style="list-style-type: none"> • N-ch open drain output • Hysteresis input |

| Type | Circuit | Remarks |
|------|---|--|
| I |  | <ul style="list-style-type: none"> • N-ch open drain output • CMOS input |
| J |  | <ul style="list-style-type: none"> • CMOS output • CMOS input • Pull-up control |

7. Handling Precautions

Any semiconductor devices have inherently a certain rate of failure. The possibility of failure is greatly affected by the conditions in which they are used (circuit conditions, environmental conditions, etc.). This page describes precautions that must be observed to minimize the chance of failure and to obtain higher reliability from your Cypress semiconductor devices.

7.1 Precautions for Product Design

This section describes precautions when designing electronic equipment using semiconductor devices.

• Absolute Maximum Ratings

Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of certain established limits, called absolute maximum ratings. Do not exceed these ratings.

• Recommended Operating Conditions

Recommended operating conditions are normal operating ranges for the semiconductor device. All the device's electrical characteristics are warranted when operated within these ranges.

Always use semiconductor devices within the recommended operating conditions. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their sales representative beforehand.

• Processing and Protection of Pins

These precautions must be followed when handling the pins which connect semiconductor devices to power supply and input/output functions.

(1) Preventing Over-Voltage and Over-Current Conditions

Exposure to voltage or current levels in excess of maximum ratings at any pin is likely to cause deterioration within the device, and in extreme cases leads to permanent damage of the device. Try to prevent such overvoltage or over-current conditions at the design stage.

(2) Protection of Output Pins

Shorting of output pins to supply pins or other output pins, or connection to large capacitance can cause large current flows. Such conditions if present for extended periods of time can damage the device.

Therefore, avoid this type of connection.

(3) Handling of Unused Input Pins

Unconnected input pins with very high impedance levels can adversely affect stability of operation. Such pins should be connected through an appropriate resistance to a power supply pin or ground pin.

• Latch-up

Semiconductor devices are constructed by the formation of P-type and N-type areas on a substrate. When subjected to abnormally high voltages, internal parasitic PNP junctions (called thyristor structures) may be formed, causing large current levels in excess of several hundred mA to flow continuously at the power supply pin. This condition is called latch-up.

CAUTION: The occurrence of latch-up not only causes loss of reliability in the semiconductor device, but can cause injury or damage from high heat, smoke or flame. To prevent this from happening, do the following:

- (1) Be sure that voltages applied to pins do not exceed the absolute maximum ratings. This should include attention to abnormal noise, surge levels, etc.
- (2) Be sure that abnormal current flows do not occur during the power-on sequence.

• Observance of Safety Regulations and Standards

Most countries in the world have established standards and regulations regarding safety, protection from electromagnetic interference, etc. Customers are requested to observe applicable regulations and standards in the design of products.

• Fail-Safe Design

Any semiconductor devices have inherently a certain rate of failure. You must protect against injury, damage or loss from such failures by incorporating safety design measures into your facility and equipment such as redundancy, fire protection, and prevention of over-current levels and other abnormal operating conditions.

• Precautions Related to Usage of Devices

Cypress semiconductor devices are intended for use in standard applications (computers, office automation and other office equipment, industrial, communications, and measurement equipment, personal or household devices, etc.).

CAUTION: Customers considering the use of our products in special applications where failure or abnormal operation may directly affect human lives or cause physical injury or property damage, or where extremely high levels of reliability are demanded (such as aerospace systems, atomic energy controls, sea floor repeaters, vehicle operating controls, medical devices for life support, etc.) are requested to consult with sales representatives before such use. The company will not be responsible for damages arising from such use without prior approval.

7.2 Precautions for Package Mounting

Package mounting may be either lead insertion type or surface mount type. In either case, for heat resistance during soldering, you should only mount under Cypress's recommended conditions. For detailed information about mount conditions, contact your sales representative.

• Lead Insertion Type

Mounting of lead insertion type packages onto printed circuit boards may be done by two methods: direct soldering on the board, or mounting by using a socket.

Direct mounting onto boards normally involves processes for inserting leads into through-holes on the board and using the flow soldering (wave soldering) method of applying liquid solder. In this case, the soldering process usually

causes leads to be subjected to thermal stress in excess of the absolute ratings for storage temperature. Mounting processes should conform to Cypress recommended mounting conditions.

If socket mounting is used, differences in surface treatment of the socket contacts and IC lead surfaces can lead to contact deterioration after long periods. For this reason it is recommended that the surface treatment of socket contacts and IC leads be verified before mounting.

- **Surface Mount Type**

Surface mount packaging has longer and thinner leads than lead-insertion packaging, and therefore leads are more easily deformed or bent. The use of packages with higher pin counts and narrower pin pitch results in increased susceptibility to open connections caused by deformed pins, or shorting due to solder bridges.

You must use appropriate mounting techniques. Cypress recommends the solder reflow method, and has established a ranking of mounting conditions for each product. Users are advised to mount packages in accordance with Cypress ranking of recommended conditions.

- **Lead-Free Packaging**

CAUTION: When ball grid array (BGA) packages with Sn-Ag-Cu balls are mounted using Sn-Pb eutectic soldering, junction strength may be reduced under some conditions of use.

- **Storage of Semiconductor Devices**

Because plastic chip packages are formed from plastic resins, exposure to natural environmental conditions will cause absorption of moisture. During mounting, the application of heat to a package that has absorbed moisture can cause surfaces to peel, reducing moisture resistance and causing packages to crack. To prevent, do the following:

- (1) Avoid exposure to rapid temperature changes, which cause moisture to condense inside the product. Store products in locations where temperature changes are slight.
- (2) Use dry boxes for product storage. Products should be stored below 70% relative humidity, and at temperatures between 5°C and 30°C.
When you open Dry Package that recommends humidity 40% to 70% relative humidity.
- (3) When necessary, Cypress packages semiconductor devices in highly moisture-resistant aluminum laminate bags, with a silica gel desiccant. Devices should be sealed in their aluminum laminate bags for storage.
- (4) Avoid storing packages where they are exposed to corrosive gases or high levels of dust.

- **Baking**

Packages that have absorbed moisture may be de-moisturized by baking (heat drying). Follow the Cypress recommended conditions for baking.

Condition: 125°C/24 h

- **Static Electricity**

Because semiconductor devices are particularly susceptible to damage by static electricity, you must take the following precautions:

- (1) Maintain relative humidity in the working environment between 40% and 70%.
Use of an apparatus for ion generation may be needed to remove electricity.
- (2) Electrically ground all conveyors, solder vessels, soldering irons and peripheral equipment.
- (3) Eliminate static body electricity by the use of rings or bracelets connected to ground through high resistance (on the level of 1 MΩ).
Wearing of conductive clothing and shoes, use of conductive floor mats and other measures to minimize shock loads is recommended.
- (4) Ground all fixtures and instruments, or protect with anti-static measures.
- (5) Avoid the use of styrofoam or other highly static-prone materials for storage of completed board assemblies.

7.3 Precautions for Use Environment

Reliability of semiconductor devices depends on ambient temperature and other conditions as described above.

For reliable performance, do the following:

(1) Humidity

Prolonged use in high humidity can lead to leakage in devices as well as printed circuit boards. If high humidity levels are anticipated, consider anti-humidity processing.

(2) Discharge of Static Electricity

When high-voltage charges exist close to semiconductor devices, discharges can cause abnormal operation. In such cases, use anti-static measures or processing to prevent discharges.

(3) Corrosive Gases, Dust, or Oil

Exposure to corrosive gases or contact with dust or oil may lead to chemical reactions that will adversely affect the device. If you use devices in such conditions, consider ways to prevent such exposure or to protect the devices.

(4) Radiation, Including Cosmic Radiation

Most devices are not designed for environments involving exposure to radiation or cosmic radiation. Users should provide shielding as appropriate.

(5) Smoke, Flame

CAUTION: Plastic molded devices are flammable, and therefore should not be used near combustible substances. If devices begin to smoke or burn, there is danger of the release of toxic gases.

Customers considering the use of Cypress products in other special environmental conditions should consult with sales representatives.

8. Notes On Device Handling

- Preventing latch-ups

When using the device, ensure that the voltage applied does not exceed the maximum voltage rating.

In a CMOS IC, if a voltage higher than V_{CC} or a voltage lower than V_{SS} is applied to an input/output pin that is neither a medium-withstand voltage pin nor a high-withstand voltage pin, or if a voltage out of the rating range of power supply voltage mentioned in “18.1 Absolute Maximum Ratings” of “Electrical Characteristics” is applied to the V_{CC} pin or the V_{SS} pin, a latch-up may occur.

When a latch-up occurs, power supply current increases significantly, which may cause a component to be thermally destroyed.

- Stabilizing supply voltage

Supply voltage must be stabilized.

A malfunction may occur when power supply voltage fluctuates rapidly even though the fluctuation is within the guaranteed operating range of the V_{CC} power supply voltage.

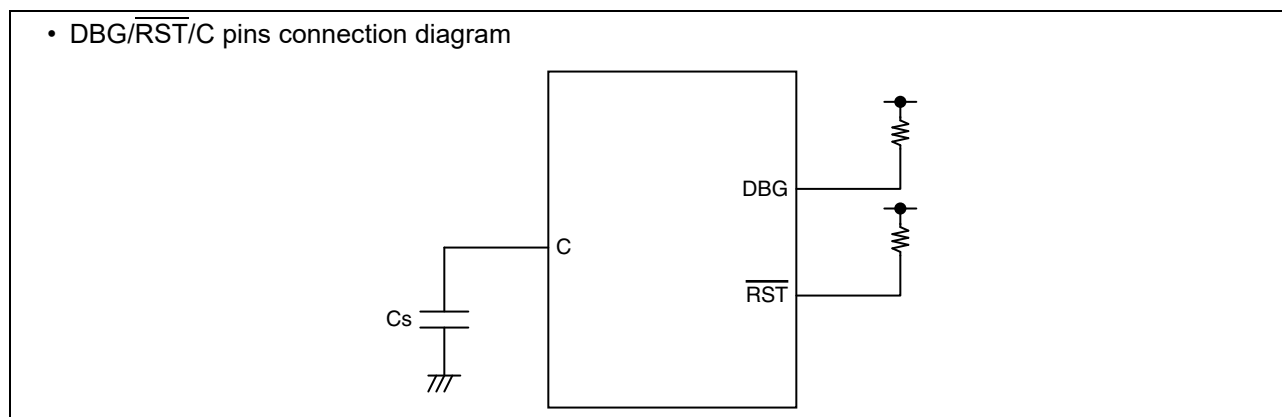
As a rule of voltage stabilization, suppress voltage fluctuation so that the fluctuation in V_{CC} ripple (p-p value) at the commercial frequency (50 Hz/60 Hz) does not exceed 10% of the standard V_{CC} value, and the transient fluctuation rate does not exceed 0.1 V/ms at a momentary fluctuation such as switching the power supply.

- Notes on using the external clock

When an external clock is used, oscillation stabilization wait time is required for power-on reset, wake-up from sub-clock mode or stop mode.

9. Pin Connection

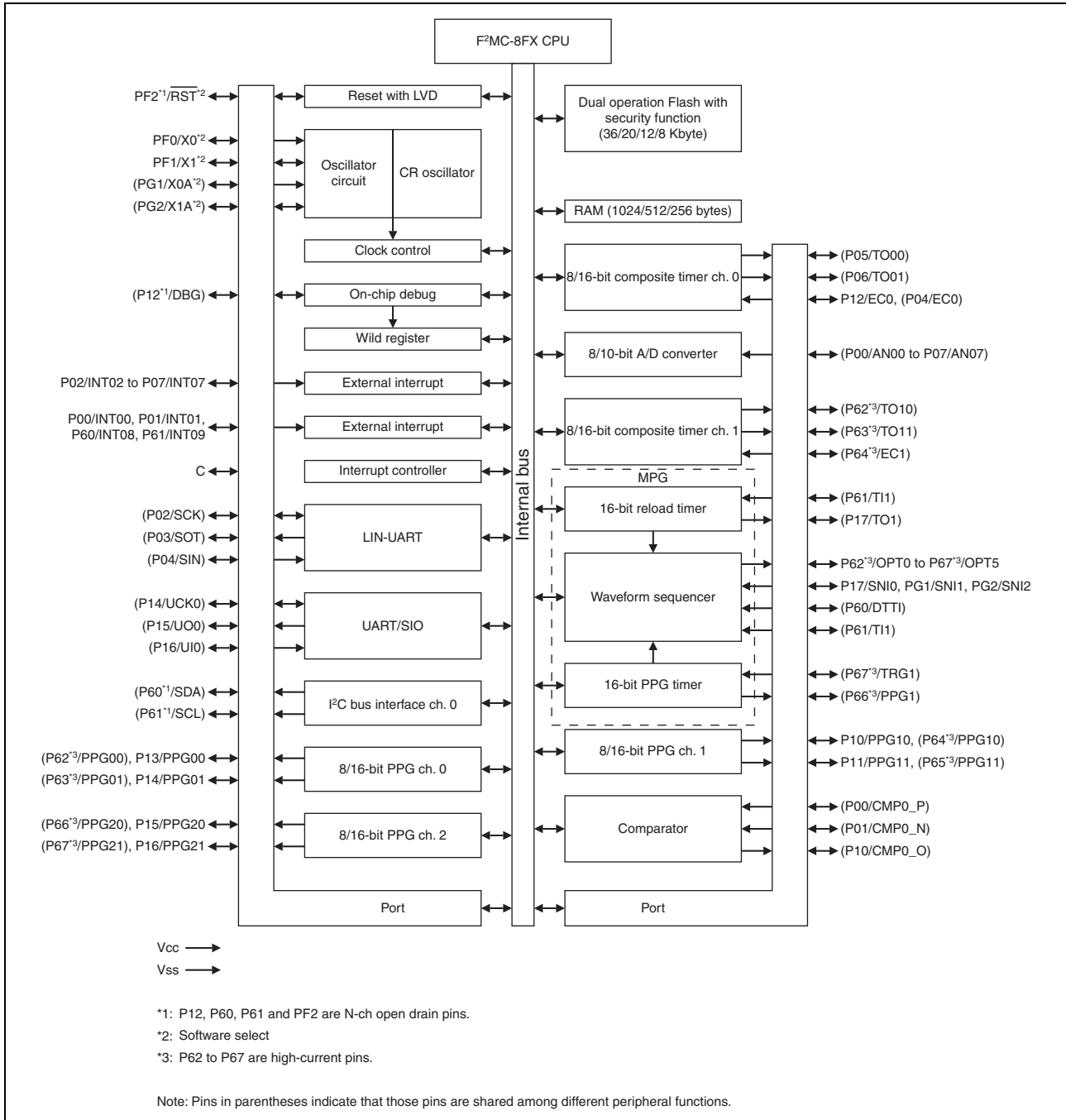
- Treatment of unused pins
If an unused input pin is left unconnected, a component may be permanently damaged due to malfunctions or latch-ups. Always pull up or pull down an unused input pin through a resistor of at least 2 kΩ. Set an unused input/output pin to the output state and leave it unconnected, or set it to the input state and treat it the same as an unused input pin. If there is an unused output pin, leave it unconnected.
- Power supply pins
To reduce unnecessary electro-magnetic emission, prevent malfunctions of strobe signals due to an increase in the ground level, and conform to the total output current standard, always connect the V_{CC} pin and the V_{SS} pin to the power supply and ground outside the device. In addition, connect the current supply source to the V_{CC} pin and the V_{SS} pin with low impedance.
It is also advisable to connect a ceramic capacitor of approximately 0.1 μF as a bypass capacitor between the V_{CC} pin and the V_{SS} pin at a location close to this device.
- DBG pin
Connect the DBG pin to an external pull-up resistor of 2 kΩ or above.
After power-on, ensure that the DBG pin does not stay at “L” level until the reset output is released.
The DBG pin becomes a communication pin in debug mode. Since the actual pull-up resistance depends on the tool used and the interconnection length, refer to the tool document when selecting a pull-up resistor.
- $\overline{\text{RST}}$ pin
Connect the $\overline{\text{RST}}$ pin to an external pull-up resistor of 2 kΩ or above.
To prevent the device from unintentionally entering the reset mode due to noise, minimize the interconnection length between a pull-up resistor and the $\overline{\text{RST}}$ pin and that between a pull-up resistor and the V_{CC} pin when designing the layout of the printed circuit board.
The PF2/ $\overline{\text{RST}}$ pin functions as the reset input/output pin after power-on. In addition, the reset output of the PF2/ $\overline{\text{RST}}$ pin can be enabled by the RSTOE bit in the SYSC register, and the reset input function and the general-purpose I/O function can be selected by the RSTEN bit in the SYSC register.
- C pin
Use a ceramic capacitor or a capacitor with equivalent frequency characteristics. The decoupling capacitor for the V_{CC} pin must have a capacitance equal to or larger than the capacitance of C_s. For the connection to a decoupling capacitor C_s, see the diagram below. To prevent the device from unintentionally entering a mode to which the device is not set to transit due to noise, minimize the distance between the C pin and C_s and the distance between C_s and the V_{SS} pin when designing the layout of a printed circuit board.



- Note on serial communication
In serial communication, reception of wrong data may occur due to noise or other causes. Therefore, design a printed

circuit board to prevent noise from occurring. Taking account of the reception of wrong data, take measures such as adding a checksum to the end of data in order to detect errors. If an error is detected, retransmit the data.

10. Block Diagram

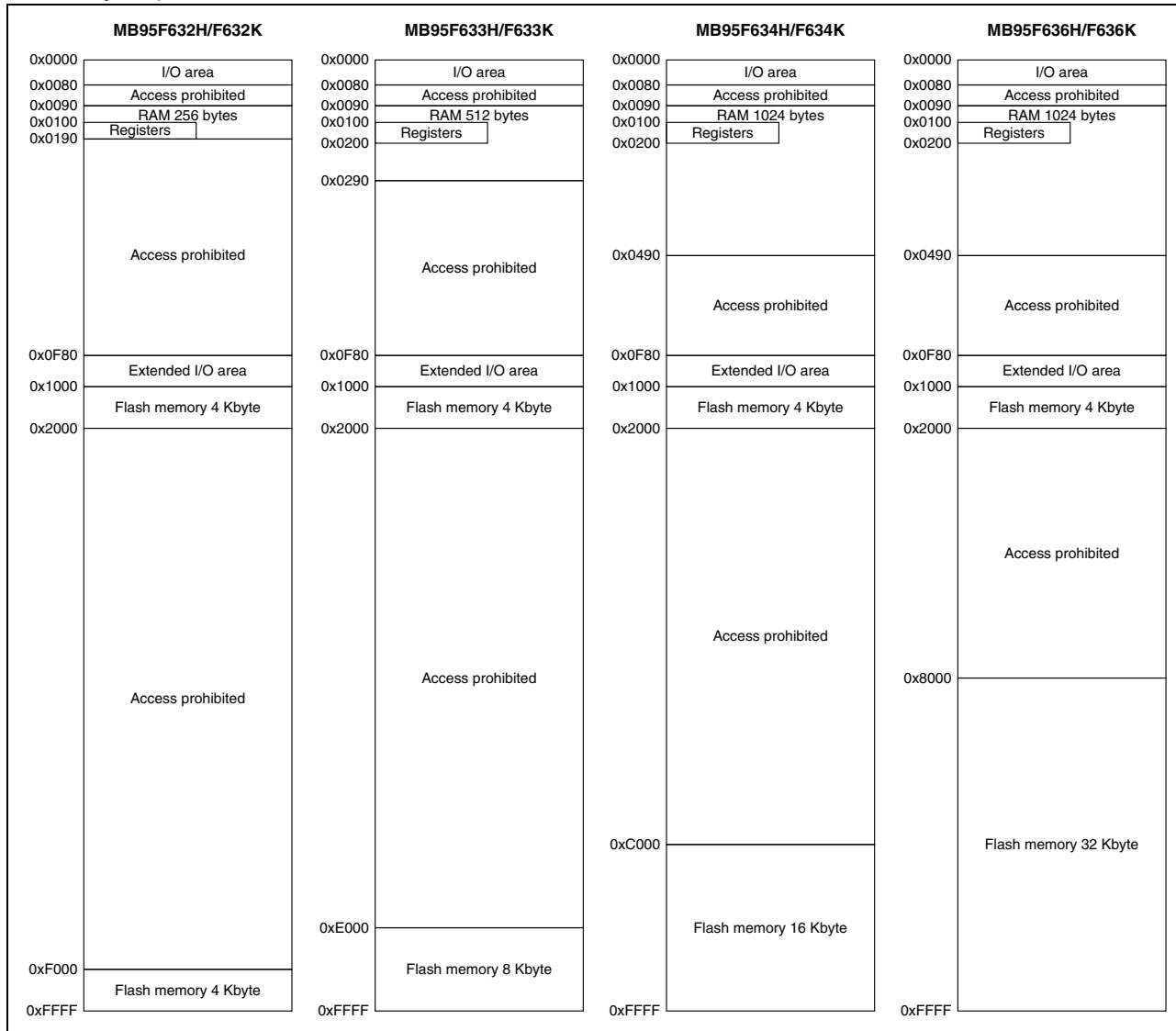


11. CPU Core

- Memory space

The memory space of the CY95630H Series is 64 Kbyte in size, and consists of an I/O area, an extended I/O area, a data area, and a program area. The memory space includes areas intended for specific purposes such as general-purpose registers and a vector table. The memory maps of the CY95630H Series are shown below.

- Memory maps

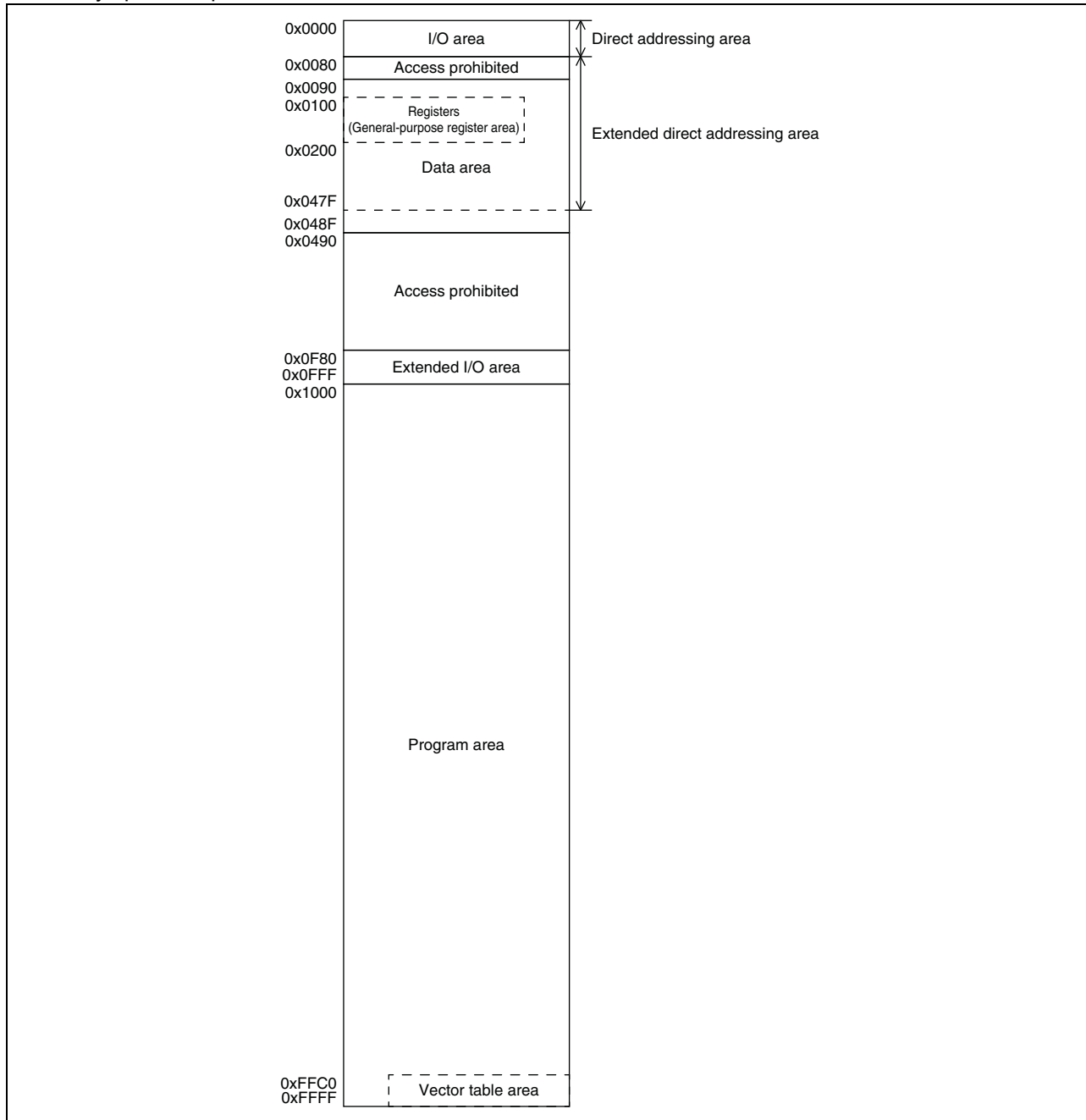


12. Memory Space

The memory space of the CY95630H Series is 64 Kbyte in size, and consists of an I/O area, an extended I/O area, a data area, and a program area. The memory space includes areas for specific applications such as general-purpose registers and a vector table.

- I/O area (addresses: 0x0000 to 0x007F)
 - This area contains the control registers and data registers for built-in peripheral functions.
 - As the I/O area forms part of the memory space, it can be accessed in the same way as the memory. It can also be accessed at high-speed by using direct addressing instructions.
- Extended I/O area (addresses: 0x0F80 to 0x0FFF)
 - This area contains the control registers and data registers for built-in peripheral functions.
 - As the extended I/O area forms part of the memory space, it can be accessed in the same way as the memory.
- Data area
 - Static RAM is incorporated in the data area as the internal data area.
 - The internal RAM size varies according to product.
 - The RAM area from 0x0090 to 0x00FF can be accessed at high-speed by using direct addressing instructions.
 - In CY95F636H/F636K, the area from 0x0090 to 0x047F is an extended direct addressing area. It can be accessed at high-speed by direct addressing instructions with a direct bank pointer set.
 - In CY95F634H/F634K, the area from 0x0090 to 0x047F is an extended direct addressing area. It can be accessed at high-speed by direct addressing instructions with a direct bank pointer set.
 - In CY95F633H/F633K, the area from 0x0090 to 0x028F is an extended direct addressing area. It can be accessed at high-speed by direct addressing instructions with a direct bank pointer set.
 - In CY95F632H/F632K, the area from 0x0090 to 0x018F is an extended direct addressing area. It can be accessed at high-speed by direct addressing instructions with a direct bank pointer set.
 - In CY95F633H/F633K/F634H/F634K/F636H/F636K, the area from 0x0100 to 0x01FF can be used as a general-purpose register area.
 - In CY95F632H/F632K, the area from 0x0100 to 0x018F can be used as a general-purpose register area.
- Program area
 - The Flash memory is incorporated in the program area as the internal program area.
 - The Flash memory size varies according to product.
 - The area from 0xFFC0 to 0xFFFF is used as the vector table.
 - The area from 0xFFBB to 0xFFBF is used to store data of the non-volatile register.

• Memory space map



13. Areas For Specific Applications

The general-purpose register area and vector table area are used for the specific applications.

- General-purpose register area (Addresses: 0x0100 to 0x01FF*1)
 - This area contains the auxiliary registers used for 8-bit arithmetic operations, transfer, etc.
 - As this area forms part of the RAM area, it can also be used as conventional RAM.
 - When the area is used as general-purpose registers, general-purpose register addressing enables high-speed access with short instructions.
- Non-volatile register data area (Addresses: 0xFFBB to 0xFFBF)
 - The area from 0xFFBB to 0xFFBF is used to store data of the non-volatile register. For details, refer to “CHAPTER 26 NON-VOLATILE REGISTER (NVR) INTERFACE” in “New 8FX CY95630H Series Hardware Manual”.
- Vector table area (Addresses: 0xFFC0 to 0xFFFF)
 - This area is used as the vector table for vector call instructions (CALLV), interrupts, and resets.
 - The top of the Flash memory area is allocated to the vector table area. The start address of a service routine is set to an address in the vector table in the form of data.

“Interrupt Source Table” lists the vector table addresses corresponding to vector call instructions, interrupts, and resets.

For details, refer to “CHAPTER 4 RESET”, “CHAPTER 5 INTERRUPTS” and “A.2 Special Instruction ■ Special Instruction ● CALLV #vct” in “New 8FX CY95630H Series Hardware Manual”.

- Direct bank pointer and access area

| Direct bank pointer (DP[2:0]) | Operand-specified dir | Access area |
|-------------------------------------|-----------------------|--------------------|
| 0bXXX (It does not affect mapping.) | 0x0000 to 0x007F | 0x0000 to 0x007F |
| 0b000 (Initial value) | 0x0090 to 0x00FF | 0x0090 to 0x00FF |
| 0b001 | 0x0080 to 0x00FF | 0x0100 to 0x017F |
| 0b010 | | 0x0180 to 0x01FF*1 |
| 0b011 | | 0x0200 to 0x027F |
| 0b100 | | 0x0280 to 0x02FF*2 |
| 0b101 | | 0x0300 to 0x037F |
| 0b110 | | 0x0380 to 0x03FF |
| 0b111 | | 0x0400 to 0x047F |

*1: Due to the memory size limit, the available access area is up to “0x018F” in CY95F632H/F632K.

*2: Due to the memory size limit, the available access area is up to “0x028F” in CY95F633H/F633K.

14. I/O Map

| Address | Register abbreviation | Register name | R/W | Initial value |
|------------------------|-----------------------|---|-----|---------------|
| 0x0000 | PDR0 | Port 0 data register | R/W | 0b00000000 |
| 0x0001 | DDR0 | Port 0 direction register | R/W | 0b00000000 |
| 0x0002 | PDR1 | Port 1 data register | R/W | 0b00000000 |
| 0x0003 | DDR1 | Port 1 direction register | R/W | 0b00000000 |
| 0x0004 | — | (Disabled) | — | — |
| 0x0005 | WATR | Oscillation stabilization wait time setting register | R/W | 0b11111111 |
| 0x0006 | PLLC | PLL control register | R/W | 0b000X0000 |
| 0x0007 | SYCC | System clock control register | R/W | 0bXXX11011 |
| 0x0008 | STBC | Standby control register | R/W | 0b00000000 |
| 0x0009 | RSRR | Reset source register | R/W | 0b000XXXXX |
| 0x000A | TBTC | Time-base timer control register | R/W | 0b00000000 |
| 0x000B | WPCR | Watch prescaler control register | R/W | 0b00000000 |
| 0x000C | WDTC | Watchdog timer control register | R/W | 0b00XX0000 |
| 0x000D | SYCC2 | System clock control register 2 | R/W | 0bXXXX0011 |
| 0x000E | STBC2 | Standby control register 2 | R/W | 0b00000000 |
| 0x000F to 0x0015 | — | (Disabled) | — | — |
| 0x0016 | PDR6 | Port 6 data register | R/W | 0b00000000 |
| 0x0017 | DDR6 | Port 6 direction register | R/W | 0b00000000 |
| 0x0018 to 0x0027 | — | (Disabled) | — | — |
| 0x0028 | PDRF | Port F data register | R/W | 0b00000000 |
| 0x0029 | DDRF | Port F direction register | R/W | 0b00000000 |
| 0x002A | PDRG | Port G data register | R/W | 0b00000000 |
| 0x002B | DDRG | Port G direction register | R/W | 0b00000000 |
| 0x002C | PUL0 | Port 0 pull-up register | R/W | 0b00000000 |
| 0x002D | PUL1 | Port 1 pull-up register | R/W | 0b00000000 |
| 0x002E to 0x0032 | — | (Disabled) | — | — |
| 0x0033 | PUL6 | Port 6 pull-up register | R/W | 0b00000000 |
| 0x0034 | — | (Disabled) | — | — |
| 0x0035 | PULG | Port G pull-up register | R/W | 0b00000000 |
| 0x0036 | T01CR1 | 8/16-bit composite timer 01 status control register 1 | R/W | 0b00000000 |

| Address | Register abbreviation | Register name | R/W | Initial value |
|-------------------|-----------------------|---|-----|---------------|
| 0x0037 | T00CR1 | 8/16-bit composite timer 00 status control register 1 | R/W | 0b00000000 |
| 0x0038 | T11CR1 | 8/16-bit composite timer 11 status control register 1 | R/W | 0b00000000 |
| 0x0039 | T10CR1 | 8/16-bit composite timer 10 status control register 1 | R/W | 0b00000000 |
| 0x003A | PC01 | 8/16-bit PPG timer 01 control register | R/W | 0b00000000 |
| 0x003B | PC00 | 8/16-bit PPG timer 00 control register | R/W | 0b00000000 |
| 0x003C | PC11 | 8/16-bit PPG timer 11 control register | R/W | 0b00000000 |
| 0x003D | PC10 | 8/16-bit PPG timer 10 control register | R/W | 0b00000000 |
| 0x003E | PC21 | 8/16-bit PPG timer 21 control register | R/W | 0b00000000 |
| 0x003F | PC20 | 8/16-bit PPG timer 20 control register | R/W | 0b00000000 |
| 0x0040 | TMCSRH1 | 16-bit reload timer control status register (upper) | R/W | 0b00000000 |
| 0x0041 | TMCSRL1 | 16-bit reload timer control status register (lower) | R/W | 0b00000000 |
| 0x0042 | CMR0C | Comparator control register | R/W | 0b00000101 |
| 0x0043 | — | (Disabled) | — | — |
| 0x0044 | PCNTH1 | 16-bit PPG status control register (upper) | R/W | 0b00000000 |
| 0x0045 | PCNTL1 | 16-bit PPG status control register (lower) | R/W | 0b00000000 |
| 0x0046, 0x0047 | — | (Disabled) | — | — |
| 0x0048 | EIC00 | External interrupt circuit control register ch. 0/ch. 1 | R/W | 0b00000000 |
| 0x0049 | EIC10 | External interrupt circuit control register ch. 2/ch. 3 | R/W | 0b00000000 |
| 0x004A | EIC20 | External interrupt circuit control register ch. 4/ch. 5 | R/W | 0b00000000 |
| 0x004B | EIC30 | External interrupt circuit control register ch. 6/ch. 7 | R/W | 0b00000000 |
| 0x004C | EIC01 | External interrupt circuit control register ch. 8/ch. 9 | R/W | 0b00000000 |
| 0x004D | — | (Disabled) | — | — |
| 0x004E | LVDR | LVD reset voltage selection ID register | R/W | 0b00000000 |
| 0x004F | — | (Disabled) | — | — |
| 0x0050 | SCR | LIN-UART serial control register | R/W | 0b00000000 |
| 0x0051 | SMR | LIN-UART serial mode register | R/W | 0b00000000 |
| 0x0052 | SSR | LIN-UART serial status register | R/W | 0b00001000 |
| 0x0053 | RDR | LIN-UART receive data register | R/W | 0b00000000 |
| | TDR | LIN-UART transmit data register | | |
| 0x0054 | ESCR | LIN-UART extended status control register | R/W | 0b00000100 |
| 0x0055 | ECCR | LIN-UART extended communication control register | R/W | 0b000000XX |
| 0x0056 | SMC10 | UART/SIO serial mode control register 1 | R/W | 0b00000000 |
| 0x0057 | SMC20 | UART/SIO serial mode control register 2 | R/W | 0b00100000 |
| 0x0058 | SSR0 | UART/SIO serial status and data register | R/W | 0b00000001 |
| 0x0059 | TDR0 | UART/SIO serial output data register | R/W | 0b00000000 |

| Address | Register abbreviation | Register name | R/W | Initial value |
|------------------------|-----------------------|---|-----|---------------|
| 0x005A | RDR0 | UART/SIO serial input data register | R | 0b00000000 |
| 0x005B to 0x005F | — | (Disabled) | — | — |
| 0x0060 | IBCR00 | I ² C bus control register 0 ch. 0 | R/W | 0b00000000 |
| 0x0061 | IBCR10 | I ² C bus control register 1 ch. 0 | R/W | 0b00000000 |
| 0x0062 | IBSR0 | I ² C bus status register ch. 0 | R/W | 0b00000000 |
| 0x0063 | IDDR0 | I ² C data register ch. 0 | R/W | 0b00000000 |
| 0x0064 | IAAR0 | I ² C address register ch. 0 | R/W | 0b00000000 |
| 0x0065 | ICCR0 | I ² C clock control register ch. 0 | R/W | 0b00000000 |
| 0x0066 | OPCUR | 16-bit MPG output control register (upper) | R/W | 0b00000000 |
| 0x0067 | OPCLR | 16-bit MPG output control register (lower) | R/W | 0b00000000 |
| 0x0068 | IPCUR | 16-bit MPG input control register (upper) | R/W | 0b00000000 |
| 0x0069 | IPCLR | 16-bit MPG input control register (lower) | R/W | 0b00000000 |
| 0x006A | NCCR | 16-bit MPG noise cancellation control register | R/W | 0b00000000 |
| 0x006B | TCSR | 16-bit MPG timer control status register | R/W | 0b00000000 |
| 0x006C | ADC1 | 8/10-bit A/D converter control register 1 | R/W | 0b00000000 |
| 0x006D | ADC2 | 8/10-bit A/D converter control register 2 | R/W | 0b00000000 |
| 0x006E | ADDH | 8/10-bit A/D converter data register (upper) | R/W | 0b00000000 |
| 0x006F | ADDL | 8/10-bit A/D converter data register (lower) | R/W | 0b00000000 |
| 0x0070 | — | (Disabled) | — | — |
| 0x0071 | FSR2 | Flash memory status register 2 | R/W | 0b00000000 |
| 0x0072 | FSR | Flash memory status register | R/W | 0b000X0000 |
| 0x0073 | SWRE0 | Flash memory sector write control register 0 | R/W | 0b00000000 |
| 0x0074 | FSR3 | Flash memory status register 3 | R | 0b000XXXXX |
| 0x0075 | FSR4 | Flash memory status register 4 | R/W | 0b00000000 |
| 0x0076 | WREN | Wild register address compare enable register | R/W | 0b00000000 |
| 0x0077 | WROR | Wild register data test setting register | R/W | 0b00000000 |
| 0x0078 | — | Mirror of register bank pointer (RP) and direct bank pointer (DP) | — | — |
| 0x0079 | ILR0 | Interrupt level setting register 0 | R/W | 0b11111111 |
| 0x007A | ILR1 | Interrupt level setting register 1 | R/W | 0b11111111 |
| 0x007B | ILR2 | Interrupt level setting register 2 | R/W | 0b11111111 |
| 0x007C | ILR3 | Interrupt level setting register 3 | R/W | 0b11111111 |
| 0x007D | ILR4 | Interrupt level setting register 4 | R/W | 0b11111111 |
| 0x007E | ILR5 | Interrupt level setting register 5 | R/W | 0b11111111 |
| 0x007F | — | (Disabled) | — | — |

| Address | Register abbreviation | Register name | R/W | Initial value |
|------------------------|-----------------------|--|-----|---------------|
| 0x0F80 | WRARH0 | Wild register address setting register (upper) ch. 0 | R/W | 0b00000000 |
| 0x0F81 | WRARL0 | Wild register address setting register (lower) ch. 0 | R/W | 0b00000000 |
| 0x0F82 | WRDR0 | Wild register data setting register ch. 0 | R/W | 0b00000000 |
| 0x0F83 | WRARH1 | Wild register address setting register (upper) ch. 1 | R/W | 0b00000000 |
| 0x0F84 | WRARL1 | Wild register address setting register (lower) ch. 1 | R/W | 0b00000000 |
| 0x0F85 | WRDR1 | Wild register data setting register ch. 1 | R/W | 0b00000000 |
| 0x0F86 | WRARH2 | Wild register address setting register (upper) ch. 2 | R/W | 0b00000000 |
| 0x0F87 | WRARL2 | Wild register address setting register (lower) ch. 2 | R/W | 0b00000000 |
| 0x0F88 | WRDR2 | Wild register data setting register ch. 2 | R/W | 0b00000000 |
| 0x0F89 to 0x0F91 | — | (Disabled) | — | — |
| 0x0F92 | T01CR0 | 8/16-bit composite timer 01 status control register 0 | R/W | 0b00000000 |
| 0x0F93 | T00CR0 | 8/16-bit composite timer 00 status control register 0 | R/W | 0b00000000 |
| 0x0F94 | T01DR | 8/16-bit composite timer 01 data register | R/W | 0b00000000 |
| 0x0F95 | T00DR | 8/16-bit composite timer 00 data register | R/W | 0b00000000 |
| 0x0F96 | TMCR0 | 8/16-bit composite timer 00/01 timer mode control register | R/W | 0b00000000 |
| 0x0F97 | T11CR0 | 8/16-bit composite timer 11 status control register 0 | R/W | 0b00000000 |
| 0x0F98 | T10CR0 | 8/16-bit composite timer 10 status control register 0 | R/W | 0b00000000 |
| 0x0F99 | T11DR | 8/16-bit composite timer 11 data register | R/W | 0b00000000 |
| 0x0F9A | T10DR | 8/16-bit composite timer 10 data register | R/W | 0b00000000 |
| 0x0F9B | TMCR1 | 8/16-bit composite timer 10/11 timer mode control register | R/W | 0b00000000 |
| 0x0F9C | PPS01 | 8/16-bit PPG01 cycle setting buffer register | R/W | 0b11111111 |
| 0x0F9D | PPS00 | 8/16-bit PPG00 cycle setting buffer register | R/W | 0b11111111 |
| 0x0F9E | PDS01 | 8/16-bit PPG01 duty setting buffer register | R/W | 0b11111111 |
| 0x0F9F | PDS00 | 8/16-bit PPG00 duty setting buffer register | R/W | 0b11111111 |
| 0x0FA0 | PPS11 | 8/16-bit PPG11 cycle setting buffer register | R/W | 0b11111111 |
| 0x0FA1 | PPS10 | 8/16-bit PPG10 cycle setting buffer register | R/W | 0b11111111 |
| 0x0FA2 | PDS11 | 8/16-bit PPG11 duty setting buffer register | R/W | 0b11111111 |
| 0x0FA3 | PDS10 | 8/16-bit PPG10 duty setting buffer register | R/W | 0b11111111 |
| 0x0FA4 | PPGS | 8/16-bit PPG start register | R/W | 0b00000000 |
| 0x0FA5 | REVC | 8/16-bit PPG output inversion register | R/W | 0b00000000 |
| 0x0FA6 | PPS21 | 8/16-bit PPG21 cycle setting buffer register | R/W | 0b11111111 |
| 0x0FA7 | PPS20 | 8/16-bit PPG20 cycle setting buffer register | R/W | 0b11111111 |

| Address | Register abbreviation | Register name | R/W | Initial value |
|------------------------|-----------------------|---|-----|---------------|
| 0x0FA8 | TMRH1 | 16-bit reload timer timer register (upper) | R/W | 0b00000000 |
| | TMRLRH1 | 16-bit reload timer reload register (upper) | | |
| 0x0FA9 | TMRL1 | 16-bit reload timer timer register (lower) | R/W | 0b00000000 |
| | TMRLRL1 | 16-bit reload timer reload register (lower) | | |
| 0x0FAA | PDS21 | 8/16-bit PPG21 duty setting buffer register | R/W | 0b11111111 |
| 0x0FAB | PDS20 | 8/16-bit PPG20 duty setting buffer register | R/W | 0b11111111 |
| 0x0FAC to 0x0FAF | — | (Disabled) | — | — |
| 0x0FB0 | PDCRH1 | 16-bit PPG downcounter register (upper) | R | 0b00000000 |
| 0x0FB1 | PDCRL1 | 16-bit PPG downcounter register (lower) | R | 0b00000000 |
| 0x0FB2 | PCSRH1 | 16-bit PPG cycle setting buffer register (upper) | R/W | 0b11111111 |
| 0x0FB3 | PCSRL1 | 16-bit PPG cycle setting buffer register (lower) | R/W | 0b11111111 |
| 0x0FB4 | PDUTH1 | 16-bit PPG duty setting buffer register (upper) | R/W | 0b11111111 |
| 0x0FB5 | PDUTL1 | 16-bit PPG duty setting buffer register (lower) | R/W | 0b11111111 |
| 0x0FB6 to 0x0FBB | — | (Disabled) | — | — |
| 0x0FBC | BGR1 | LIN-UART baud rate generator register 1 | R/W | 0b00000000 |
| 0x0FBD | BGR0 | LIN-UART baud rate generator register 0 | R/W | 0b00000000 |
| 0x0FBE | PSSR0 | UART/SIO dedicated baud rate generator prescaler select register | R/W | 0b00000000 |
| 0x0FBF | BRSR0 | UART/SIO dedicated baud rate generator baud rate setting register | R/W | 0b00000000 |
| 0x0FC0 to 0x0FC2 | — | (Disabled) | — | — |
| 0x0FC3 | AIDRL | A/D input disable register (lower) | R/W | 0b00000000 |
| 0x0FC4 | OPDBRH0 | 16-bit MPG output data buffer register (upper) ch. 0 | R/W | 0b00000000 |
| 0x0FC5 | OPDBRL0 | 16-bit MPG output data buffer register (lower) ch. 0 | R/W | 0b00000000 |
| 0x0FC6 | OPDBRH1 | 16-bit MPG output data buffer register (upper) ch. 1 | R/W | 0b00000000 |
| 0x0FC7 | OPDBRL1 | 16-bit MPG output data buffer register (lower) ch. 1 | R/W | 0b00000000 |
| 0x0FC8 | OPDBRH2 | 16-bit MPG output data buffer register (upper) ch. 2 | R/W | 0b00000000 |
| 0x0FC9 | OPDBRL2 | 16-bit MPG output data buffer register (lower) ch. 2 | R/W | 0b00000000 |
| 0x0FCA | OPDBRH3 | 16-bit MPG output data buffer register (upper) ch. 3 | R/W | 0b00000000 |
| 0x0FCB | OPDBRL3 | 16-bit MPG output data buffer register (lower) ch. 3 | R/W | 0b00000000 |
| 0x0FCC | OPDBRH4 | 16-bit MPG output data buffer register (upper) ch. 4 | R/W | 0b00000000 |
| 0x0FCD | OPDBRL4 | 16-bit MPG output data buffer register (lower) ch. 4 | R/W | 0b00000000 |

| Address | Register abbreviation | Register name | R/W | Initial value |
|------------------------|-----------------------|---|-----|---------------|
| 0x0FCE | OPDBRH5 | 16-bit MPG output data buffer register (upper) ch. 5 | R/W | 0b00000000 |
| 0x0FCF | OPDBRL5 | 16-bit MPG output data buffer register (lower) ch. 5 | R/W | 0b00000000 |
| 0x0FD0 | OPDBRH6 | 16-bit MPG output data buffer register (upper) ch. 6 | R/W | 0b00000000 |
| 0x0FD1 | OPDBRL6 | 16-bit MPG output data buffer register (lower) ch. 6 | R/W | 0b00000000 |
| 0x0FD2 | OPDBRH7 | 16-bit MPG output data buffer register (upper) ch. 7 | R/W | 0b00000000 |
| 0x0FD3 | OPDBRL7 | 16-bit MPG output data buffer register (lower) ch. 7 | R/W | 0b00000000 |
| 0x0FD4 | OPDBRH8 | 16-bit MPG output data buffer register (upper) ch. 8 | R/W | 0b00000000 |
| 0x0FD5 | OPDBRL8 | 16-bit MPG output data buffer register (lower) ch. 8 | R/W | 0b00000000 |
| 0x0FD6 | OPDBRH9 | 16-bit MPG output data buffer register (upper) ch. 9 | R/W | 0b00000000 |
| 0x0FD7 | OPDBRL9 | 16-bit MPG output data buffer register (lower) ch. 9 | R/W | 0b00000000 |
| 0x0FD8 | OPDBRHA | 16-bit MPG output data buffer register (upper) ch. A | R/W | 0b00000000 |
| 0x0FD9 | OPDBRLA | 16-bit MPG output data buffer register (lower) ch. A | R/W | 0b00000000 |
| 0x0FDA | OPDBRHB | 16-bit MPG output data buffer register (upper) ch. B | R/W | 0b00000000 |
| 0x0FDB | OPDBRLB | 16-bit MPG output data buffer register (lower) ch. B | R/W | 0b00000000 |
| 0x0FDC | OPDUR | 16-bit MPG output data register (upper) | R | 0b0000XXXX |
| 0x0FDD | OPDLR | 16-bit MPG output data register (lower) | R | 0bXXXXXXXXXX |
| 0x0FDE | CPCUR | 16-bit MPG compare clear register (upper) | R/W | 0bXXXXXXXXXX |
| 0x0FDF | CPCLR | 16-bit MPG compare clear register (lower) | R/W | 0bXXXXXXXXXX |
| 0x0FE0, 0x0FE1 | — | (Disabled) | — | — |
| 0x0FE2 | TMBUR | 16-bit MPG timer buffer register (upper) | R | 0bXXXXXXXXXX |
| 0x0FE3 | TMBLR | 16-bit MPG timer buffer register (lower) | R | 0bXXXXXXXXXX |
| 0x0FE4 | CRTH | Main CR clock trimming register (upper) | R/W | 0b000XXXXX |
| 0x0FE5 | CRTL | Main CR clock trimming register (lower) | R/W | 0b000XXXXX |
| 0x0FE6 | — | (Disabled) | — | — |
| 0x0FE7 | CRTDA | Main CR clock temperature dependent adjustment register | R/W | 0b000XXXXX |
| 0x0FE8 | SYSC | System configuration register | R/W | 0b11000011 |
| 0x0FE9 | CMCR | Clock monitoring control register | R/W | 0b00000000 |
| 0x0FEA | CMDR | Clock monitoring data register | R | 0b00000000 |
| 0x0FEB | WDTH | Watchdog timer selection ID register (upper) | R | 0bXXXXXXXXXX |
| 0x0FEC | WDTL | Watchdog timer selection ID register (lower) | R | 0bXXXXXXXXXX |
| 0x0FED, 0x0FEE | — | (Disabled) | — | — |
| 0x0FEF | WICR | Interrupt pin selection circuit control register | R/W | 0b01000000 |
| 0x0FF0 to 0x0FFF | — | (Disabled) | — | — |

- R/W access symbols
R/W : Readable/Writable
R : Read only
- Initial value symbols
0 : The initial value of this bit is “0”.
1 : The initial value of this bit is “1”.
X : The initial value of this bit is undefined.

Note: Do not write to an address that is “(Disabled)”. If a “(Disabled)” address is read, an indeterminate value is returned.

15. I/O Ports

- List of port registers

| Register name | | Read/Write | Initial value |
|------------------------------------|-------|------------|---------------|
| Port 0 data register | PDR0 | R, RM/W | 0b00000000 |
| Port 0 direction register | DDR0 | R/W | 0b00000000 |
| Port 1 data register | PDR1 | R, RM/W | 0b00000000 |
| Port 1 direction register | DDR1 | R/W | 0b00000000 |
| Port 6 data register | PDR6 | R, RM/W | 0b00000000 |
| Port 6 direction register | DDR6 | R/W | 0b00000000 |
| Port F data register | PDRF | R, RM/W | 0b00000000 |
| Port F direction register | DDRF | R/W | 0b00000000 |
| Port G data register | PDRG | R, RM/W | 0b00000000 |
| Port G direction register | DDRG | R/W | 0b00000000 |
| Port 0 pull-up register | PUL0 | R/W | 0b00000000 |
| Port 1 pull-up register | PUL1 | R/W | 0b00000000 |
| Port 6 pull-up register | PUL6 | R/W | 0b00000000 |
| Port G pull-up register | PULG | R/W | 0b00000000 |
| A/D input disable register (lower) | AIDRL | R/W | 0b00000000 |

R/W : Readable/writable (The read value is the same as the write value.)

R, RM/W : Readable/writable (The read value is different from the write value. The write value is read by the read-modify-write (RMW) type of instruction.)

15.1 Port 0

Port 0 is a general-purpose I/O port. This section focuses on its functions as a general-purpose I/O port. For details of peripheral functions, refer to their respective chapters in “New 8FX CY95630H Series Hardware Manual”.

15.1.1 Port 0 configuration

Port 0 is made up of the following elements.

- General-purpose I/O pins/peripheral function I/O pins
- Port 0 data register (PDR0)
- Port 0 direction register (DDR0)
- Port 0 pull-up register (PUL0)
- A/D input disable register (lower) (AIDRL)

15.1.2 Block diagrams of port 0

• P00/INT00/AN00/CMP0_P pin

This pin has the following peripheral functions:

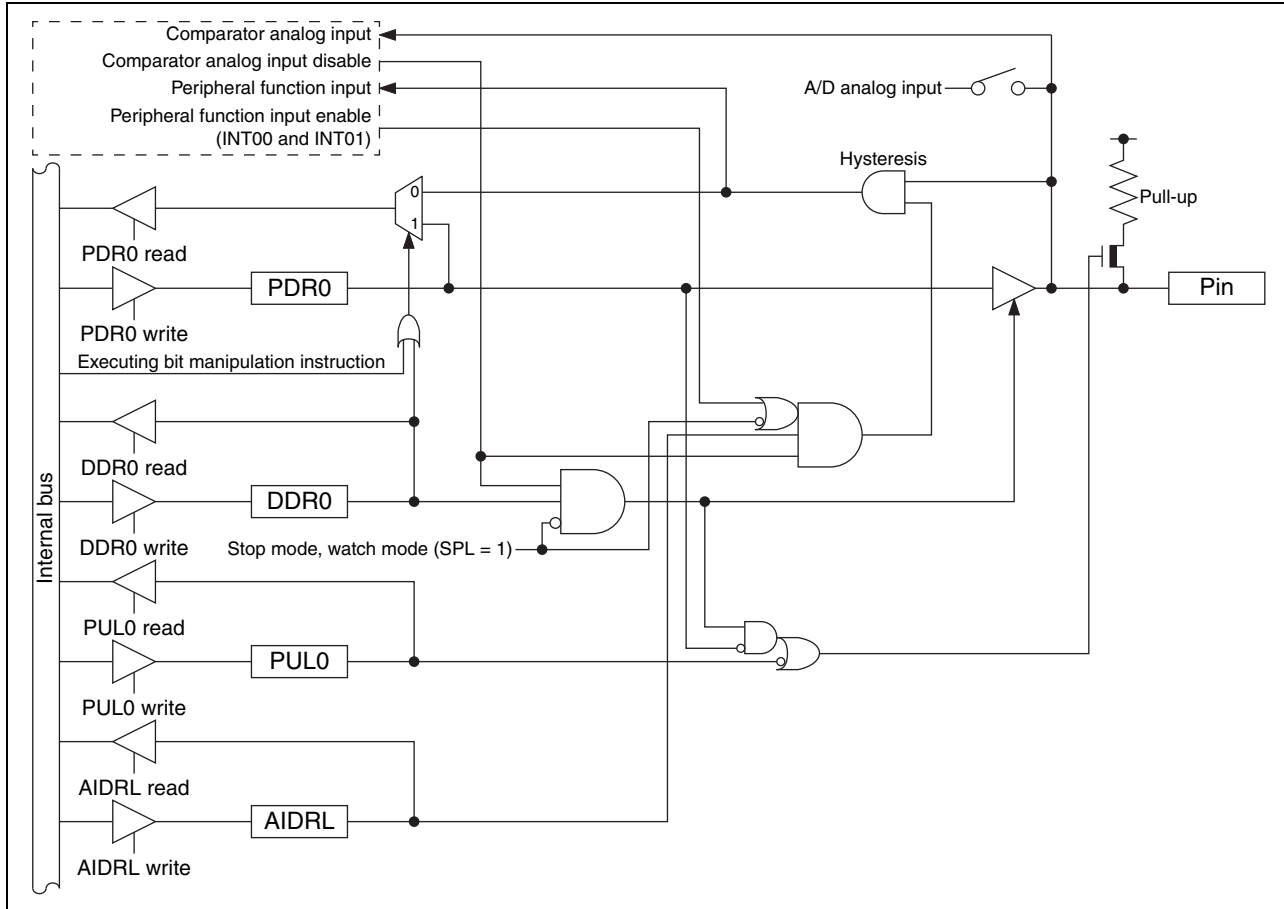
- External interrupt circuit input pin (INT00)
- 8/10-bit A/D converter analog input pin (AN00)
- Comparator non-inverting analog input (positive input) pin (CMP0_P)

• P01/INT01/AN01/CMP0_N pin

This pin has the following peripheral functions:

- External interrupt circuit input pin (INT01)
- 8/10-bit A/D converter analog input pin (AN01)
- Comparator inverting analog input (negative input) pin (CMP0_N)

- Block diagram of P00/INT00/AN00/CMP0_P and P01/INT01/AN01/CMP0_N



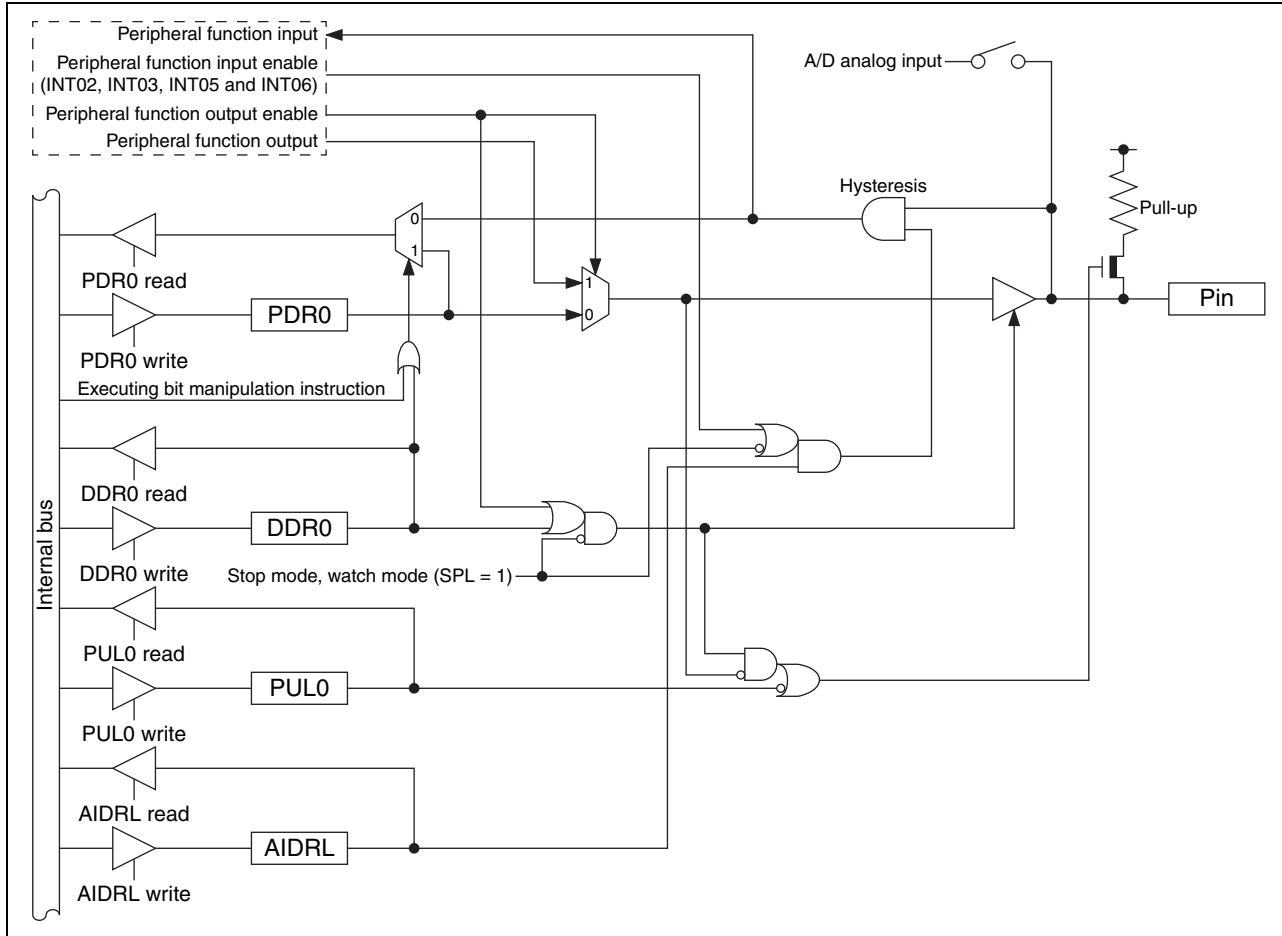
- P02/INT02/AN02/SCK pin
This pin has the following peripheral functions:
 - External interrupt circuit input pin (INT02)
 - 8/10-bit A/D converter analog input pin (AN02)
 - LIN-UART clock I/O pin (SCK)

- P03/INT03/AN03/SOT pin
This pin has the following peripheral functions:
 - External interrupt circuit input pin (INT03)
 - 8/10-bit A/D converter analog input pin (AN03)
 - LIN-UART data output pin (SOT)

- P05/INT05/AN05/TO00 pin
This pin has the following peripheral functions:
 - External interrupt circuit input pin (INT05)
 - 8/10-bit A/D converter analog input pin (AN05)
 - 8/16-bit composite timer ch. 0 output pin (TO00)

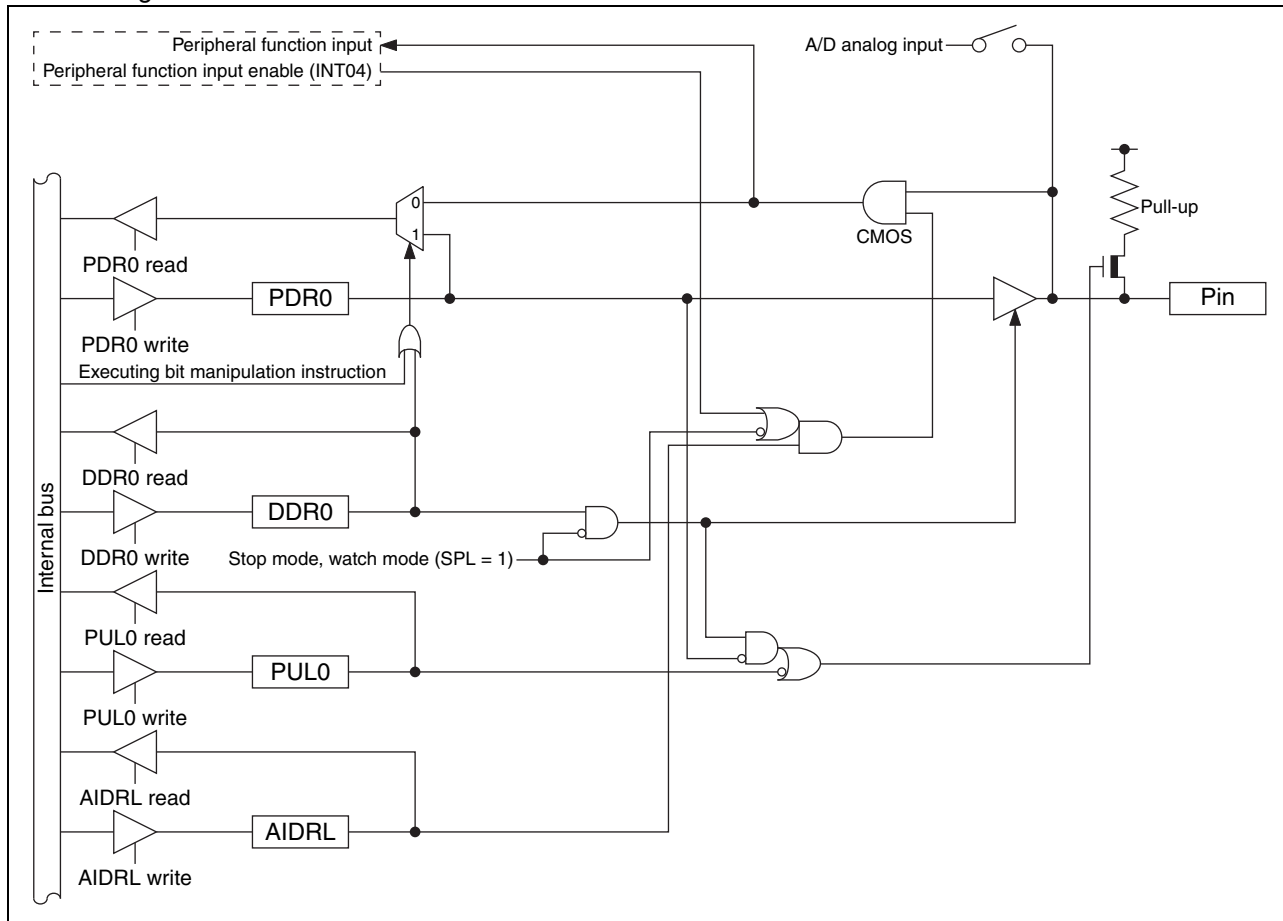
- P06/INT06/AN06/TO01 pin
This pin has the following peripheral functions:
 - External interrupt circuit input pin (INT06)
 - 8/10-bit A/D converter analog input pin (AN06)
 - 8/16-bit composite timer ch. 0 output pin (TO01)

- Block diagram of P02/INT02/AN02/SCK, P03/INT03/AN03/SOT, P05/INT05/AN05/TO00 and P06/INT06/AN06/TO01



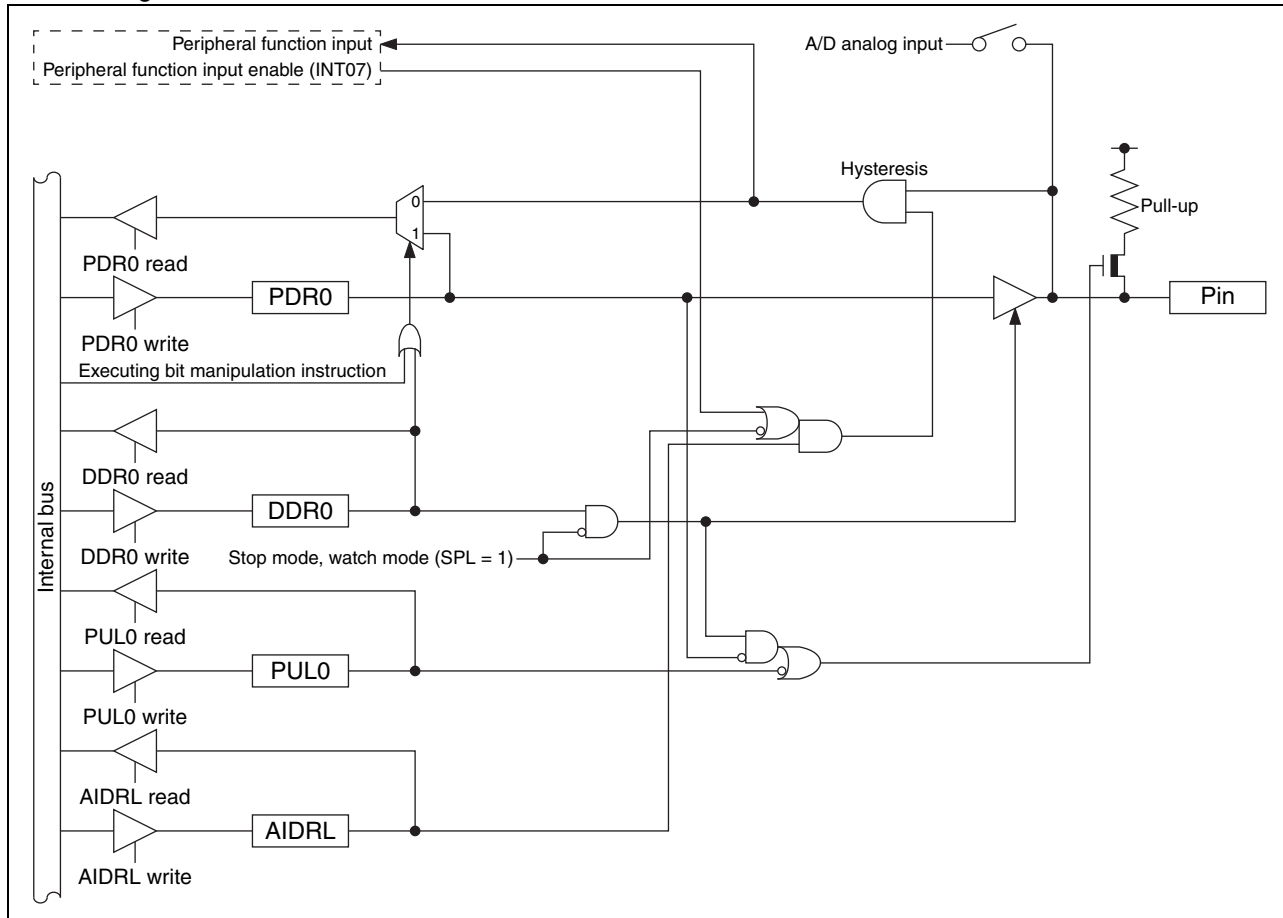
- P04/INT04/AN04/SIN/EC0 pin
 - This pin has the following peripheral functions:
 - External interrupt circuit input pin (INT04)
 - 8/10-bit A/D converter analog input pin (AN04)
 - LIN-UART data input pin (SIN)
 - 8/16-bit composite timer ch. 0 clock input pin (EC0)

• Block diagram of P04/INT04/AN04/SIN/EC0



- P07/INT07/AN07 pin
 - This pin has the following peripheral functions:
 - External interrupt circuit input pin (INT07)
 - 8/10-bit A/D converter analog input pin (AN07)

• Block diagram of P07/INT07/AN07



15.1.3 Port 0 registers

- Port 0 register functions

| Register abbreviation | Data | Read | Read by read-modify-write (RMW) instruction | Write |
|-----------------------|------|-------------------------|---|------------------------------------|
| PDR0 | 0 | Pin state is “L” level. | PDR0 value is “0”. | As output port, outputs “L” level. |
| | 1 | Pin state is “H” level. | PDR0 value is “1”. | As output port, outputs “H” level. |
| DDR0 | 0 | Port input enabled | | |
| | 1 | Port output enabled | | |
| PUL0 | 0 | Pull-up disabled | | |
| | 1 | Pull-up enabled | | |
| AIDRL | 0 | Analog input enabled | | |
| | 1 | Port input enabled | | |

- Correspondence between registers and pins for port 0

| | Correspondence between related register bits and pins | | | | | | | |
|----------|---|------|------|------|------|------|------|------|
| Pin name | P07 | P06 | P05 | P04 | P03 | P02 | P01 | P00 |
| PDR0 | bit7 | bit6 | bit5 | bit4 | bit3 | bit2 | bit1 | bit0 |
| DDR0 | | | | | | | | |
| PUL0 | | | | | | | | |
| AIDRL | | | | | | | | |

15.1.4 Port 0 operations

- Operation as an output port
 - A pin becomes an output port if the bit in the DDR0 register corresponding to that pin is set to “1”.
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
 - When a pin is used as an output port, it outputs the value of the PDR0 register to external pins.
 - If data is written to the PDR0 register, the value is stored in the output latch and is output to the pin set as an output port as it is.
 - Reading the PDR0 register returns the PDR0 register value.
- Operation as an input port
 - A pin becomes an input port if the bit in the DDR0 register corresponding to that pin is set to “0”.
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
 - When using a pin shared with the analog input function as an input port, set the corresponding bit in the A/D input disable register (lower) (AIDRL) to “1”.
 - If data is written to the PDR0 register, the value is stored in the output latch but is not output to the pin set as an input port.
 - Reading the PDR0 register returns the pin value. However, if the read-modify-write (RMW) type of instruction is used to read the PDR0 register, the PDR0 register value is returned.
- Operation as a peripheral function output pin
 - A pin becomes a peripheral function output pin if the peripheral output function is enabled by setting the output enable bit of a peripheral function corresponding to that pin.
 - The pin value can be read from the PDR0 register even if the peripheral function output is enabled. Therefore, the output value of a peripheral function can be read by the read operation on the PDR0 register. However, if the read-modify-write (RMW) type of instruction is used to read the PDR0 register, the PDR0 register value is returned.

- Operation as a peripheral function input pin
 - To set a pin as an input port, set the bit in the DDR0 register corresponding to the input pin of a peripheral function to “0”.
 - When using a pin shared with the analog input function as another peripheral function input pin, configure it as an input port by setting the bit in the AIDRL register corresponding to that pin to “1”.
 - Reading the PDR0 register returns the pin value, regardless of whether the peripheral function uses that pin as its input pin. However, if the read-modify-write (RMW) type of instruction is used to read the PDR0 register, the PDR0 register value is returned.
- Operation at reset

If the CPU is reset, all bits in the DDR0 register are initialized to “0” and port input is enabled. As for a pin shared with analog input, its port input is disabled because the AIDRL register is initialized to “0”.
- Operation in stop mode and watch mode
 - If the pin state setting bit in the standby control register (STBC:SPL) is set to “1” and the device transits to stop mode or watch mode, the pin is compulsorily made to enter the high impedance state regardless of the DDR0 register value. The input of that pin is locked to “L” level and blocked in order to prevent leaks due to input open. However, if the interrupt input is enabled for the external interrupt (INT00 to INT07), the input is enabled and not blocked.
 - If the pin state setting bit is “0”, the state of the port I/O or that of the peripheral function I/O remains unchanged and the output level is maintained.
- Operation as an analog input pin
 - Set the bit in the DDR0 register bit corresponding to the analog input pin to “0” and the bit corresponding to that pin in the AIDRL register to “0”.
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions. In addition, set the corresponding bit in the PUL0 register to “0”.
- Operation as an external interrupt input pin
 - Set the bit in the DDR0 register corresponding to the external interrupt input pin to “0”.
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
 - The pin value is always input to the external interrupt circuit. When using a pin for a function other than the interrupt, disable the external interrupt function corresponding to that pin.
- Operation of the pull-up register

Setting the bit in the PUL0 register to “1” makes the pull-up resistor be internally connected to the pin. When the pin output is “L” level, the pull-up resistor is disconnected regardless of the value of the PUL0 register.
- Operation as a comparator input pin (only for P00 and P01)
 - Set the bit in the AIDRL register corresponding to the comparator input pin to “0”.
 - Regardless of the value of the PDR0 register and that of the DDR0 register, if the comparator analog input enable bit in the comparator control register (CMR0C:VCID) is set to “0”, the comparator input function is enabled.
 - To disable the comparator input function, set the VCID bit to “1”.
 - For details of the comparator, refer to “CHAPTER 27 COMPARATOR” in “New 8FX CY95630H Series Hardware Manual”.

15.2 Port 1

Port 1 is a general-purpose I/O port. This section focuses on its functions as a general-purpose I/O port. For details of peripheral functions, refer to their respective chapters in “New 8FX CY95630H Series Hardware Manual”.

15.2.1 Port 1 configuration

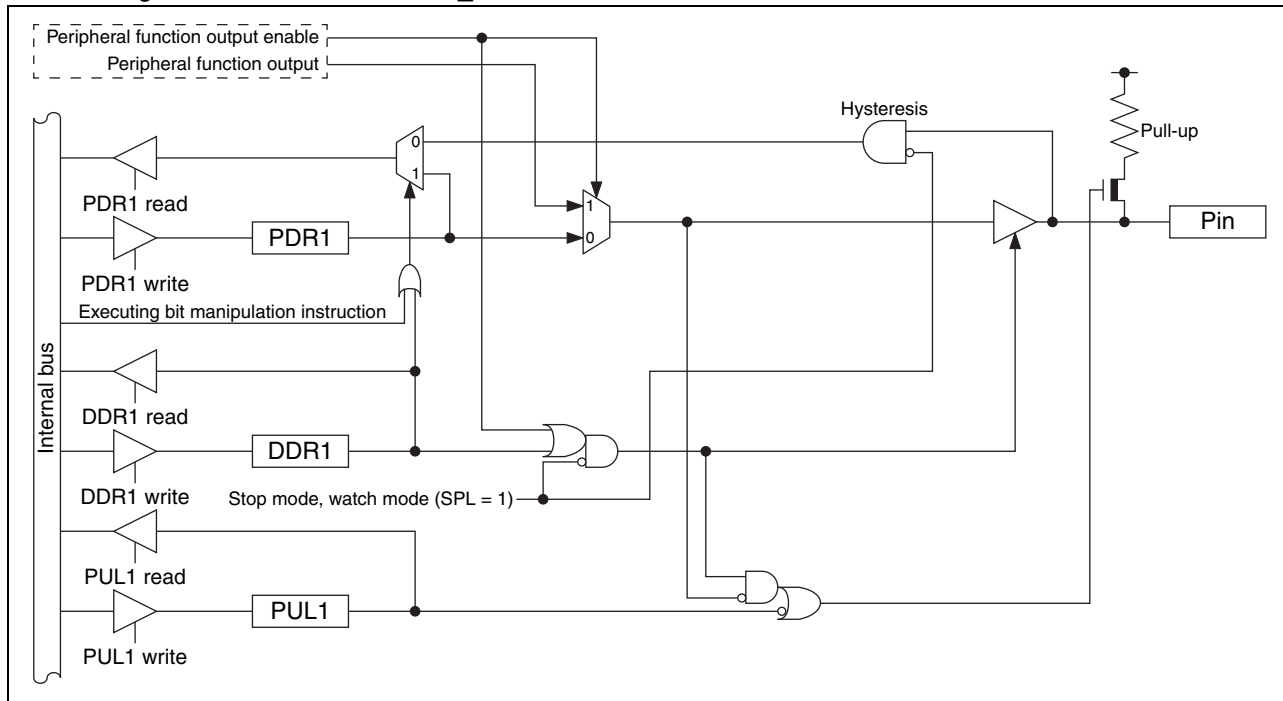
Port 1 is made up of the following elements.

- General-purpose I/O pins/peripheral function I/O pins
- Port 1 data register (PDR1)
- Port 1 direction register (DDR1)
- Port 1 pull-up register (PUL1)

15.2.2 Block diagrams of port 1

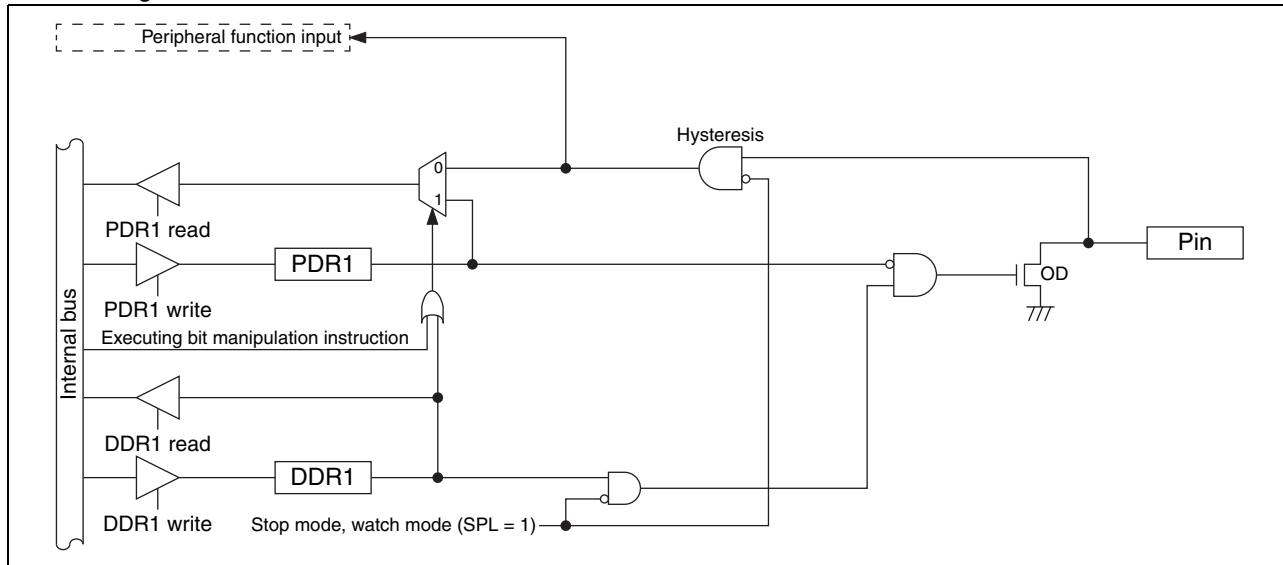
- P10/PPG10/CMP0_O pin
This pin has the following peripheral functions:
 - 8/16-bit PPG ch. 1 output pin (PPG10)
 - Comparator digital output pin (CMP0_O)
- P11/PPG11 pin
This pin has the following peripheral function:
 - 8/16-bit PPG ch. 1 output pin (PPG11)
- P13/PPG00 pin
This pin has the following peripheral function:
 - 8/16-bit PPG ch. 0 output pin (PPG00)
- P15/UO0/PPG20 pin
This pin has the following peripheral functions:
 - UART/SIO ch. 0 data output pin (UO0)
 - 8/16-bit PPG ch. 2 output pin (PPG20)

- Block diagram of P10/PPG10/CMP0_O, P11/PPG11, P13/PPG00 and P15/UO0/PPG20



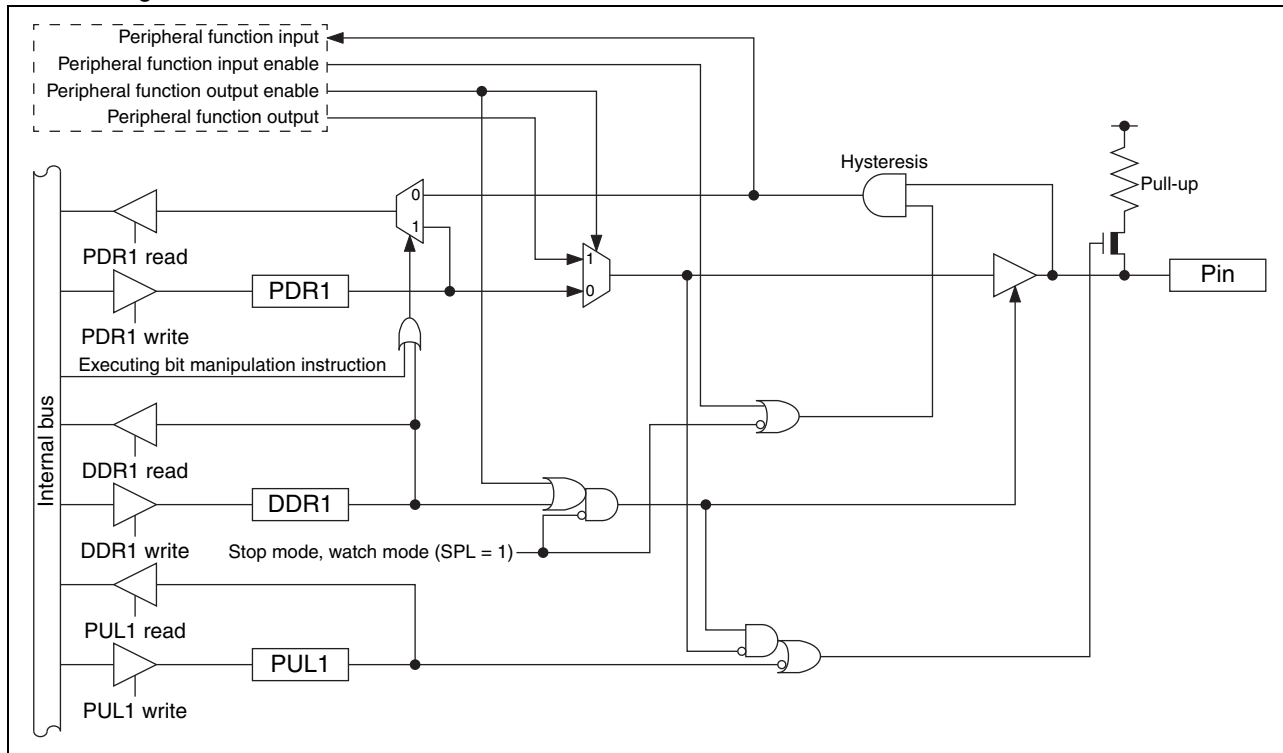
- P12/DBG/EC0 pin
 - This pin has the following peripheral functions:
 - DBG input pin (DBG)
 - 8/16-bit composite timer ch. 0 clock input pin (EC0)

• Block diagram of P12/DBG/EC0



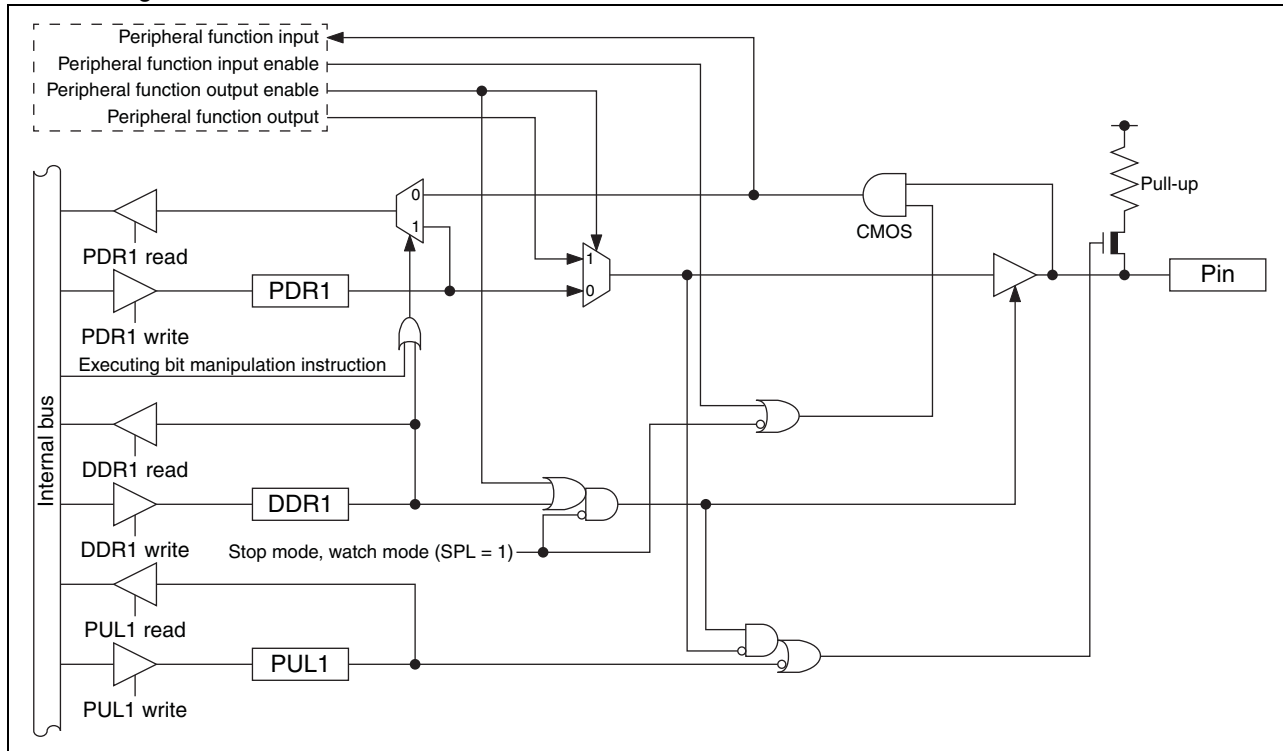
- P14/UCK0/PPG01 pin
 - This pin has the following peripheral functions:
 - UART/SIO ch. 0 clock I/O pin (UCK0)
 - 8/16-bit PPG ch. 0 output pin (PPG01)

• Block diagram of P14/UCK0/PPG01



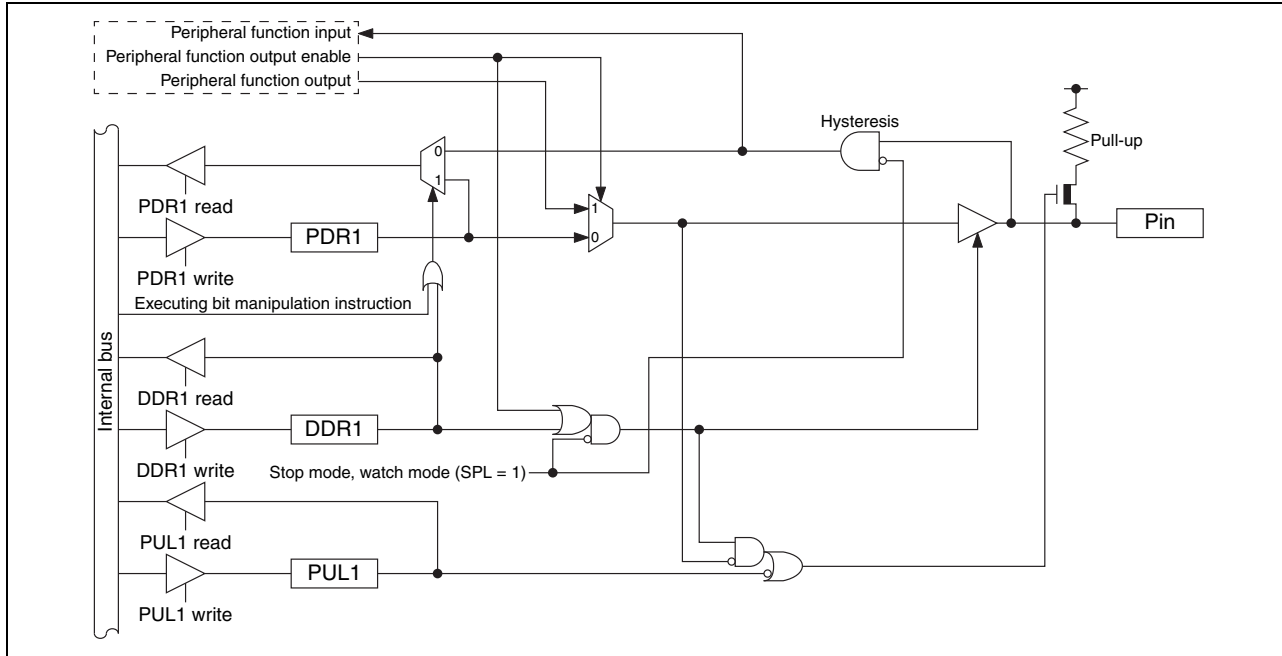
- P16/UI0/PPG21 pin
 - This pin has the following peripheral functions:
 - UART/SIO ch. 0 data input pin (UI0)
 - 8/16-bit PPG ch. 2 output pin (PPG21)

- Block diagram of P16/UI0/PPG21



- P17/TO1/SNI0 pin
 - This pin has the following peripheral functions:
 - 16-bit reload timer ch. 1 output pin (TO1)
 - Trigger input pin for the position detection function of the MPG waveform sequencer (SNI0)

• Block diagram of P17/TO1/SNI0



15.2.3 Port 1 registers

- Port 1 register functions

| Register abbreviation | Data | Read | Read by read-modify-write (RMW) instruction | Write |
|-----------------------|------|-------------------------|---|-------------------------------------|
| PDR1 | 0 | Pin state is “L” level. | PDR1 value is “0”. | As output port, outputs “L” level. |
| | 1 | Pin state is “H” level. | PDR1 value is “1”. | As output port, outputs “H” level.* |
| DDR1 | 0 | Port input enabled | | |
| | 1 | Port output enabled | | |
| PUL1 | 0 | Pull-up disabled | | |
| | 1 | Pull-up enabled | | |

*: If the pin is an N-ch open drain pin, the pin state becomes Hi-Z.

- Correspondence between registers and pins for port 1

| | Correspondence between related register bits and pins | | | | | | | |
|----------|---|------|------|------|------|-------|------|------|
| Pin name | P17 | P16 | P15 | P14 | P13 | P12 | P11 | P10 |
| PDR1 | bit7 | bit6 | bit5 | bit4 | bit3 | bit2* | bit1 | bit0 |
| DDR1 | | | | | | | | |
| PUL1 | | | | | | | | |

*: Though P12 has no pull-up function, bit2 in the PUL1 register can still be accessed. The operation of P12 is not affected by the setting of bit2 in the PUL1 register.

15.2.4 Port 1 operations

- Operation as an output port
 - A pin becomes an output port if the bit in the DDR1 register corresponding to that pin is set to “1”.
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
 - When a pin is used as an output port, it outputs the value of the PDR1 register to external pins.
 - If data is written to the PDR1 register, the value is stored in the output latch and is output to the pin set as an output port as it is.
 - Reading the PDR1 register returns the PDR1 register value.
- Operation as an input port
 - A pin becomes an input port if the bit in the DDR1 register corresponding to that pin is set to “0”.
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
 - If data is written to the PDR1 register, the value is stored in the output latch but is not output to the pin set as an input port.
 - Reading the PDR1 register returns the pin value. However, if the read-modify-write (RMW) type of instruction is used to read the PDR1 register, the PDR1 register value is returned.
- Operation as a peripheral function output pin
 - A pin becomes a peripheral function output pin if the peripheral output function is enabled by setting the output enable bit of a peripheral function corresponding to that pin.
 - The pin value can be read from the PDR1 register even if the peripheral function output is enabled. Therefore, the output value of a peripheral function can be read by the read operation on the PDR1 register. However, if the read-modify-write (RMW) type of instruction is used to read the PDR1 register, the PDR1 register value is returned.
- Operation as a peripheral function input pin
 - To set a pin as an input port, set the bit in the DDR1 register corresponding to the input pin of a peripheral function

to “0”.

- Reading the PDR1 register returns the pin value, regardless of whether the peripheral function uses that pin as its input pin. However, if the read-modify-write (RMW) type of instruction is used to read the PDR1 register, the PDR1 register value is returned.
- Operation at reset
If the CPU is reset, all bits in the DDR1 register are initialized to “0” and port input is enabled.
- Operation in stop mode and watch mode
 - If the pin state setting bit in the standby control register (STBC:SPL) is set to “1” and the device transits to stop mode or watch mode, the pin is compulsorily made to enter the high impedance state regardless of the DDR1 register value. The input of that pin is locked to “L” level and blocked in order to prevent leaks due to input open. However, if the interrupt input of P14/UCK0 and P16/UI0 is enabled by the external interrupt control register ch. 0 (EIC00) of the external interrupt circuit and the interrupt pin selection circuit control register (WICR) of the interrupt pin selection circuit, the input is enabled and is not blocked.
 - If the pin state setting bit is “0”, the state of the port I/O or that of the peripheral function I/O remains unchanged and the output level is maintained.
- Operation of the pull-up register
Setting the bit in the PUL1 register to “1” makes the pull-up resistor be internally connected to the pin. When the pin output is “L” level, the pull-up resistor is disconnected regardless of the value of the PUL1 register.

15.3 Port 6

Port 6 is a general-purpose I/O port. This section focuses on its functions as a general-purpose I/O port. For details of peripheral functions, refer to their respective chapters in “New 8FX CY95630H Series Hardware Manual”.

15.3.1 Port 6 configuration

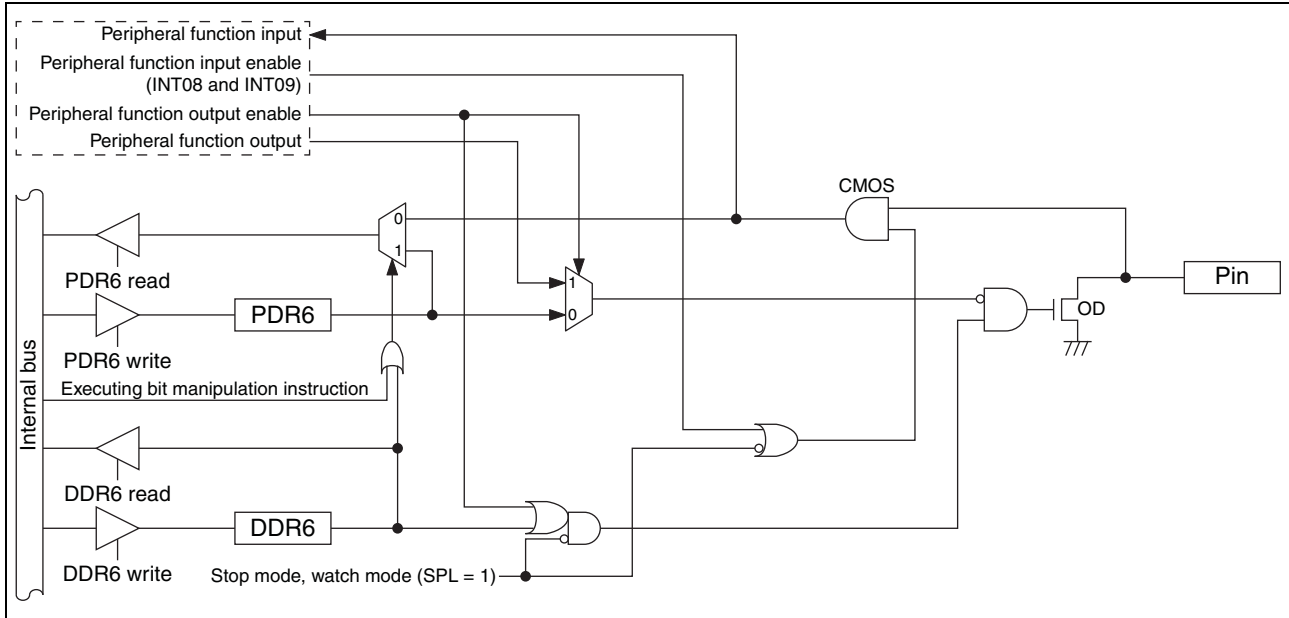
Port 6 is made up of the following elements.

- General-purpose I/O pins/peripheral function I/O pins
- Port 6 data register (PDR6)
- Port 6 direction register (DDR6)
- Port 6 pull-up register (PUL6)

15.3.2 Block diagrams of port 6

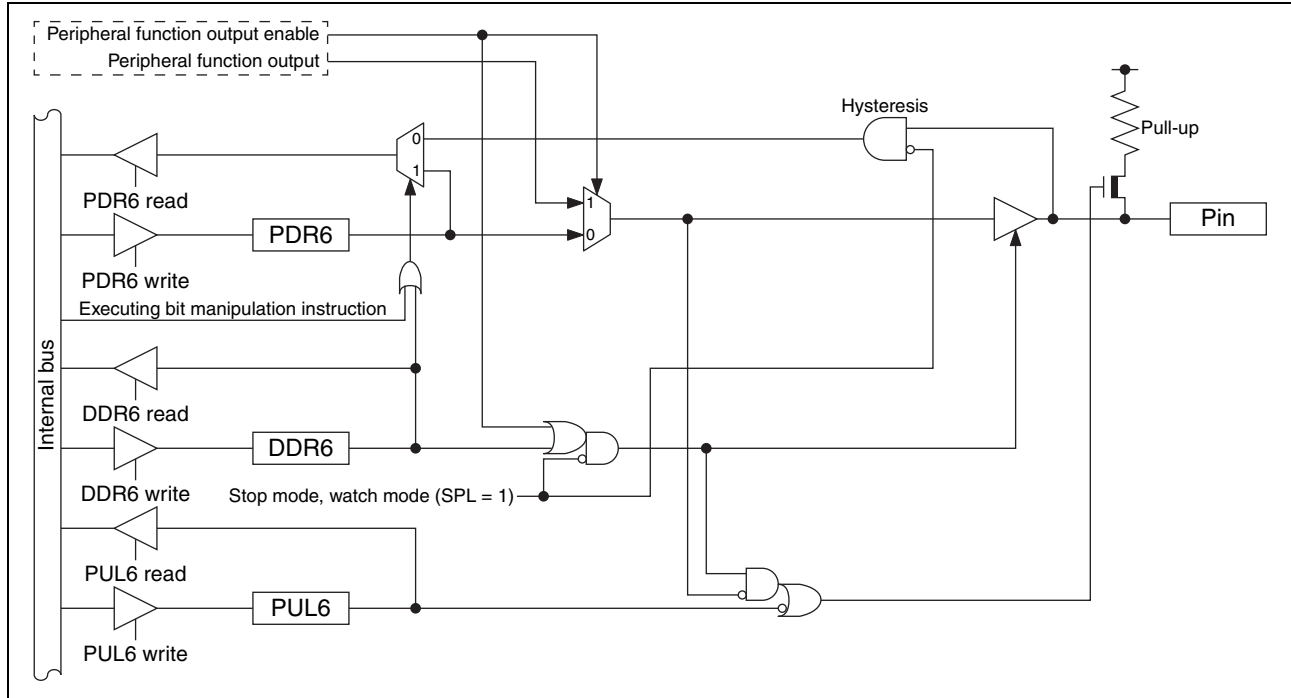
- P60/INT08/SDA/DTTI pin
This pin has the following peripheral functions:
 - External interrupt circuit input pin (INT08)
 - I²C bus interface ch. 0 data I/O pin (SDA)
 - MPG waveform sequencer input pin (DTTI)
- P61/INT09/SCL/TI1 pin
This pin has the following peripheral functions:
 - External interrupt circuit input pin (INT09)
 - I²C bus interface ch. 0 clock I/O pin (SCL)
 - 16-bit reload timer ch. 1 input pin (TI1)

- Block diagram of P60/INT08/SDA/DTTI and P61/INT09/SCL/TI1



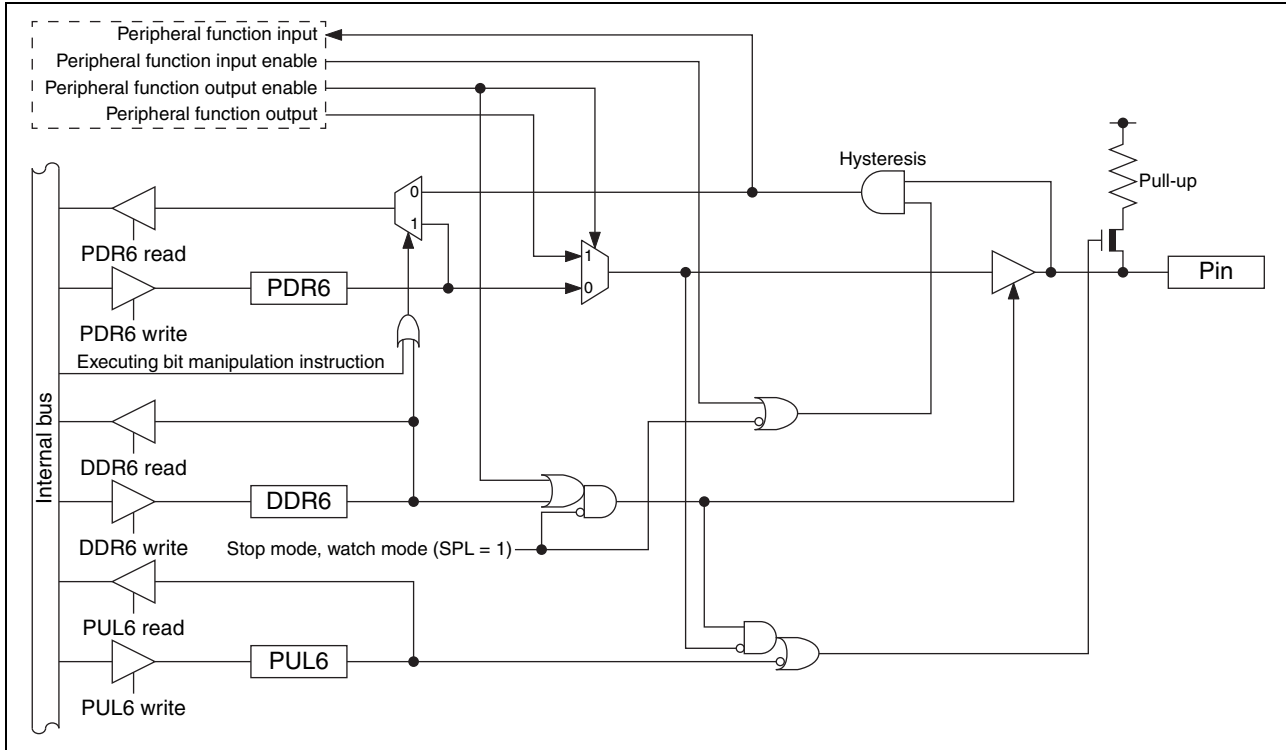
- P62/TO10/PPG00/OPT0 pin
 - This pin has the following peripheral functions:
 - 8/16-bit composite timer ch. 1 output pin (TO10)
 - 8/16-bit PPG ch. 0 output pin (PPG00)
 - MPG waveform sequencer output pin (OPT0)
- P63/TO11/PPG01/OPT1 pin
 - This pin has the following peripheral functions:
 - 8/16-bit composite timer ch. 1 output pin (TO11)
 - 8/16-bit PPG ch. 0 output pin (PPG01)
 - MPG waveform sequencer output pin (OPT1)
- P65/PPG11/OPT3 pin
 - This pin has the following peripheral functions:
 - 8/16-bit PPG ch. 1 output pin (PPG11)
 - MPG waveform sequencer output pin (OPT3)
- P66/PPG20/PPG1/OPT4 pin
 - This pin has the following peripheral functions:
 - 8/16-bit PPG ch. 2 output pin (PPG20)
 - 16-bit PPG timer ch. 1 output pin (PPG1)
 - MPG waveform sequencer output pin (OPT4)
- Block diagram of P62/TO10/PPG00/OPT0, P63/TO11/PPG01/OPT1, P65/PPG11/OPT3 and

P66/PPG20/PPG1/OPT4



- P64/EC1/PPG10/OPT2 pin
This pin has the following peripheral functions:
 - 8/16-bit composite timer ch. 1 clock input pin (EC1)
 - 8/16-bit PPG ch. 1 output pin (PPG10)
 - MPG waveform sequencer output pin (OPT2)
- P67/PPG21/TRG1/OPT5 pin
This pin has the following peripheral functions:
 - 8/16-bit PPG ch. 2 output pin (PPG21)
 - 16-bit PPG timer ch. 1 trigger input pin (TRG1)
 - MPG waveform sequencer output pin (OPT5)

- Block diagram of P64/EC1/PPG10/OPT2 and P67/PPG21/TRG1/OPT5



15.3.3 Port 6 registers
 • Port 6 register functions

| Register abbreviation | Data | Read | Read by read-modify-write (RMW) instruction | Write |
|-----------------------|------|-------------------------|---|-------------------------------------|
| PDR6 | 0 | Pin state is "L" level. | PDR6 value is "0". | As output port, outputs "L" level. |
| | 1 | Pin state is "H" level. | PDR6 value is "1". | As output port, outputs "H" level.* |
| DDR6 | 0 | Port input enabled | | |
| | 1 | Port output enabled | | |
| PUL6 | 0 | Pull-up disabled | | |
| | 1 | Pull-up enabled | | |

*: If the pin is an N-ch open drain pin, the pin state becomes Hi-Z.

- Correspondence between registers and pins for port 6

| | Correspondence between related register bits and pins | | | | | | | |
|----------|---|------|------|------|------|------|------|------|
| Pin name | P67 | P66 | P65 | P64 | P63 | P62 | P61 | P60 |
| PDR6 | | | | | | | bit1 | bit0 |
| DDR6 | bit7 | bit6 | bit5 | bit4 | bit3 | bit2 | | |
| PUL6 | | | | | | | - | - |

15.3.4 Port 6 operations

- Operation as an output port
 - A pin becomes an output port if the bit in the DDR6 register corresponding to that pin is set to “1”.
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
 - When a pin is used as an output port, it outputs the value of the PDR6 register to external pins.
 - If data is written to the PDR6 register, the value is stored in the output latch and is output to the pin set as an output port as it is.
 - Reading the PDR6 register returns the PDR6 register value.

- Operation as an input port
 - A pin becomes an input port if the bit in the DDR6 register corresponding to that pin is set to “0”.
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
 - If data is written to the PDR6 register, the value is stored in the output latch but is not output to the pin set as an input port.
 - Reading the PDR6 register returns the pin value. However, if the read-modify-write (RMW) type of instruction is used to read the PDR6 register, the PDR6 register value is returned.

- Operation as a peripheral function output pin
 - A pin becomes a peripheral function output pin if the peripheral output function is enabled by setting the output enable bit of a peripheral function corresponding to that pin.
 - The pin value can be read from the PDR6 register even if the peripheral function output is enabled. Therefore, the output value of a peripheral function can be read by the read operation on the PDR6 register. However, if the read-modify-write (RMW) type of instruction is used to read the PDR6 register, the PDR6 register value is returned.

- Operation as a peripheral function input pin
 - To set a pin as an input port, set the bit in the DDR6 register corresponding to the input pin of a peripheral function to “0”.
 - Reading the PDR6 register returns the pin value, regardless of whether the peripheral function uses that pin as its input pin. However, if the read-modify-write (RMW) type of instruction is used to read the PDR6 register, the PDR6 register value is returned.

- Operation at reset

If the CPU is reset, all bits in the DDR6 register are initialized to “0” and port input is enabled.

- Operation in stop mode and watch mode
 - If the pin state setting bit in the standby control register (STBC:SPL) is set to “1” and the device transits to stop mode or watch mode, the pin is compulsorily made to enter the high impedance state regardless of the DDR6 register value. The input of that pin is locked to “L” level and blocked in order to prevent leaks due to input open. However, if the interrupt input from the external interrupt (INT08, INT09) is enabled, or if the interrupt input of P64/EC1 and P67/TRG1 is enabled by the external interrupt control register ch. 0 (EIC00) of the external interrupt circuit and the interrupt pin selection circuit control register (WICR) of the interrupt pin selection circuit, the input is enabled and is not blocked.
 - If the pin state setting bit is “0”, the state of the port I/O or that of the peripheral function I/O remains unchanged and the output level is maintained.

- Operation of the pull-up register

Setting the bit in the PUL6 register to “1” makes the pull-up resistor be internally connected to the pin. When the pin output is “L” level, the pull-up resistor is disconnected regardless of the value of the PUL6 register.

15.4 Port F

Port F is a general-purpose I/O port. This section focuses on its functions as a general-purpose I/O port. For details of peripheral functions, refer to their respective chapters in “New 8FX CY95630H Series Hardware Manual”.

15.4.1 Port F configuration

Port F is made up of the following elements.

- General-purpose I/O pins/peripheral function I/O pins
- Port F data register (PDRF)
- Port F direction register (DDRF)

15.4.2 Block diagrams of port F

- PF0/X0 pin

This pin has the following peripheral function:

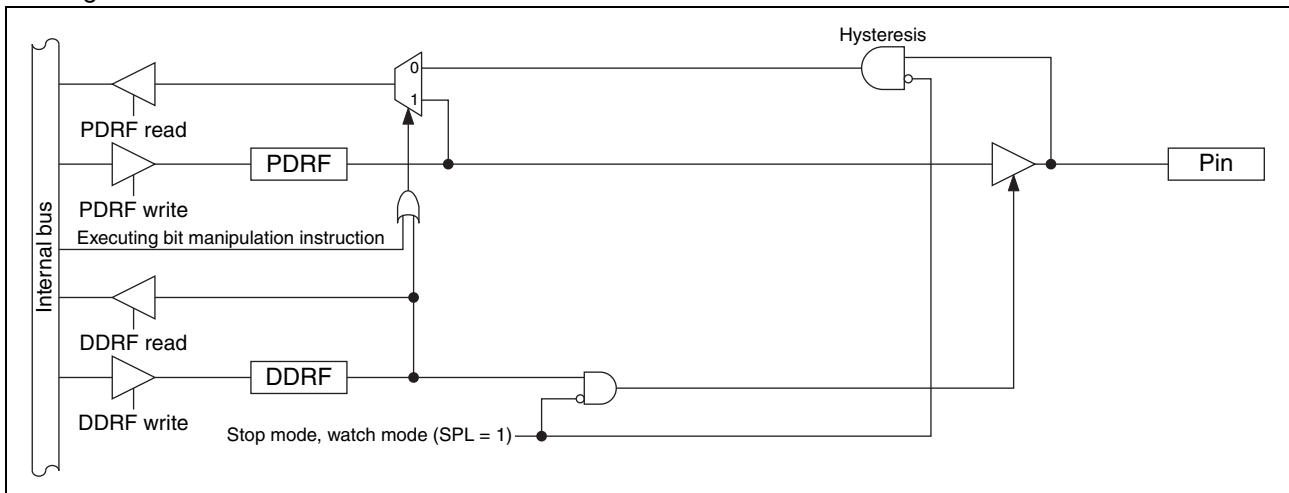
- Main clock input oscillation pin (X0)

- PF1/X1 pin

This pin has the following peripheral function:

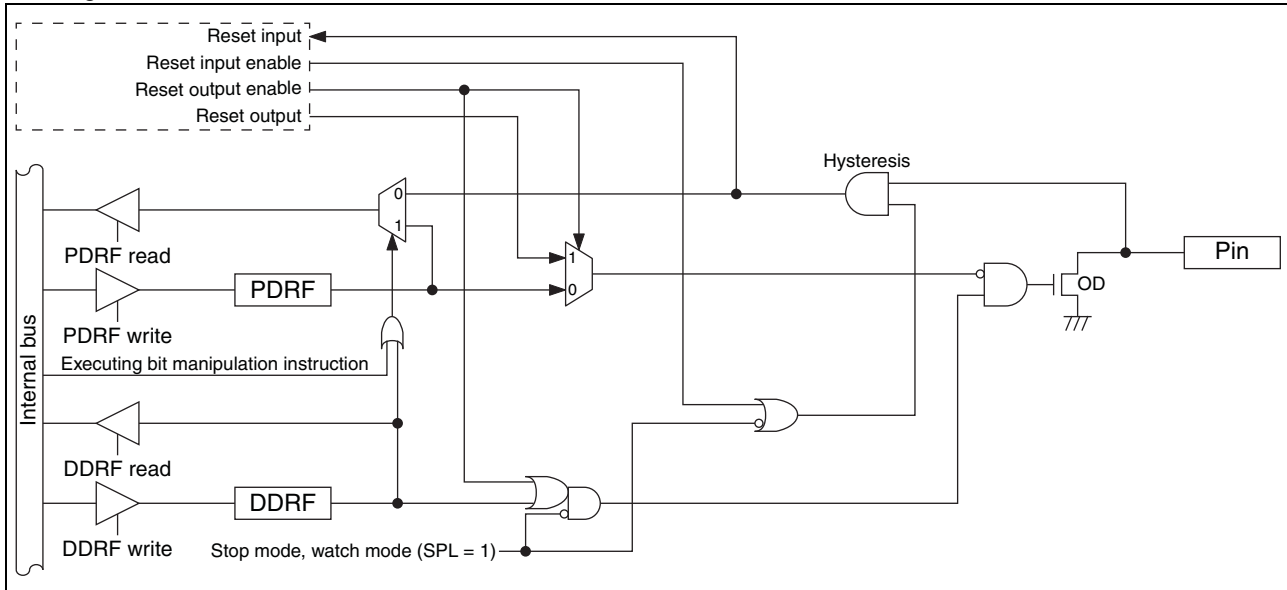
- Main clock I/O oscillation pin (X1)

- Block diagram of PF0/X0 and PF1/X1



- PF2/ $\overline{\text{RST}}$ pin
 - This pin has the following peripheral function:
 - Reset pin ($\overline{\text{RST}}$)

• Block diagram of PF2/ $\overline{\text{RST}}$



15.4.3 Port F registers

- Port F register functions

| Register abbreviation | Data | Read | Read by read-modify-write (RMW) instruction | Write |
|-----------------------|------|-------------------------|---|-------------------------------------|
| PDRF | 0 | Pin state is "L" level. | PDRF value is "0". | As output port, outputs "L" level. |
| | 1 | Pin state is "H" level. | PDRF value is "1". | As output port, outputs "H" level.* |
| DDRF | 0 | Port input enabled | | |
| | 1 | Port output enabled | | |

*: If the pin is an N-ch open drain pin, the pin state becomes Hi-Z.

- Correspondence between registers and pins for port F

| Pin name | Correspondence between related register bits and pins | | | | | | | |
|----------|---|---|---|---|---|------|------|------|
| | - | - | - | - | - | PF2* | PF1 | PF0 |
| PDRF | - | - | - | - | - | bit2 | bit1 | bit0 |
| DDRF | - | - | - | - | - | | | |

*: PF2/ $\overline{\text{RST}}$ is the dedicated reset pin on CY95F632H/F633H/F634H/F636H.

15.4.4 Port F operations

- Operation as an output port
 - A pin becomes an output port if the bit in the DDRF register corresponding to that pin is set to "1".
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
 - When a pin is used as an output port, it outputs the value of the PDRF register to external pins.
 - If data is written to the PDRF register, the value is stored in the output latch and is output to the pin set as an output port as it is.
 - Reading the PDRF register returns the PDRF register value.

- Operation as an input port
 - A pin becomes an input port if the bit in the DDRF register corresponding to that pin is set to “0”.
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
 - If data is written to the PDRF register, the value is stored in the output latch but is not output to the pin set as an input port.
 - Reading the PDRF register returns the pin value. However, if the read-modify-write (RMW) type of instruction is used to read the PDRF register, the PDRF register value is returned.
- Operation at reset

If the CPU is reset, all bits in the DDRF register are initialized to “0” and port input is enabled.
- Operation in stop mode and watch mode
 - If the pin state setting bit in the standby control register (STBC:SPL) is set to “1” and the device transits to stop mode or watch mode, the pin is compulsorily made to enter the high impedance state regardless of the DDRF register value. The input of that pin is locked to “L” level and blocked in order to prevent leaks due to input open.
 - If the pin state setting bit is “0”, the state of the port I/O or that of the peripheral function I/O remains unchanged and the output level is maintained.

15.5 Port G

Port G is a general-purpose I/O port. This section focuses on its functions as a general-purpose I/O port. For details of peripheral functions, refer to their respective chapters in “New 8FX CY95630H Series Hardware Manual”.

15.5.1 Port G configuration

Port G is made up of the following elements.

- General-purpose I/O pins/peripheral function I/O pins
- Port G data register (PDRG)
- Port G direction register (DDRG)
- Port G pull-up register (PULG)

15.5.2 Block diagram of port G

- PG1/X0A/SNI1 pin

This pin has the following peripheral functions:

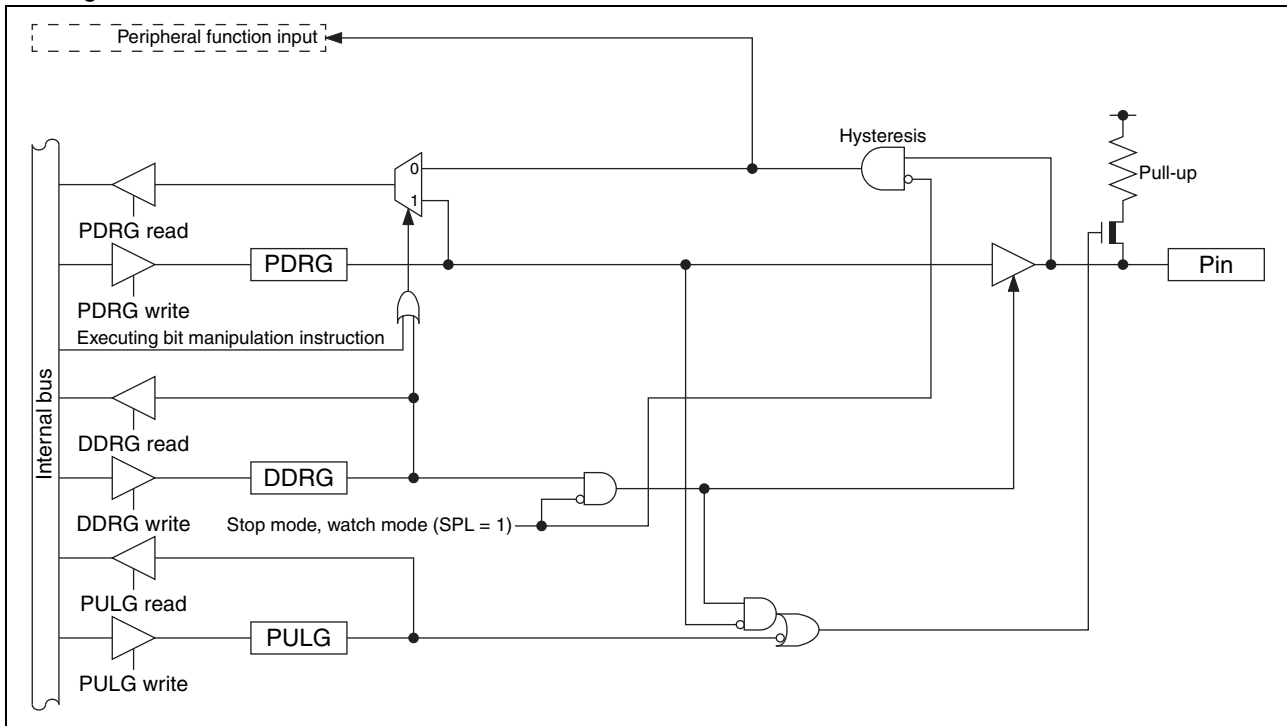
- Subclock input oscillation pin (X0A)
- Trigger input pin for the position detection function of the MPG waveform sequencer (SNI1)

- PG2/X1A/SNI2 pin

This pin has the following peripheral functions:

- Subclock I/O oscillation pin (X1A)
- Trigger input pin for the position detection function of the MPG waveform sequencer (SNI2)

- Block diagram of PG1/X0A/SNI1 and PG2/X1A/SNI2



15.5.3 Port G registers

- Port G register functions

| Register abbreviation | Data | Read | Read by read-modify-write (RMW) instruction | Write |
|-----------------------|------|-------------------------|---|------------------------------------|
| PDRG | 0 | Pin state is "L" level. | PDRG value is "0". | As output port, outputs "L" level. |
| | 1 | Pin state is "H" level. | PDRG value is "1". | As output port, outputs "H" level. |
| DDRG | 0 | Port input enabled | | |
| | 1 | Port output enabled | | |
| PULG | 0 | Pull-up disabled | | |
| | 1 | Pull-up enabled | | |

- Correspondence between registers and pins for port G

| | Correspondence between related register bits and pins | | | | | | | |
|----------|---|---|---|---|---|------|------|---|
| Pin name | - | - | - | - | - | PG2 | PG1 | - |
| PDRG | | | | | | | | |
| DDRG | - | - | - | - | - | bit2 | bit1 | - |
| PULG | | | | | | | | |

15.5.4 Port G operations

- Operation as an output port
 - A pin becomes an output port if the bit in the DDRG register corresponding to that pin is set to "1".
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
 - When a pin is used as an output port, it outputs the value of the PDRG register to external pins.

- If data is written to the PDRG register, the value is stored in the output latch and is output to the pin set as an output port as it is.
- Reading the PDRG register returns the PDRG register value.
- Operation as an input port
 - A pin becomes an input port if the bit in the DDRG register corresponding to that pin is set to “0”.
 - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
 - If data is written to the PDRG register, the value is stored in the output latch but is not output to the pin set as an input port.
 - Reading the PDRG register returns the pin value. However, if the read-modify-write (RMW) type of instruction is used to read the PDRG register, the PDRG register value is returned.
- Operation as a peripheral function input pin
 - To set a pin as an input port, set the bit in the DDRG register corresponding to the input pin of a peripheral function to “0”.
 - Reading the PDRG register returns the pin value, regardless of whether the peripheral function uses that pin as its input pin. However, if the read-modify-write (RMW) type of instruction is used to read the PDRG register, the PDRG register value is returned.
- Operation at reset

If the CPU is reset, all bits in the DDRG register are initialized to “0” and port input is enabled.
- Operation in stop mode and watch mode
 - If the pin state setting bit in the standby control register (STBC:SPL) is set to “1” and the device transits to stop mode or watch mode, the pin is compulsorily made to enter the high impedance state regardless of the DDRG register value. The input of that pin is locked to “L” level and blocked in order to prevent leaks due to input open.
 - If the pin state setting bit is “0”, the state of the port I/O or that of the peripheral function I/O remains unchanged and the output level is maintained.
- Operation of the pull-up register

Setting the bit in the PULG register to “1” makes the pull-up resistor be internally connected to the pin. When the pin output is “L” level, the pull-up resistor is disconnected regardless of the value of the PULG register.

16. Interrupt Source Table

| Interrupt source | Interrupt request number | Vector table address | | Interrupt level setting register | | Priority order of interrupt sources of the same level (occurring simultaneously) |
|--|--------------------------|----------------------|--------|----------------------------------|-----------|---|
| | | Upper | Lower | Register | Bit | |
| External interrupt ch. 0 | IRQ00 | 0xFFFA | 0xFFFB | ILR0 | L00 [1:0] | <div style="display: flex; align-items: center; justify-content: center;"> <div style="text-align: center;">High</div> <div style="flex-grow: 1; border-left: 1px solid black; position: relative;"> <div style="position: absolute; top: -10px; left: 50%; transform: translate(-50%, -100%);">↑</div> <div style="position: absolute; bottom: -10px; left: 50%; transform: translate(-50%, 100%);">↓</div> </div> <div style="text-align: center;">Low</div> </div> |
| External interrupt ch. 4 | | | | | | |
| External interrupt ch. 1 | IRQ01 | 0xFFF8 | 0xFFF9 | ILR0 | L01 [1:0] | |
| External interrupt ch. 5 | | | | | | |
| External interrupt ch. 2 | IRQ02 | 0xFFF6 | 0xFFF7 | ILR0 | L02 [1:0] | |
| External interrupt ch. 6 | | | | | | |
| External interrupt ch. 3 | IRQ03 | 0xFFF4 | 0xFFF5 | ILR0 | L03 [1:0] | |
| External interrupt ch. 7 | | | | | | |
| UART/SIO ch. 0 | IRQ04 | 0xFFF2 | 0xFFF3 | ILR1 | L04 [1:0] | |
| MPG (DTTI) | | | | | | |
| 8/16-bit composite timer ch. 0 (lower) | IRQ05 | 0xFFF0 | 0xFFF1 | ILR1 | L05 [1:0] | |
| 8/16-bit composite timer ch. 0 (upper) | | | | | | |
| 8/16-bit composite timer ch. 0 (upper) | IRQ06 | 0xFFEE | 0xFFEF | ILR1 | L06 [1:0] | |
| 8/16-bit composite timer ch. 0 (lower) | | | | | | |
| LIN-UART (reception) | IRQ07 | 0xFFEC | 0xFFED | ILR1 | L07 [1:0] | |
| LIN-UART (transmission) | | | | | | |
| 8/16-bit PPG ch. 1 (lower) | IRQ09 | 0xFFE8 | 0xFFE9 | ILR2 | L09 [1:0] | |
| 8/16-bit PPG ch. 1 (upper) | | | | | | |
| 8/16-bit PPG ch. 2 (upper) | IRQ11 | 0xFFE4 | 0xFFE5 | ILR2 | L11 [1:0] | |
| 8/16-bit PPG ch. 0 (upper) | | | | | | |
| 8/16-bit PPG ch. 0 (upper) | IRQ12 | 0xFFE2 | 0xFFE3 | ILR3 | L12 [1:0] | |
| 8/16-bit PPG ch. 0 (lower) | | | | | | |
| 8/16-bit PPG ch. 0 (lower) | IRQ13 | 0xFFE0 | 0xFFE1 | ILR3 | L13 [1:0] | |
| 8/16-bit composite timer ch. 1 (upper) | | | | | | |
| 8/16-bit composite timer ch. 1 (upper) | IRQ14 | 0xFFDE | 0xFFDF | ILR3 | L14 [1:0] | |
| 8/16-bit PPG ch. 2 (lower) | | | | | | |
| 8/16-bit PPG ch. 2 (lower) | IRQ15 | 0xFFDC | 0xFFDD | ILR3 | L15 [1:0] | |
| 16-bit reload timer ch. 1 | | | | | | |
| 16-bit reload timer ch. 1 | IRQ16 | 0xFFDA | 0xFFDB | ILR4 | L16 [1:0] | |
| MPG (write timing/compare clear) | | | | | | |
| I ² C bus interface | IRQ17 | 0xFFD8 | 0xFFD9 | ILR4 | L17 [1:0] | |
| 16-bit PPG timer ch. 1 | | | | | | |
| MPG (position detection/compare interrupt) | IRQ18 | 0xFFD6 | 0xFFD7 | ILR4 | L18 [1:0] | |
| 8/10-bit A/D converter | | | | | | |
| 8/10-bit A/D converter | IRQ19 | 0xFFD4 | 0xFFD5 | ILR4 | L19 [1:0] | |
| Time-base timer | | | | | | |
| Time-base timer | IRQ20 | 0xFFD2 | 0xFFD3 | ILR5 | L20 [1:0] | |
| Watch prescaler | | | | | | |
| Watch prescaler | IRQ21 | 0xFFD0 | 0xFFD1 | ILR5 | L21 [1:0] | |
| Comparator | | | | | | |
| External interrupt ch. 8 | IRQ21 | 0xFFD0 | 0xFFD1 | ILR5 | L21 [1:0] | |
| External interrupt ch. 9 | | | | | | |
| External interrupt ch. 9 | IRQ22 | 0xFFCE | 0xFFCF | ILR5 | L22 [1:0] | |
| 8/16-bit composite timer ch. 1 (lower) | | | | | | |
| 8/16-bit composite timer ch. 1 (lower) | IRQ23 | 0xFFCC | 0xFFCD | ILR5 | L23 [1:0] | |
| Flash memory | | | | | | |

17. Pin States In Each Mode

| Pin name | Normal operation | Sleep mode | Stop mode | | Watch mode | | On reset |
|-----------------------------|--|--|---|--|---|--|---|
| | | | SPL=0 | SPL=1 | SPL=0 | SPL=1 | |
| PF0/X0 | Oscillation input | Oscillation input | Hi-Z | Hi-Z | Hi-Z | Hi-Z | — |
| | I/O port*4 | I/O port*4 | - Previous state kept - Input blocked*2*4 | - Hi-Z - Input blocked*2*4 | - Previous state kept - Input blocked*2*4 | - Hi-Z - Input blocked*2*4 | - Hi-Z - Input enabled*1 (However, it does not function.) |
| PF1/X1 | Oscillation input | Oscillation input | Hi-Z | Hi-Z | Hi-Z | Hi-Z | — |
| | I/O port*4 | I/O port*4 | - Previous state kept - Input blocked*2*4 | - Hi-Z - Input blocked*2*4 | - Previous state kept - Input blocked*2*4 | - Hi-Z - Input blocked*2*4 | - Hi-Z - Input enabled*1 (However, it does not function.) |
| PG1/X0A/ SNI1 | Oscillation input | Oscillation input | Hi-Z | Hi-Z | Hi-Z | Hi-Z | — |
| | I/O port*4/ peripheral function I/O | I/O port*4/ peripheral function I/O | - Previous state kept - Input blocked*2*4 | - Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2*4 | - Previous state kept - Input blocked*2*4 | - Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2*4 | - Hi-Z - Input enabled*1 (However, it does not function.) |
| PG2/X1A/ SNI2 | Oscillation input | Oscillation input | Hi-Z | Hi-Z | Hi-Z | Hi-Z | — |
| | I/O port*4/ peripheral function I/O | I/O port*4/ peripheral function I/O | - Previous state kept - Input blocked*2*4 | - Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2*4 | - Previous state kept - Input blocked*2*4 | - Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2*4 | - Hi-Z - Input enabled*1 (However, it does not function.) |
| PF2/RST | I/O port | Reset input | Reset input | Reset input | Reset input | Reset input | Reset input*3 |
| P60/INT08/ SDA/DTTI | I/O port/ peripheral function I/O | I/O port/ peripheral function I/O | - Previous state kept - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) | - Hi-Z - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) | - Previous state kept - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) | - Hi-Z - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) | - Hi-Z - Input enabled*1 (However, it does not function.) |
| P61/INT09/ SCL/TI1 | | | | | | | |
| P62/TO10/ PPG00/ OPT0 | I/O port/ peripheral function I/O | I/O port/ peripheral function I/O | - Previous state kept - Input blocked*2 | - Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2 | - Previous state kept - Input blocked*2 | - Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2 | - Hi-Z - Input enabled*1 (However, it does not function.) |
| P63/TO11/ PPG01/ OPT1 | | | | | | | |

| Pin name | Normal operation | Sleep mode | Stop mode | | Watch mode | | On reset |
|---|---|---|---|--|---|--|---|
| | | | SPL=0 | SPL=1 | SPL=0 | SPL=1 | |
| P64/EC1/ PPG10/ OPT2 | I/O port/ peripheral function I/O | I/O port/ peripheral function I/O | - Previous state kept - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) | - Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) | - Previous state kept - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) | - Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) | - Hi-Z - Input enabled*1 (However, it does not function.) |
| P65/PPG11/ OPT3 P66/PPG1/ PPG20/ OPT4 | I/O port/ peripheral function I/O | I/O port/ peripheral function I/O | - Previous state kept - Input blocked*2 | - Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2 | - Previous state kept - Input blocked*2 | - Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2 | - Hi-Z - Input enabled*1 (However, it does not function.) |
| P67/TRG1/ PPG21/ OPT5 | I/O port/ peripheral function I/O | I/O port/ peripheral function I/O | - Previous state kept - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) | - Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) | - Previous state kept - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) | - Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) | - Hi-Z - Input enabled*1 (However, it does not function.) |
| P10/PPG10/ CMP0_O P11/PPG11 | I/O port/ peripheral function I/O | I/O port/ peripheral function I/O | - Previous state kept - Input blocked*2 | - Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2 | - Previous state kept - Input blocked*2 | - Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2 | - Hi-Z - Input enabled*1 (However, it does not function.) |
| P12/DBG/ EC0 | I/O port/ peripheral function I/O | I/O port/ peripheral function I/O | - Previous state kept - Input blocked*2 | - Hi-Z - Input blocked*2 | - Previous state kept - Input blocked*2 | - Hi-Z - Input blocked*2 | - Hi-Z - Input enabled*1 (However, it does not function.) |
| P13/PPG00 | I/O port/ peripheral function I/O | I/O port/ peripheral function I/O | - Previous state kept - Input blocked*2 | - Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2 | - Previous state kept - Input blocked*2 | - Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2 | - Hi-Z - Input enabled*1 (However, it does not function.) |

| Pin name | Normal operation | Sleep mode | Stop mode | | Watch mode | | On reset |
|-------------------------------|--|--|---|--|---|--|---|
| | | | SPL=0 | SPL=1 | SPL=0 | SPL=1 | |
| P14/UCK0/ PPG01 | I/O port/ peripheral function I/O | I/O port/ peripheral function I/O | - Previous state kept - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) | - Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) | - Previous state kept - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) | - Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) | - Hi-Z - Input enabled*1 (However, it does not function.) |
| P15/UO0/ PPG20 | I/O port/ peripheral function I/O | I/O port/ peripheral function I/O | - Previous state kept - Input blocked*2 | - Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2 | - Previous state kept - Input blocked*2 | - Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2 | - Hi-Z - Input enabled*1 (However, it does not function.) |
| P16/UI0/ PPG21 | I/O port/ peripheral function I/O | I/O port/ peripheral function I/O | - Previous state kept - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) | - Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) | - Previous state kept - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) | - Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) | - Hi-Z - Input enabled*1 (However, it does not function.) |
| P17/TO1/ SNI0 | I/O port/ peripheral function I/O | I/O port/ peripheral function I/O | - Previous state kept - Input blocked*2 | - Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2 | - Previous state kept - Input blocked*2 | - Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2 | - Hi-Z - Input enabled*1 (However, it does not function.) |
| P00/INT00/ AN00/ CMP0_P | I/O port/ peripheral function I/O/ analog input | I/O port/ peripheral function I/O/ analog input | - Previous state kept | - Hi-Z (However, the setting of the pull-up control is effective.) | - Previous state kept | - Hi-Z (However, the setting of the pull-up control is effective.) | - Hi-Z - Input blocked*2 |
| P01/INT01/ AN01/ CMP0_N | | | - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) | - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) | - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) | - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) | |
| P02/INT02/ AN02/SCK | | | | | | | |
| P03/INT03/ AN03/SOT | | | | | | | |

| Pin name | Normal operation | Sleep mode | Stop mode | | Watch mode | | On reset |
|--------------------------------|--|--|---|--|---|--|-----------------------------|
| | | | SPL=0 | SPL=1 | SPL=0 | SPL=1 | |
| P04/INT04/ AN04/SIN/ EC0 | I/O port/ peripheral function I/O/ analog input | I/O port/ peripheral function I/O/ analog input | - Previous state kept - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) | - Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) | - Previous state kept - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) | - Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.) | - Hi-Z - Input blocked*2 |
| P05/INT05/ AN05/TO00 | | | | | | | |
| P06/INT06/ AN06/TO01 | | | | | | | |
| P07/INT07/ AN07 | | | | | | | |

SPL: Pin state setting bit in the standby control register (STBC:SPL)

Hi-Z: High impedance

*1: "Input enabled" means that the input function is enabled. While the input function is enabled, a pull-up or pull-down operation has to be performed in order to prevent leaks due to external input. If a pin is used as an output port, its pin state is the same as that of other ports.

*2: "Input blocked" means direct input gate operation from the pin is disabled.

*3: The PF2/RST pin stays at the state shown when configured as a reset pin.

*4: The pin stays at the state shown when configured as a general-purpose I/O port.

18. Electrical Characteristics

18.1 Absolute Maximum Ratings

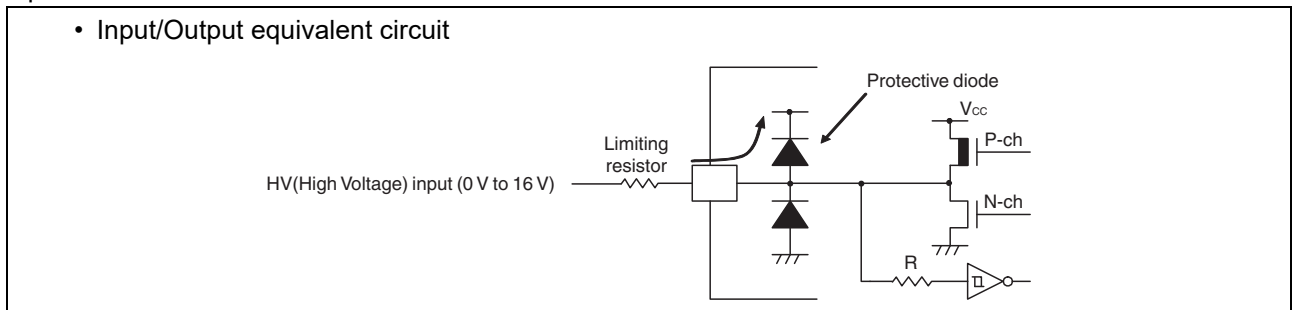
| Parameter | Symbol | Rating | | Unit | Remarks |
|--|--------------------|----------------|--------------|------|--|
| | | Min | Max | | |
| Power supply voltage*1 | V_{CC} | $V_{SS} - 0.3$ | $V_{SS} + 6$ | V | |
| Input voltage*1 | V_I | $V_{SS} - 0.3$ | $V_{SS} + 6$ | V | *2 |
| Output voltage*1 | V_O | $V_{SS} - 0.3$ | $V_{SS} + 6$ | V | *2 |
| Maximum clamp current | I_{CLAMP} | -2 | +2 | mA | Applicable to specific pins*3 |
| Total maximum clamp current | $\sum I_{CLAMP} $ | — | 20 | mA | Applicable to specific pins*3 |
| “L” level maximum output current | I_{OL} | — | 15 | mA | |
| “L” level average current | I_{OLAV1} | — | 4 | mA | Other than P62 to P67 Average output current = operating current × operating ratio (1 pin) |
| | I_{OLAV2} | | 12 | | P62 to P67 Average output current = operating current × operating ratio (1 pin) |
| “L” level total maximum output current | $\sum I_{OL}$ | — | 100 | mA | |
| “L” level total average output current | $\sum I_{OLAV}$ | — | 37 | mA | Total average output current = operating current × operating ratio (Total number of pins) |
| “H” level maximum output current | I_{OH} | — | -15 | mA | |
| “H” level average current | I_{OHAV1} | — | -4 | mA | Other than P62 to P67 Average output current = operating current × operating ratio (1 pin) |
| | I_{OHAV2} | | -8 | | P62 to P67 Average output current = operating current × operating ratio (1 pin) |
| “H” level total maximum output current | $\sum I_{OH}$ | — | -100 | mA | |
| “H” level total average output current | $\sum I_{OHAV}$ | — | -47 | mA | Total average output current = operating current × operating ratio (Total number of pins) |
| Power consumption | P_d | — | 320 | mW | |
| Operating temperature | T_A | -40 | +85 | °C | |
| Storage temperature | T_{stg} | -55 | +150 | °C | |

*1: These parameters are based on the condition that V_{SS} is 0.0 V.

*2: V_I and V_O must not exceed $V_{CC} + 0.3$ V. V_I must not exceed the rated voltage. However, if the maximum current to/from an input is limited by means of an external component, the I_{CLAMP} rating is used instead of the V_I rating.

*3: Specific pins: P00 to P07, P10, P11, P13 to P17, P62 to P67, PF0, PF1, PG1, PG2

- Use under recommended operating conditions.
- Use with DC voltage (current).
- The HV (High Voltage) signal is an input signal exceeding the V_{CC} voltage. Always connect a limiting resistor between the HV (High Voltage) signal and the microcontroller before applying the HV (High Voltage) signal.
- The value of the limiting resistor should be set to a value at which the current to be input to the microcontroller pin when the HV (High Voltage) signal is input is below the standard value, irrespective of whether the current is transient current or stationary current.
- When the microcontroller drive current is low, such as in low power consumption modes, the HV (High Voltage) input potential may pass through the protective diode to increase the potential of the V_{CC} pin, affecting other devices.
- If the HV (High Voltage) signal is input when the microcontroller power supply is off (not fixed at 0 V), since power is supplied from the pins, incomplete operations may be executed.
- If the HV (High Voltage) input is input after power-on, since power is supplied from the pins, the voltage of power supply may not be sufficient to enable a power-on reset.
- Do not leave the HV (High Voltage) input pin unconnected.
- Example of a recommended circuit:



WARNING: Semiconductor devices may be permanently damaged by application of stress (including, without limitation, voltage, current or temperature) in excess of absolute maximum ratings. Do not exceed any of these ratings.

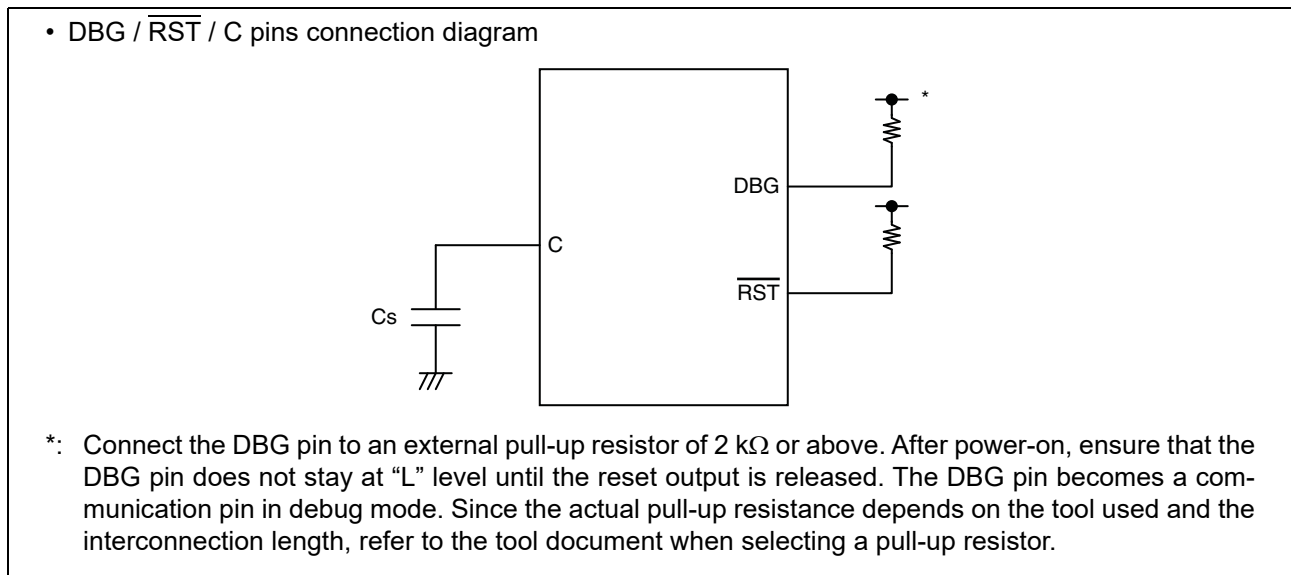
18.2 Recommended Operating Conditions

(V_{SS} = 0.0 V)

| Parameter | Symbol | Value | | Unit | Remarks |
|-----------------------|-----------------|-------|-----|------|-------------------------------|
| | | Min | Max | | |
| Power supply voltage | V _{CC} | 2.4*1 | 5.5 | V | In normal operation |
| | | 2.3 | 5.5 | | Hold condition in stop mode |
| Decoupling capacitor | C _s | 0.022 | 1 | μF | *2 |
| Operating temperature | T _A | - 40 | +85 | °C | Other than on-chip debug mode |
| | | +5 | +35 | | On-chip debug mode |

*1: The minimum power supply voltage becomes 2.88 V when a product with the low-voltage detection reset is used or when the on-chip debug mode is used.

*2: Use a ceramic capacitor or a capacitor with equivalent frequency characteristics. The decoupling capacitor for the V_{CC} pin must have a capacitance equal to or larger than the capacitance of C_s. For the connection to a decoupling capacitor C_s, see the diagram below. To prevent the device from unintentionally entering an unknown mode due to noise, minimize the distance between the C pin and C_s and the distance between C_s and the V_{SS} pin when designing the layout of a printed circuit board.



WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated under these conditions.

Any use of semiconductor devices will be under their recommended operating condition. Operation under any conditions other than these conditions may adversely affect reliability of device and could result in device failure.

No warranty is made with respect to any use, operating conditions or combinations not represented on this data sheet. If you are considering application under any conditions other than listed herein, please contact sales representatives beforehand.

18.3 DC Characteristics
 $(V_{CC} = 5.0\text{ V} \pm 10\%, V_{SS} = 0.0\text{ V}, T_A = -40\text{ }^\circ\text{C to } +85\text{ }^\circ\text{C})$

| Parameter | Symbol | Pin name | Condition | Value | | | Unit | Remarks |
|---|------------|--|-------------------------------|----------------|-----|----------------|---------------|--|
| | | | | Min | Typ | Max | | |
| “H” level input voltage | V_{IH1} | P04, P16, P60, P61 | — | $0.7 V_{CC}$ | — | $V_{CC} + 0.3$ | V | CMOS input level |
| | V_{IHS} | P00 to P07, P10 to P17, P60 to P67, PF0, PF1, PG1, PG2 | — | $0.8 V_{CC}$ | — | $V_{CC} + 0.3$ | V | Hysteresis input |
| | V_{IHM} | PF2 | — | $0.8 V_{CC}$ | — | $V_{CC} + 0.3$ | V | Hysteresis input |
| “L” level input voltage | V_{IL1} | P04, P16, P60, P61 | — | $V_{SS} - 0.3$ | — | $0.3 V_{CC}$ | V | CMOS input level |
| | V_{ILS} | P00 to P07, P10 to P17, P60 to P67, PF0, PF1, PG1, PG2 | — | $V_{SS} - 0.3$ | — | $0.2 V_{CC}$ | V | Hysteresis input |
| | V_{ILM} | PF2 | — | $V_{SS} - 0.3$ | — | $0.2 V_{CC}$ | V | Hysteresis input |
| Open-drain output application voltage | V_D | P12, P60, P61, PF2 | — | $V_{SS} - 0.3$ | — | $V_{SS} + 5.5$ | V | |
| “H” level output voltage | V_{OH1} | Output pins other than P12, P62 to P67, PF2 | $I_{OH} = -4\text{ mA}$ | $V_{CC} - 0.5$ | — | — | V | |
| | V_{OH2} | P62 to P67 | $I_{OH} = -8\text{ mA}$ | $V_{CC} - 0.5$ | — | — | V | |
| “L” level output voltage | V_{OL1} | Output pins other than P62 to P67 | $I_{OL} = 4\text{ mA}$ | — | — | 0.4 | V | |
| | V_{OL2} | P62 to P67 | $I_{OL} = 12\text{ mA}$ | — | — | 0.4 | V | |
| Input leak current (Hi-Z output leak current) | I_{LI} | All input pins | $0.0\text{ V} < V_I < V_{CC}$ | -5 | — | +5 | μA | When the internal pull-up resistor is disabled |
| Internal pull-up resistor | R_{PULL} | P00 to P07, P10, P11, P13 to P17, P62 to P67, PG1, PG2 | $V_I = 0\text{ V}$ | 25 | 50 | 100 | k Ω | When the internal pull-up resistor is enabled |
| Input capacitance | C_{IN} | Other than V_{CC} and V_{SS} | $f = 1\text{ MHz}$ | — | 5 | 15 | pF | |

(V_{CC} = 5.0 V±10%, V_{SS} = 0.0 V, T_A = -40 °C to +85 °C)

| Parameter | Symbol | Pin name | Condition | Value | | | Unit | Remarks |
|------------------------|---------------------|--|---|-------|-------|-------|----------------------|--|
| | | | | Min | Typ*1 | Max*2 | | |
| Power supply current*3 | I _{CC} | V _{CC} (External clock operation) | F _{CH} = 32 MHz F _{MP} = 16 MHz Main clock mode (divided by 2) | — | 3.6 | 5.8 | mA | Except during Flash memory programming and erasing |
| | | | | — | 7.5 | 13.8 | mA | During Flash memory programming and erasing |
| | | | | — | 4.1 | 9.1 | mA | At A/D conversion |
| | I _{CCS} | | F _{CH} = 32 MHz F _{MP} = 16 MHz Main sleep mode (divided by 2) | — | 1.3 | 3 | mA | |
| | I _{CCCL} | | F _{CL} = 32 kHz F _{MPL} = 16 kHz Subclock mode (divided by 2) T _A = +25°C | — | 49 | 145 | μA | |
| | I _{CCLS} | | F _{CL} = 32 kHz F _{MPL} = 16 kHz Subsleep mode (divided by 2) T _A = +25°C | — | 10 | 15 | μA | In deep standby mode |
| | I _{CCCT} | F _{CL} = 32 kHz Watch mode Main stop mode T _A = +25°C | — | 7 | 13 | μA | In deep standby mode | |
| | I _{CCMPLL} | V _{CC} | F _{MCRPLL} = 16 MHz F _{MP} = 16 MHz Main CR PLL clock mode (multiplied by 4) T _A = +25°C | — | 4.7 | 6.8 | mA | |
| | I _{CCMCR} | | F _{CRH} = 4 MHz F _{MP} = 4 MHz Main CR clock mode | — | 1.1 | 4.6 | mA | |
| | I _{CCSCR} | | Sub-CR clock mode (divided by 2) T _A = +25°C | — | 58.1 | 230 | μA | |
| | I _{CCTS} | V _{CC} (External clock operation) | F _{CH} = 32 MHz Time-base timer mode T _A = +25°C | — | 345 | 395 | μA | In deep standby mode |
| | I _{CCCH} | | Substop mode T _A = +25°C | — | 6 | 10 | μA | In deep standby mode |

($V_{CC} = 5.0\text{ V} \pm 10\%$, $V_{SS} = 0.0\text{ V}$, $T_A = -40\text{ }^\circ\text{C}$ to $+85\text{ }^\circ\text{C}$)

| Parameter | Symbol | Pin name | Condition | Value | | | Unit | Remarks |
|------------------------|---------------------|-----------------|--|-------|-------|-------|------|---------|
| | | | | Min | Typ*1 | Max*2 | | |
| Power supply current*3 | I _v | V _{CC} | Current consumption of the comparator | — | 60 | 160 | μA | |
| | I _{LVD} | | Current consumption of the low-voltage detection circuit | — | 4 | 7 | μA | |
| | I _{CRH} | | Current consumption of the main CR oscillator | — | 240 | 320 | μA | |
| | I _{CRL} | | Current consumption of the sub-CR oscillator oscillating at 100 kHz | — | 7 | 20 | μA | |
| | I _{INSTBY} | | Current consumption difference between normal standby mode and deep standby mode T _A = +25°C | — | 20 | 30 | μA | |

 *1: $V_{CC} = 5.0\text{ V}$, $T_A = +25\text{ }^\circ\text{C}$

 *2: $V_{CC} = 5.5\text{ V}$, $T_A = +85\text{ }^\circ\text{C}$ (unless otherwise specified)

 *3: • The power supply current is determined by the external clock. When the low-voltage detection circuit is selected, the power supply current is the sum of adding the current consumption of the low-voltage detection circuit (I_{LVD}) to one of the values from I_{CC} to I_{CCH}. In addition, when both the low-voltage detection option and the CR oscillator are selected, the power supply current is the sum of adding up the current consumption of the low-voltage detection circuit (I_{LVD}), the current consumption of the CR oscillators (I_{CRH}, I_{CRL}) and a specified value. In on-chip debug mode, the CR oscillator (I_{CRH}) and the low-voltage detection circuit are always in operation, and current consumption therefore increases accordingly.

 • See “4. AC Characteristics Clock Timing” for F_{CH}, F_{CL}, F_{CRH} and F_{MCRPLL}.

 • See “4. AC Characteristics Source Clock/Machine Clock” for F_{MP} and F_{MPL}.

 • The power supply current value in standby mode is measured in deep standby mode. The current consumption in normal standby is higher than that in deep standby mode. The power supply current value in normal standby can be found by adding the current consumption difference between normal standby mode and deep standby mode (I_{INSTBY}) to the power supply current value in deep standby mode. For details of normal standby and deep standby mode, refer to “CHAPTER 3 CLOCK CONTROLLER” in “New 8FX CY95630H Series Hardware Manual”.

18.4 AC Characteristics
18.4.1 Clock Timing

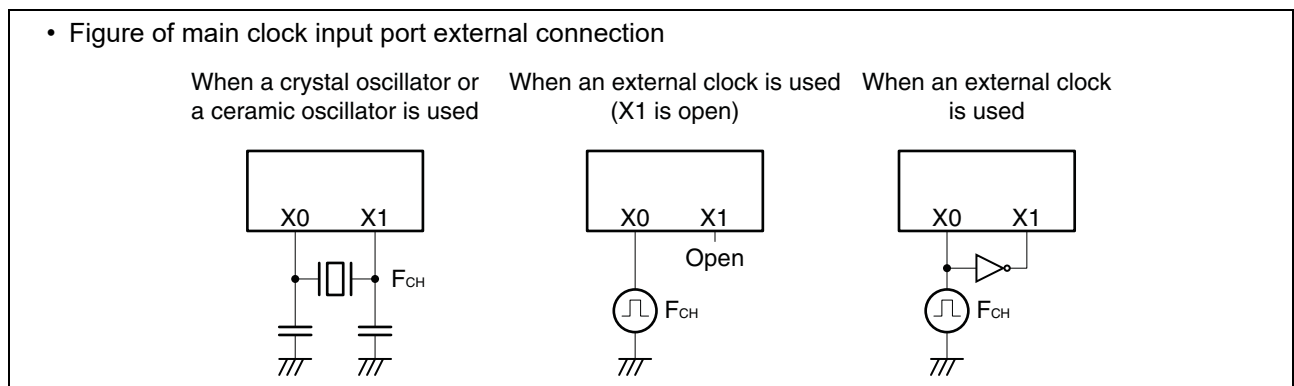
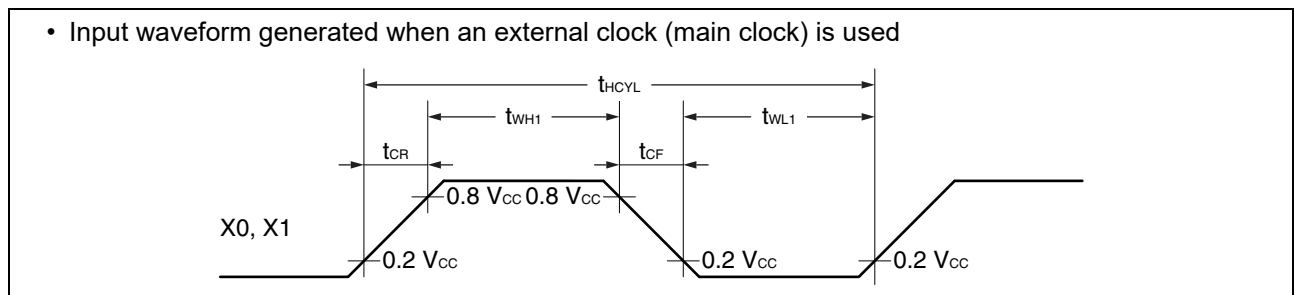
 (V_{CC} = 2.4 V to 5.5 V, V_{SS} = 0.0 V, T_A = -40°C to +85°C)

| Parameter | Symbol | Pin name | Condition | Value | | | Unit | Remarks | |
|-----------------|---------------------|----------|-----------|-------|-------|--------|-------|---|---|
| | | | | Min | Typ | Max | | | |
| Clock frequency | F _{CH} | X0, X1 | — | 1 | — | 16.25 | MHz | When the main oscillation circuit is used | |
| | | X0 | X1: open | 1 | — | 12 | MHz | When the main external clock is used | |
| | | X0, X1 | * | 1 | — | 32.5 | MHz | is used | |
| | F _{CRH} | — | — | — | 3.92 | 4 | 4.08 | MHz | Operating conditions • The main CR clock is used. • 0°C ≤ T _A ≤ +70°C |
| | | | | | 3.8 | 4 | 4.2 | MHz | Operating conditions • The main CR clock is used. • -40 °C ≤ T _A < 0 °C, +70 °C < T _A ≤ +85 °C |
| | F _{MCRPLL} | — | — | — | 7.84 | 8 | 8.16 | MHz | Operating conditions • PLL multiplication rate: 2 • 0°C ≤ T _A ≤ +70°C |
| | | | | | 7.6 | 8 | 8.4 | MHz | Operating conditions • PLL multiplication rate: 2 • -40 °C ≤ T _A < 0 °C, +70 °C < T _A ≤ +85 °C |
| | | | | | 9.8 | 10 | 10.2 | MHz | Operating conditions • PLL multiplication rate: 2.5 • 0°C ≤ T _A ≤ +70°C |
| | | | | | 9.5 | 10 | 10.5 | MHz | Operating conditions • PLL multiplication rate: 2.5 • -40 °C ≤ T _A < 0 °C, +70 °C < T _A ≤ +85 °C |
| | | | | | 11.76 | 12 | 12.24 | MHz | Operating conditions • PLL multiplication rate: 3 • 0°C ≤ T _A ≤ +70°C |
| | | | | | 11.4 | 12 | 12.6 | MHz | Operating conditions • PLL multiplication rate: 3 • -40 °C ≤ T _A < 0 °C, +70 °C < T _A ≤ +85 °C |
| | | | | | 15.68 | 16 | 16.32 | MHz | Operating conditions • PLL multiplication rate: 4 • 0°C ≤ T _A ≤ +70°C |
| | | | | | 15.2 | 16 | 16.8 | MHz | Operating conditions • PLL multiplication rate: 4 • -40 °C ≤ T _A < 0 °C, +70 °C < T _A ≤ +85 °C |
| | F _{CL} | X0A, X1A | — | — | — | 32.768 | — | kHz | When the suboscillation circuit is used |
| | | | | | — | 32.768 | — | kHz | When the sub-external clock is used |
| | F _{CRL} | — | — | — | 50 | 100 | 150 | kHz | When the sub-CR clock is used |

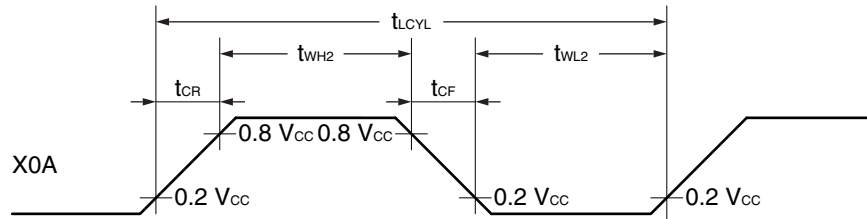
($V_{CC} = 2.4\text{ V to }5.5\text{ V}$, $V_{SS} = 0.0\text{ V}$, $T_A = -40^\circ\text{C to }+85^\circ\text{C}$)

| Parameter | Symbol | Pin name | Condition | Value | | | Unit | Remarks |
|--|--------------------|------------------|-----------|-------|------|------|---------------|--|
| | | | | Min | Typ | Max | | |
| Clock cycle time | t_{HCYL} | X0, X1 | — | 61.5 | — | 1000 | ns | When the main oscillation circuit is used |
| | | X0 | X1: open | 83.4 | — | 1000 | ns | When an external clock is used |
| | | X0, X1 | * | 30.8 | — | 1000 | ns | |
| | t_{LCYL} | X0A, X1A | — | — | 30.5 | — | μs | When the subclock is used |
| Input clock pulse width | t_{WH1}, t_{WL1} | X0 | X1: open | 33.4 | — | — | ns | When an external clock is used, the duty ratio should range between 40% and 60%. |
| | | X0, X1 | * | 12.4 | — | — | ns | |
| | | X0A | — | — | 15.2 | — | μs | |
| Input clock rising time and falling time | t_{CR}, t_{CF} | X0, X0A | X1: open | — | — | 5 | ns | When an external clock is used |
| | | X0, X1, X0A, X1A | * | — | — | 5 | ns | |
| CR oscillation start time | t_{CRHWK} | — | — | — | — | 50 | μs | When the main CR clock is used |
| | t_{CRLWK} | — | — | — | — | 30 | μs | When the sub-CR clock is used |
| PLL oscillation start time | $t_{MCRPLLWK}$ | — | — | — | — | 100 | μs | When the main CR PLL clock is used |

*: The external clock signal is input to X0 and the inverted external clock signal to X1.

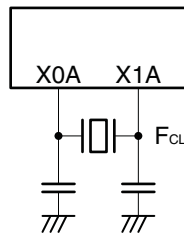


- Input waveform generated when an external clock (subclock) is used

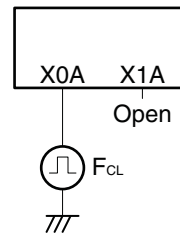


- Figure of subclock input port external connection

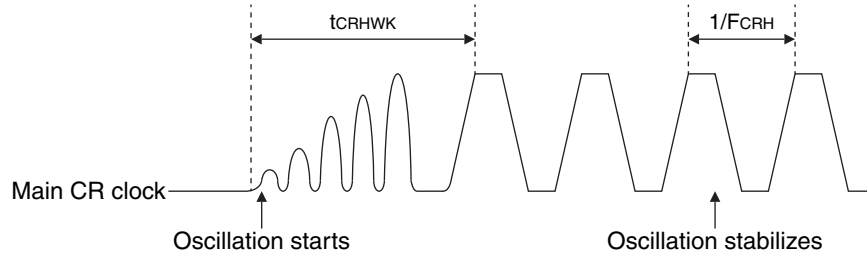
When a crystal oscillator or a ceramic oscillator is used



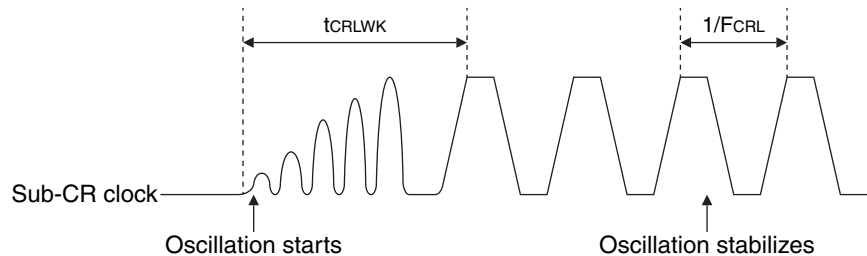
When an external clock is used



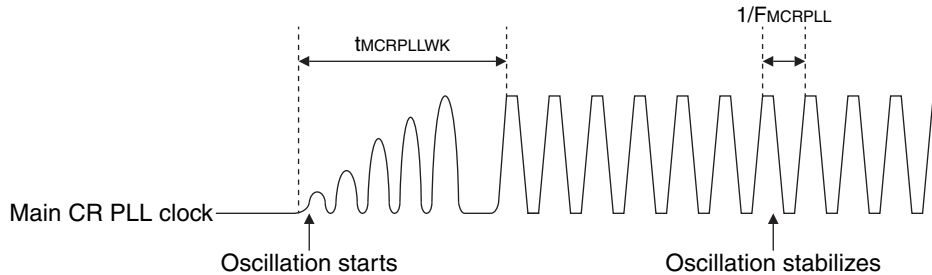
- Input waveform generated when an internal clock (main CR clock) is used



- Input waveform generated when an internal clock (sub-CR clock) is used



- Input waveform generated when an internal clock (main CR PLL clock) is used



18.4.2 Source Clock/Machine Clock

($V_{CC} = 5.0 V \pm 10\%$, $V_{SS} = 0.0 V$, $T_A = -40^\circ C$ to $+85^\circ C$)

| Parameter | Symbol | Pin name | Value | | | Unit | Remarks |
|--|-------------------|----------|-------|--------|-------|------|---|
| | | | Min | Typ | Max | | |
| Source clock cycle time*1 | t _{SCLK} | — | 61.5 | — | 2000 | ns | When the main external clock is used Min: F _{CH} = 32.5 MHz, divided by 2 Max: F _{CH} = 1 MHz, divided by 2 |
| | | | 62.5 | — | 250 | ns | When the main CR clock is used Min: F _{CRH} = 4 MHz, multiplied by 4 Max: F _{CRH} = 4 MHz, no division |
| | | | — | 61 | — | μs | When the suboscillation clock is used F _{CL} = 32.768 kHz, divided by 2 |
| | | | — | 20 | — | μs | When the sub-CR clock is used F _{CL} = 100 kHz, divided by 2 |
| Source clock frequency | F _{SP} | — | 0.5 | — | 16.25 | MHz | When the main oscillation clock is used |
| | | | — | 4 | — | MHz | When the main CR clock is used |
| | F _{SPL} | | — | 16.384 | — | kHz | When the suboscillation clock is used |
| | | | — | 50 | — | kHz | When the sub-CR clock is used F _{CRL} = 100 kHz, divided by 2 |
| Machine clock cycle time*2 (minimum instruction execution time) | t _{MCLK} | — | 61.5 | — | 32000 | ns | When the main oscillation clock is used Min: F _{SP} = 16.25 MHz, no division Max: F _{SP} = 0.5 MHz, divided by 16 |
| | | | 250 | — | 4000 | ns | When the main CR clock is used Min: F _{SP} = 4 MHz, no division Max: F _{SP} = 4 MHz, divided by 16 |
| | | | 61 | — | 976.5 | μs | When the suboscillation clock is used Min: F _{SPL} = 16.384 kHz, no division Max: F _{SPL} = 16.384 kHz, divided by 16 |
| | | | 20 | — | 320 | μs | When the sub-CR clock is used Min: F _{SPL} = 50 kHz, no division Max: F _{SPL} = 50 kHz, divided by 16 |

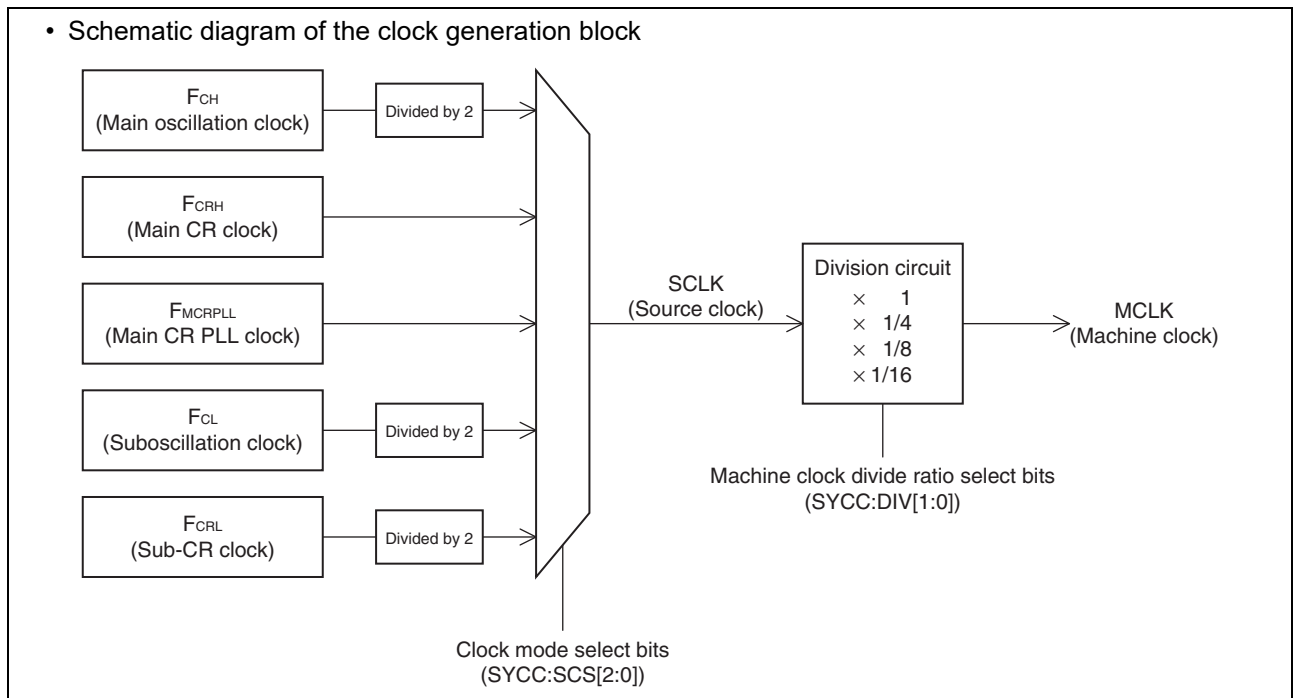
| Parameter | Symbol | Pin name | Value | | | Unit | Remarks |
|-------------------------|------------------|----------|-------|-----|--------|------|---|
| | | | Min | Typ | Max | | |
| Machine clock frequency | F _{MP} | — | 0.031 | — | 16.25 | MHz | When the main oscillation clock is used |
| | | | 0.25 | — | 16 | MHz | When the main CR clock is used |
| | F _{MPL} | | 1.024 | — | 16.384 | kHz | When the suboscillation clock is used |
| | | | 3.125 | — | 50 | kHz | When the sub-CR clock is used F _{CRL} = 100 kHz |

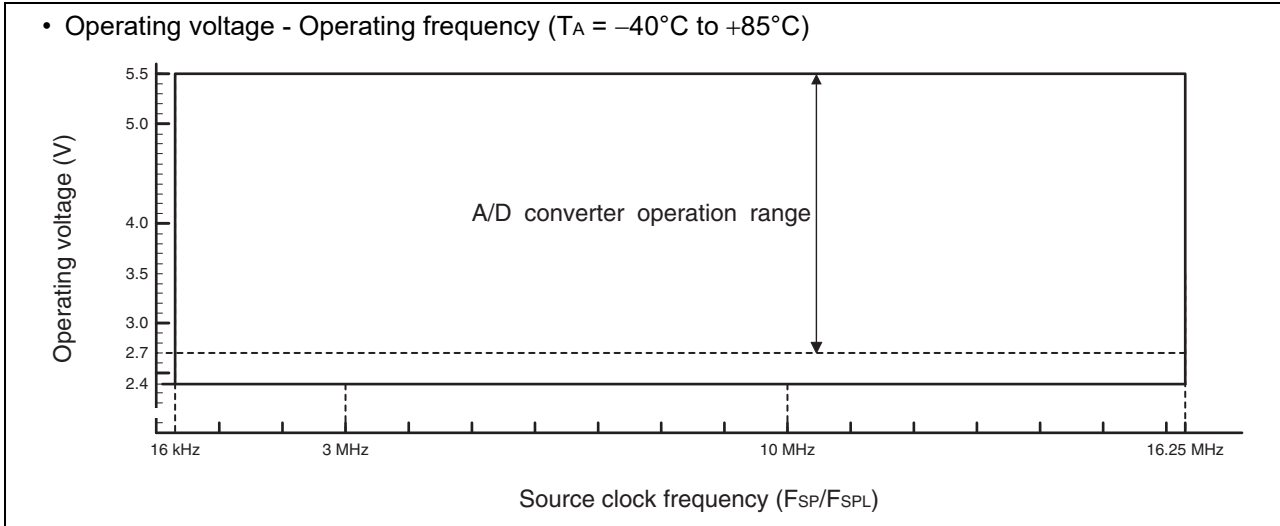
*1: This is the clock before it is divided according to the division ratio set by the machine clock division ratio select bits (SYCC:DIV[1:0]). This source clock is divided to become a machine clock according to the division ratio set by the machine clock division ratio select bits (SYCC:DIV[1:0]). In addition, a source clock can be selected from the following.

- Main clock divided by 2
- Main CR clock
- PLL multiplication of main CR clock (Select a multiplication rate from 2, 2.5, 3 and 4.)
- Subclock divided by 2
- Sub-CR clock divided by 2

*2: This is the operating clock of the microcontroller. A machine clock can be selected from the following.

- Source clock (no division)
- Source clock divided by 4
- Source clock divided by 8
- Source clock divided by 16



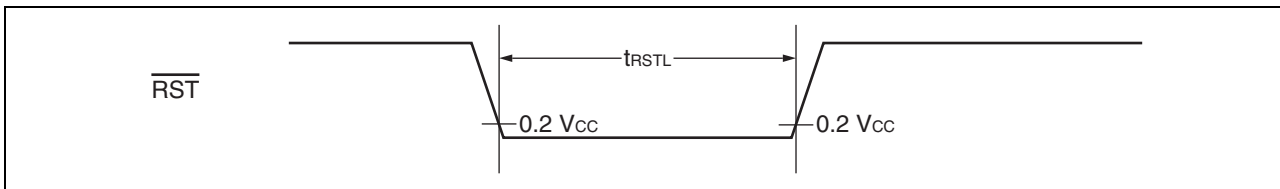


18.4.3 External Reset

($V_{CC} = 5.0\text{ V} \pm 10\%$, $V_{SS} = 0.0\text{ V}$, $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$)

| Parameter | Symbol | Value | | Unit | Remarks |
|---------------------------|------------|----------------|-----|------|---------|
| | | Min | Max | | |
| RST "L" level pulse width | t_{RSTL} | $2 t_{MCLK}^*$ | — | ns | |

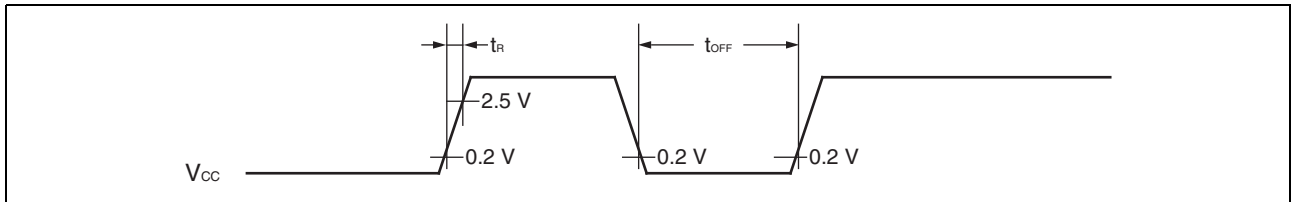
*: See "Source Clock/Machine Clock" for t_{MCLK} .



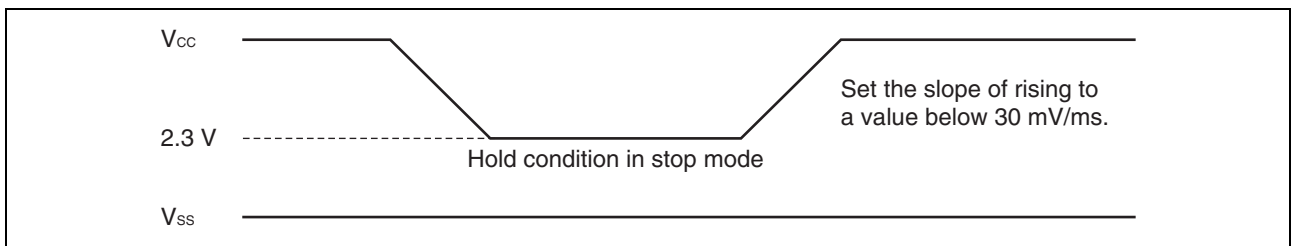
18.4.4 Power-on Reset

($V_{SS} = 0.0\text{ V}$, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$)

| Parameter | Symbol | Condition | Value | | Unit | Remarks |
|--------------------------|-----------|-----------|-------|-----|------|--------------------------|
| | | | Min | Max | | |
| Power supply rising time | t_R | — | — | 50 | ms | |
| Power supply cutoff time | t_{OFF} | — | 1 | — | ms | Wait time until power-on |



Note: A sudden change of power supply voltage may activate the power-on reset function. When changing the power supply voltage during the operation, set the slope of rising to a value below within 30 mV/ms as shown below.

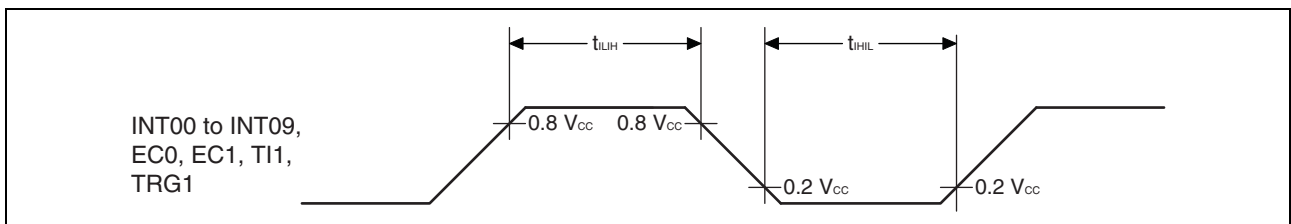


18.4.5 Peripheral Input Timing

($V_{CC} = 5.0\text{ V} \pm 10\%$, $V_{SS} = 0.0\text{ V}$, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$)

| Parameter | Symbol | Pin name | Value | | Unit |
|----------------------------------|----------|-------------------------------------|----------------|-----|------|
| | | | Min | Max | |
| Peripheral input "H" pulse width | t_{LH} | INT00 to INT09, EC0, EC1, TI1, TRG1 | $2 t_{MCLK}^*$ | — | ns |
| Peripheral input "L" pulse width | t_{HL} | TRG1 | $2 t_{MCLK}^*$ | — | ns |

*: See "Source Clock/Machine Clock" for t_{MCLK} .



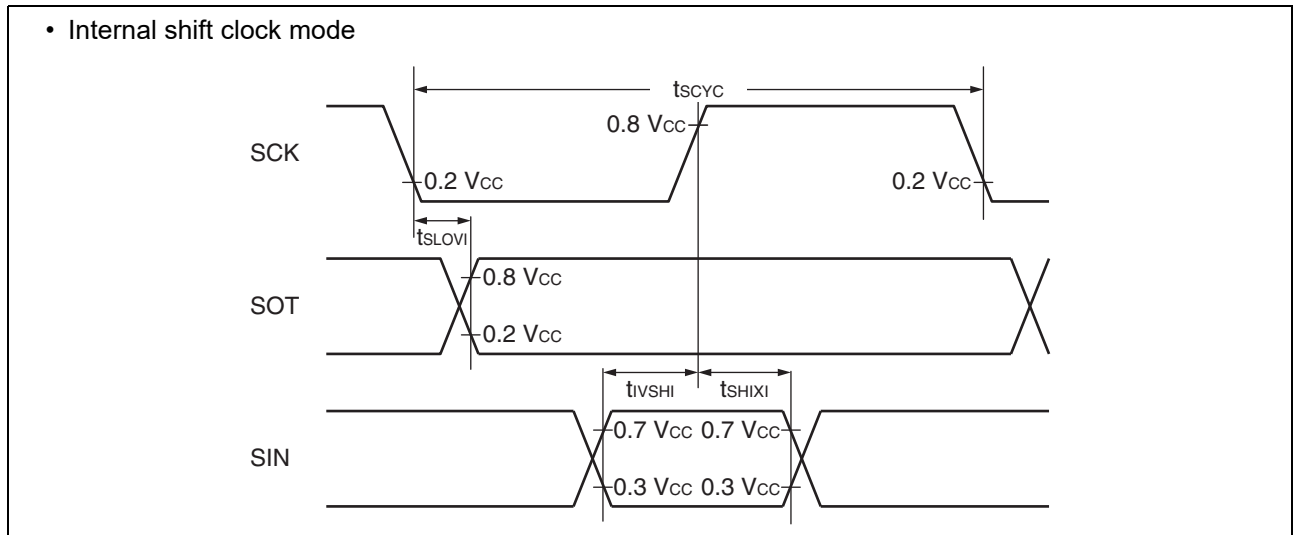
18.4.6 LIN-UART Timing

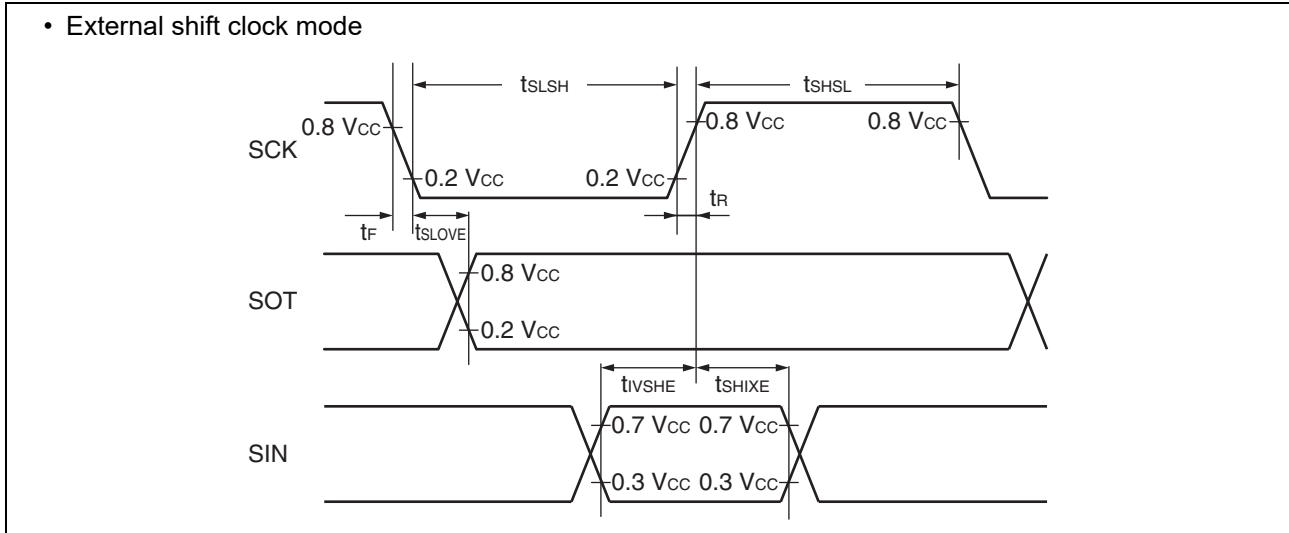
Sampling is executed at the rising edge of the sampling clock*¹, and serial clock delay is disabled*².
 (ESCR register : SCES bit = 0, ECCR register : SCDE bit = 0)

(V_{CC} = 5.0 V±10%, V_{SS} = 0.0 V, T_A = -40°C to +85°C)

| Parameter | Symbol | Pin name | Condition | Value | | Unit |
|------------------------------|--------------------|----------|--|---|---|------|
| | | | | Min | Max | |
| Serial clock cycle time | t _{SCYC} | SCK | Internal clock operation output pin: C _L = 80 pF + 1 TTL | 5 t _{MCLK} * ³ | — | ns |
| SCK↓ → SOT delay time | t _{SLOVI} | SCK, SOT | | -50 | +50 | ns |
| Valid SIN → SCK↑ | t _{IVSHI} | SCK, SIN | | t _{MCLK} * ³ + 80 | — | ns |
| SCK↑ → valid SIN hold time | t _{SHIXI} | SCK, SIN | | 0 | — | ns |
| Serial clock “L” pulse width | t _{SLSH} | SCK | External clock operation output pin: C _L = 80 pF + 1 TTL | 3 t _{MCLK} * ³ - t _R | — | ns |
| Serial clock “H” pulse width | t _{SHSL} | SCK | | t _{MCLK} * ³ + 10 | — | ns |
| SCK↓ → SOT delay time | t _{SLOVE} | SCK, SOT | | — | 2 t _{MCLK} * ³ + 60 | ns |
| Valid SIN → SCK↑ | t _{IVSHE} | SCK, SIN | | 30 | — | ns |
| SCK↑ → valid SIN hold time | t _{SHIXE} | SCK, SIN | | t _{MCLK} * ³ + 30 | — | ns |
| SCK falling time | t _F | SCK | | — | 10 | ns |
| SCK rising time | t _R | SCK | | — | 10 | ns |

- *1: There is a function used to choose whether the sampling of reception data is performed at a rising edge or a falling edge of the serial clock.
- *2: The serial clock delay function is a function used to delay the output signal of the serial clock for half the clock.
- *3: See “Source Clock/Machine Clock” for t_{MCLK}.





Sampling is executed at the falling edge of the sampling clock*1, and serial clock delay is disabled*2.
 (ESCR register : SCES bit = 1, ECCR register : SCDE bit = 0)

(V_{CC} = 5.0 V ± 10%, V_{SS} = 0.0 V, T_A = -40°C to +85°C)

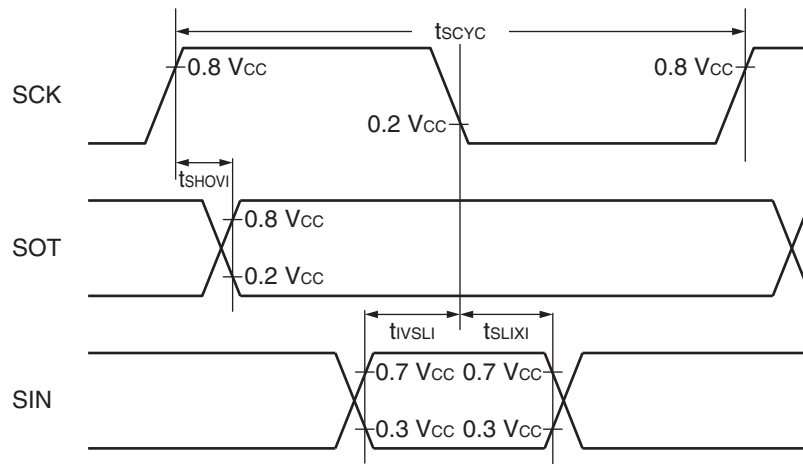
| Parameter | Symbol | Pin name | Condition | Value | | Unit |
|------------------------------|--------------------|----------|--|---|-----------------------------|------|
| | | | | Min | Max | |
| Serial clock cycle time | t _{SCYC} | SCK | Internal clock operation output pin: C _L = 80 pF + 1 TTL | 5 t _{MCLK} *3 | — | ns |
| SCK↑ → SOT delay time | t _{SHOVI} | SCK, SOT | | -50 | +50 | ns |
| Valid SIN → SCK↓ | t _{IVSLI} | SCK, SIN | | t _{MCLK} *3 + 80 | — | ns |
| SCK↓ → valid SIN hold time | t _{SLIXI} | SCK, SIN | | 0 | — | ns |
| Serial clock “H” pulse width | t _{SHSL} | SCK | External clock operation output pin: C _L = 80 pF + 1 TTL | 3 t _{MCLK} *3 - t _R | — | ns |
| Serial clock “L” pulse width | t _{SLSH} | SCK | | t _{MCLK} *3 + 10 | — | ns |
| SCK↑ → SOT delay time | t _{SHOVE} | SCK, SOT | | — | 2 t _{MCLK} *3 + 60 | ns |
| Valid SIN → SCK↓ | t _{IVSLE} | SCK, SIN | | 30 | — | ns |
| SCK↓ → valid SIN hold time | t _{SLIXE} | SCK, SIN | | t _{MCLK} *3 + 30 | — | ns |
| SCK falling time | t _F | SCK | | — | 10 | ns |
| SCK rising time | t _R | SCK | | — | 10 | ns |

*1: There is a function used to choose whether the sampling of reception data is performed at a rising edge or a falling edge of the serial clock.

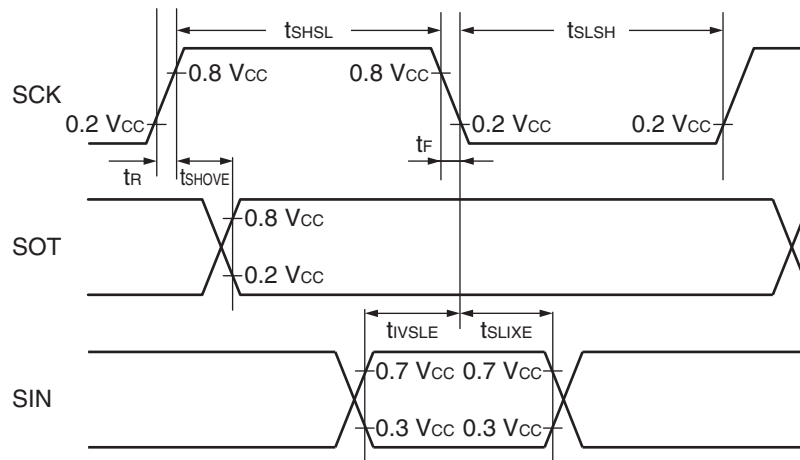
*2: The serial clock delay function is a function used to delay the output signal of the serial clock for half the clock.

*3: See “Source Clock/Machine Clock” for t_{MCLK}.

• Internal shift clock mode



• External shift clock mode



Sampling is executed at the rising edge of the sampling clock*¹, and serial clock delay is enabled*².
 (ESCR register : SCES bit = 0, ECCR register : SCDE bit = 1)

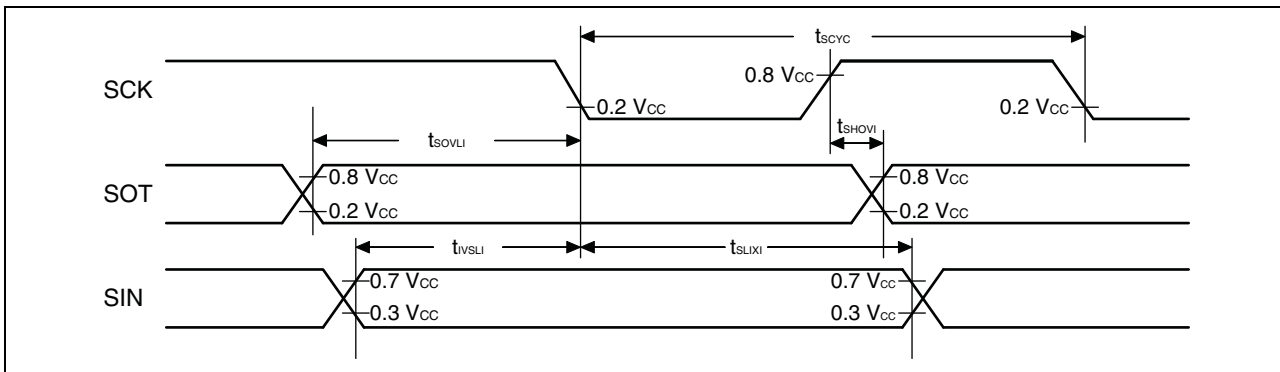
(V_{CC} = 5.0 V±10%, V_{SS} = 0.0 V, T_A = -40°C to +85°C)

| Parameter | Symbol | Pin name | Condition | Value | | Unit |
|----------------------------|--------------------|----------|--|--|-----|------|
| | | | | Min | Max | |
| Serial clock cycle time | t _{SCYC} | SCK | Internal clock operation output pin: C _L = 80 pF + 1 TTL | 5 t _{MCLK} * ³ | — | ns |
| SCK↑ → SOT delay time | t _{SHOVI} | SCK, SOT | | -50 | +50 | ns |
| Valid SIN → SCK↓ | t _{IVSLI} | SCK, SIN | | t _{MCLK} * ³ + 80 | — | ns |
| SCK↓ → valid SIN hold time | t _{SLIXI} | SCK, SIN | | 0 | — | ns |
| SOT → SCK↓ delay time | t _{SOVLI} | SCK, SOT | | 3t _{MCLK} * ³ - 70 | — | ns |

*1: There is a function used to choose whether the sampling of reception data is performed at a rising edge or a falling edge of the serial clock.

*2: The serial clock delay function is a function used to delay the output signal of the serial clock for half the clock.

*3: See “Source Clock/Machine Clock” for t_{MCLK}.



Sampling is executed at the falling edge of the sampling clock*¹, and serial clock delay is enabled*².

(ESCR register : SCES bit = 1, ECCR register : SCDE bit = 1)

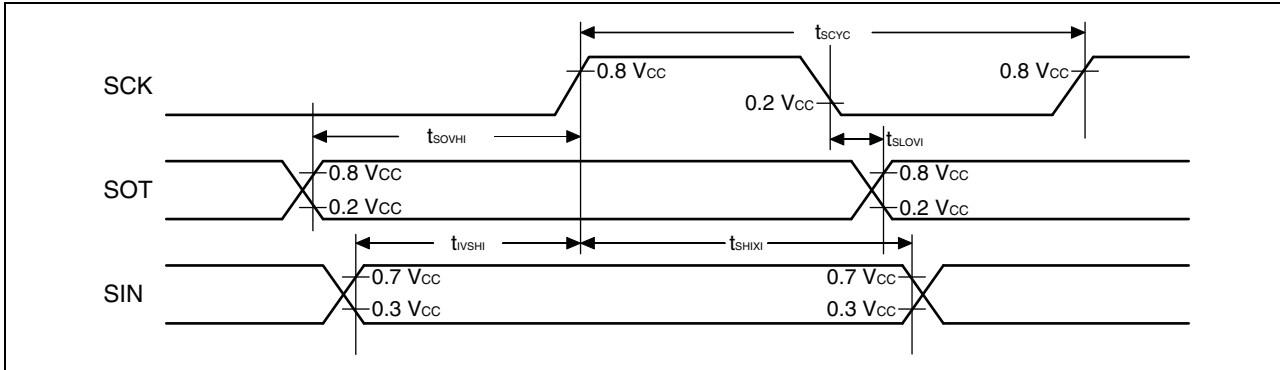
(V_{CC} = 5.0 V±10%, V_{SS} = 0.0 V, T_A = -40°C to +85°C)

| Parameter | Symbol | Pin name | Condition | Value | | Unit |
|----------------------------|--------------------|----------|--|--|-----|------|
| | | | | Min | Max | |
| Serial clock cycle time | t _{SCYC} | SCK | Internal clock operation output pin: C _L = 80 pF + 1 TTL | 5 t _{MCLK} * ³ | — | ns |
| SCK↓ → SOT delay time | t _{SLOVI} | SCK, SOT | | -50 | +50 | ns |
| Valid SIN → SCK↑ | t _{IVSHI} | SCK, SIN | | t _{MCLK} * ³ + 80 | — | ns |
| SCK↑ → valid SIN hold time | t _{SHIXI} | SCK, SIN | | 0 | — | ns |
| SOT → SCK↑ delay time | t _{SOVHI} | SCK, SOT | | 3t _{MCLK} * ³ - 70 | — | ns |

*1: There is a function used to choose whether the sampling of reception data is performed at a rising edge or a falling edge of the serial clock.

*2: The serial clock delay function is a function used to delay the output signal of the serial clock for half the clock.

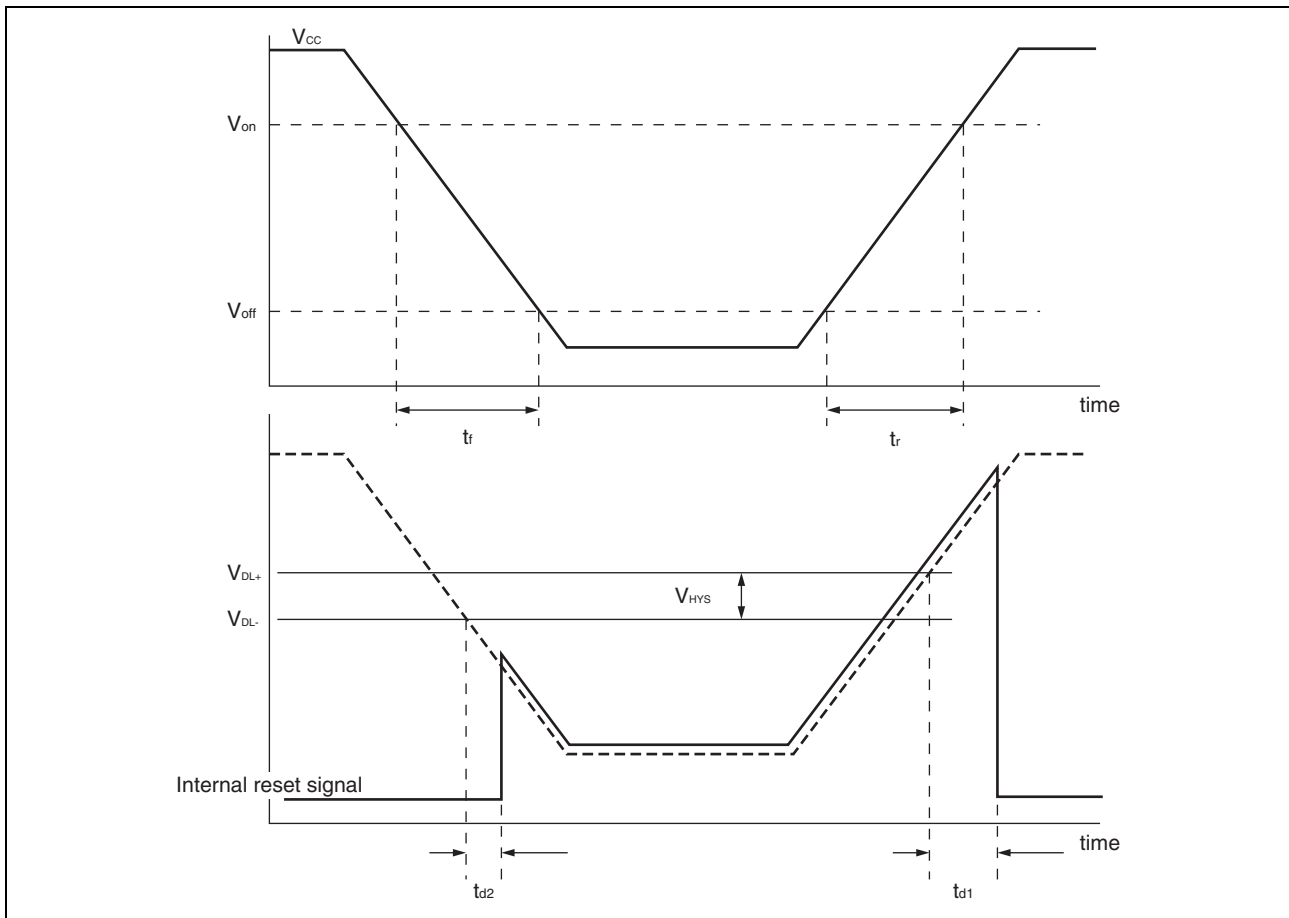
*3: See “Source Clock/Machine Clock” for t_{MCLK}.


18.4.7 Low-voltage Detection

 (V_{SS} = 0.0 V, T_A = -40°C to +85°C)

| Parameter | Symbol | Value | | | Unit | Remarks |
|---|------------------|-------|-----|------|------|---|
| | | Min | Typ | Max | | |
| Release voltage* | V _{DL+} | 2.52 | 2.7 | 2.88 | V | At power supply rise |
| | | 2.61 | 2.8 | 2.99 | | |
| | | 2.89 | 3.1 | 3.31 | | |
| | | 3.08 | 3.3 | 3.52 | | |
| Detection voltage* | V _{DL-} | 2.43 | 2.6 | 2.77 | V | At power supply fall |
| | | 2.52 | 2.7 | 2.88 | | |
| | | 2.80 | 3 | 3.20 | | |
| | | 2.99 | 3.2 | 3.41 | | |
| Hysteresis width | V _{HYS} | — | — | 100 | mV | |
| Power supply start voltage | V _{off} | — | — | 2.3 | V | |
| Power supply end voltage | V _{on} | 4.9 | — | — | V | |
| Power supply voltage change time (at power supply rise) | t _r | 650 | — | — | μs | Slope of power supply that the reset release signal generates within the rating (V _{DL+}) |
| Power supply voltage change time (at power supply fall) | t _r | 650 | — | — | μs | Slope of power supply that the reset detection signal generates within the rating (V _{DL-}) |
| Reset release delay time | t _{d1} | — | — | 30 | μs | |
| Reset detection delay time | t _{d2} | — | — | 30 | μs | |
| LVD reset threshold voltage transition stabilization time | t _{stb} | 10 | — | — | μs | |

*: The release voltage and the detection voltage can be selected by using the LVD reset voltage selection ID register (LVDR) in the low-voltage detection reset circuit. For details of the LVDR register, refer to “CHAPTER 16 LOW-VOLTAGE DETECTION RESET CIRCUIT” in “New 8FX CY95630H Series Hardware Manual”.

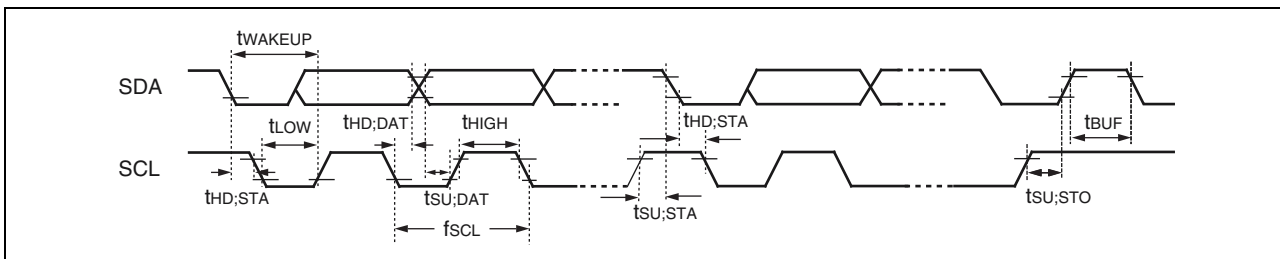


18.4.8 I²C Bus Interface Timing

(V_{CC} = 5.0 V ± 10%, V_{SS} = 0.0 V, T_A = -40°C to +85°C)

| Parameter | Symbol | Pin name | Condition | Value | | | | Unit |
|--|---------------------|----------|----------------------------|---------------|--------|-----------|-------|------|
| | | | | Standard-mode | | Fast-mode | | |
| | | | | Min | Max | Min | Max | |
| SCL clock frequency | f _{SCL} | SCL | R = 1.7 kΩ, C = 50 pF*1 | 0 | 100 | 0 | 400 | kHz |
| (Repeated) START condition hold time SDA ↓ → SCL ↓ | t _{HD;STA} | SCL, SDA | | 4.0 | — | 0.6 | — | μs |
| SCL clock "L" width | t _{LOW} | SCL | | 4.7 | — | 1.3 | — | μs |
| SCL clock "H" width | t _{HIGH} | SCL | | 4.0 | — | 0.6 | — | μs |
| (Repeated) START condition setup time SCL ↑ → SDA ↓ | t _{SU;STA} | SCL, SDA | | 4.7 | — | 0.6 | — | μs |
| Data hold time SCL ↓ → SDA ↓↑ | t _{HD;DAT} | SCL, SDA | | 0 | 3.45*2 | 0 | 0.9*3 | μs |
| Data setup time SDA ↓↑ → SCL ↑ | t _{SU;DAT} | SCL, SDA | | 0.25 | — | 0.1 | — | μs |
| STOP condition setup time SCL ↑ → SDA ↑ | t _{SU;STO} | SCL, SDA | | 4 | — | 0.6 | — | μs |
| Bus free time between STOP condition and START condition | t _{BUF} | SCL, SDA | | 4.7 | — | 1.3 | — | μs |

- *1: R represents the pull-up resistor of the SCL and SDA lines, and C the load capacitor of the SCL and SDA lines.
- *2: The maximum t_{HD;DAT} in the Standard-mode is applicable only when the time during which the device is holding the SCL signal at "L" (t_{LOW}) does not extend.
- *3: A Fast-mode I²C-bus device can be used in a Standard-mode I²C-bus system, provided that the condition of t_{SU;DAT} ≥ 250 ns is fulfilled.



(V_{CC} = 5.0 V ± 10%, V_{SS} = 0.0 V, T_A = -40°C to +85°C)

| Parameter | Symbol | Pin name | Condition | Value*2 | | Unit | Remarks |
|--|---------------------|----------|----------------------------|----------------------------|----------------------------|--------------|--|
| | | | | Min | Max | | |
| SCL clock "L" width | t _{LOW} | SCL | R = 1.7 kΩ, C = 50 pF*1 | $(2 + nm/2)t_{MCLK} - 20$ | — | ns | Master mode |
| SCL clock "H" width | t _{HIGH} | SCL | | $(nm/2)t_{MCLK} - 20$ | $(nm/2)t_{MCLK} + 20$ | ns | Master mode |
| START condition hold time | t _{HD;STA} | SCL, SDA | | $(-1 + nm/2)t_{MCLK} - 20$ | $(-1 + nm)t_{MCLK} + 20$ | ns | Master mode Maximum value is applied when m, n = 1, 8. Otherwise, the minimum value is applied. |
| STOP condition setup time | t _{SU;STO} | SCL, SDA | | $(1 + nm/2)t_{MCLK} - 20$ | $(1 + nm/2)t_{MCLK} + 20$ | ns | Master mode |
| START condition setup time | t _{SU;STA} | SCL, SDA | | $(1 + nm/2)t_{MCLK} - 20$ | $(1 + nm/2)t_{MCLK} + 20$ | ns | Master mode |
| Bus free time between STOP condition and START condition | t _{BUF} | SCL, SDA | | $(2nm + 4)t_{MCLK} - 20$ | — | ns | |
| Data hold time | t _{HD;DAT} | SCL, SDA | | $3t_{MCLK} - 20$ | — | ns | Master mode |
| Data setup time | t _{SU;DAT} | SCL, SDA | | $(-2 + nm/2)t_{MCLK} - 20$ | $(-1 + nm/2)t_{MCLK} + 20$ | ns | Master mode It is assumed that "L" of SCL is not extended. The minimum value is applied to the first bit of continuous data. Otherwise, the maximum value is applied. |
| Setup time between clearing interrupt and SCL rising | t _{SU;INT} | SCL | | $(nm/2)t_{MCLK} - 20$ | $(1 + nm/2)t_{MCLK} + 20$ | ns | The minimum value is applied to the interrupt at the ninth SCL↓. The maximum value is applied to the interrupt at the eighth SCL↓. |
| SCL clock "L" width | t _{LOW} | SCL | | $4t_{MCLK} - 20$ | — | ns | At reception |
| SCL clock "H" width | t _{HIGH} | SCL | $4t_{MCLK} - 20$ | — | ns | At reception | |

(Continued)

 ($V_{CC} = 5.0 V \pm 10\%$, $V_{SS} = 0.0 V$, $T_A = -40^\circ C$ to $+85^\circ C$)

| Parameter | Symbol | Pin name | Condition | Value*2 | | Unit | Remarks |
|--|--------------|----------|-------------------------------------|---|-----|------|--|
| | | | | Min | Max | | |
| START condition detection | $t_{HD;STA}$ | SCL, SDA | R = 1.7 k Ω , C = 50 pF*1 | $2 t_{MCLK} - 20$ | — | ns | No START condition is detected when 1 t_{MCLK} is used at reception. |
| STOP condition detection | $t_{SU;STO}$ | SCL, SDA | | $2 t_{MCLK} - 20$ | — | ns | No STOP condition is detected when 1 t_{MCLK} is used at reception. |
| RESTART condition detection condition | $t_{SU;STA}$ | SCL, SDA | | $2 t_{MCLK} - 20$ | — | ns | No RESTART condition is detected when 1 t_{MCLK} is used at reception. |
| Bus free time | t_{BUF} | SCL, SDA | | $2 t_{MCLK} - 20$ | — | ns | At reception |
| Data hold time | $t_{HD;DAT}$ | SCL, SDA | | $2 t_{MCLK} - 20$ | — | ns | At slave transmission mode |
| Data setup time | $t_{SU;DAT}$ | SCL, SDA | | $t_{LOW} - 3 t_{MCLK} - 20$ | — | ns | At slave transmission mode |
| Data hold time | $t_{HD;DAT}$ | SCL, SDA | | 0 | — | ns | At reception |
| Data setup time | $t_{SU;DAT}$ | SCL, SDA | | $t_{MCLK} - 20$ | — | ns | At reception |
| SDA \downarrow \rightarrow SCL \uparrow (with wakeup function in use) | t_{WAKEUP} | SCL, SDA | | Oscillation stabilization wait time $+2 t_{MCLK} - 20$ | — | ns | |

*1: R represents the pull-up resistor of the SCL and SDA lines, and C the load capacitor of the SCL and SDA lines.

*2: • See “Source Clock/Machine Clock” for t_{MCLK} .

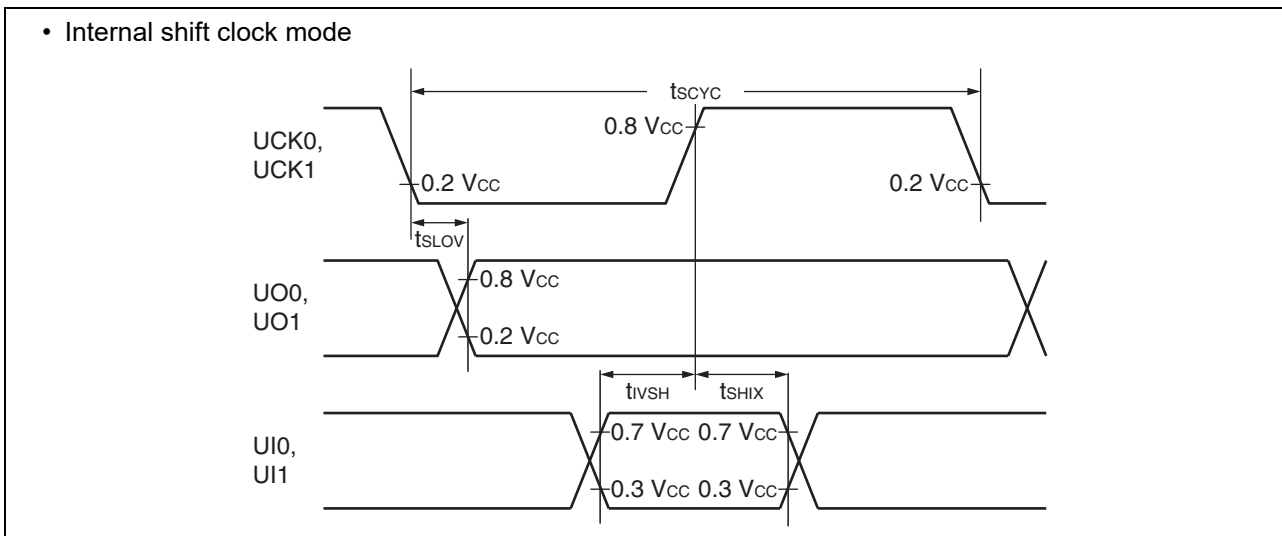
- m represents the CS[4:3] bits in the I²C clock control register ch. 0 (ICCR0).
- n represents the CS[2:0] bits in the I²C clock control register ch. 0 (ICCR0).
- The actual timing of the I²C bus interface is determined by the values of m and n set by the machine clock (t_{MCLK}) and the CS[4:0] bits in the ICCR0 register.
- Standard-mode:
 - m and n can be set to values in the following range: 0.9 MHz < t_{MCLK} (machine clock) < 16.25 MHz.
 - The usable frequencies of the machine clock are determined by the settings of m and n as shown below.
 - (m, n) = (1, 8) : 0.9 MHz < $t_{MCLK} \leq 1$ MHz
 - (m, n) = (1, 22), (5, 4), (6, 4), (7, 4), (8, 4) : 0.9 MHz < $t_{MCLK} \leq 2$ MHz
 - (m, n) = (1, 38), (5, 8), (6, 8), (7, 8), (8, 8) : 0.9 MHz < $t_{MCLK} \leq 4$ MHz
 - (m, n) = (1, 98), (5, 22), (6, 22), (7, 22) : 0.9 MHz < $t_{MCLK} \leq 10$ MHz
 - (m, n) = (8, 22) : 0.9 MHz < $t_{MCLK} \leq 16.25$ MHz
- Fast-mode:
 - m and n can be set to values in the following range: 3.3 MHz < t_{MCLK} (machine clock) < 16.25 MHz.
 - The usable frequencies of the machine clock are determined by the settings of m and n as shown below.
 - (m, n) = (1, 8) : 3.3 MHz < $t_{MCLK} \leq 4$ MHz
 - (m, n) = (1, 22), (5, 4) : 3.3 MHz < $t_{MCLK} \leq 8$ MHz
 - (m, n) = (1, 38), (6, 4), (7, 4), (8, 4) : 3.3 MHz < $t_{MCLK} \leq 10$ MHz
 - (m, n) = (5, 8) : 3.3 MHz < $t_{MCLK} \leq 16.25$ MHz

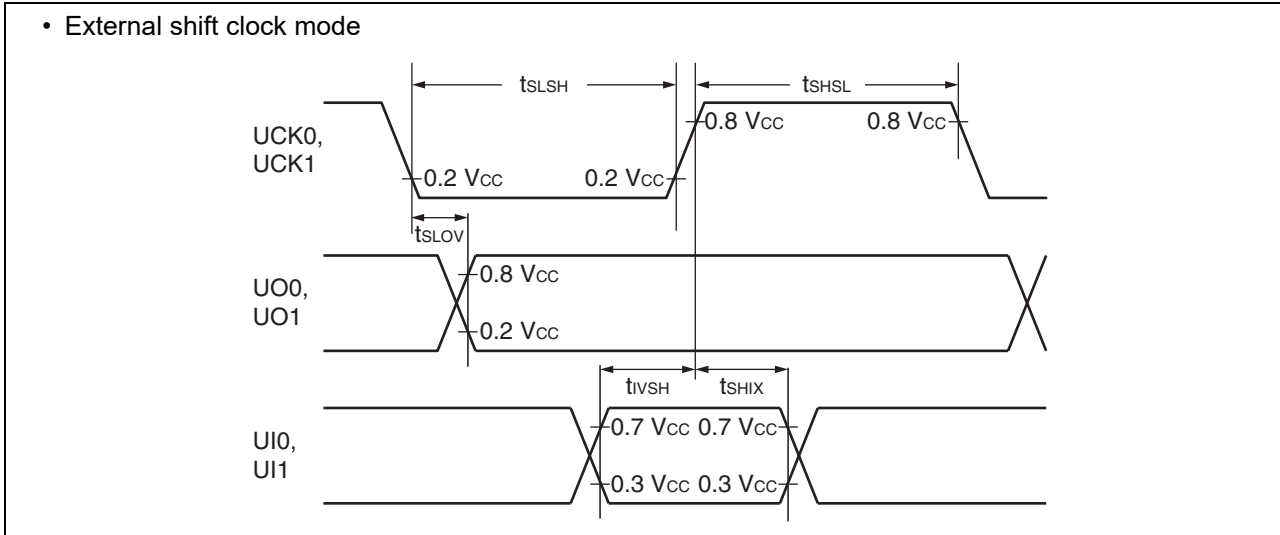
18.4.9 UART/SIO, Serial I/O Timing

($V_{CC} = 5.0 V \pm 10\%$, $V_{SS} = 0.0 V$, $T_A = -40^\circ C$ to $+85^\circ C$)

| Parameter | Symbol | Pin name | Condition | Value | | Unit |
|------------------------------|------------|-----------|--------------------------|----------------|------|------|
| | | | | Min | Max | |
| Serial clock cycle time | t_{SCYC} | UCK0 | Internal clock operation | $4 t_{MCLK}^*$ | — | ns |
| UCK ↓ → UO time | t_{SLOV} | UCK0, UO0 | | -190 | +190 | ns |
| Valid UI → UCK ↑ | t_{VSH} | UCK0, UI0 | | $2 t_{MCLK}^*$ | — | ns |
| UCK ↑ → valid UI hold time | t_{SHIX} | UCK0, UI0 | | $2 t_{MCLK}^*$ | — | ns |
| Serial clock "H" pulse width | t_{SHSL} | UCK0 | External clock operation | $4 t_{MCLK}^*$ | — | ns |
| Serial clock "L" pulse width | t_{SLSH} | UCK0 | | $4 t_{MCLK}^*$ | — | ns |
| UCK ↓ → UO time | t_{SLOV} | UCK0, UO0 | | — | 190 | ns |
| Valid UI → UCK ↑ | t_{VSH} | UCK0, UI0 | | $2 t_{MCLK}^*$ | — | ns |
| UCK ↑ → valid UI hold time | t_{SHIX} | UCK0, UI0 | $2 t_{MCLK}^*$ | — | ns | |

*: See "Source Clock/Machine Clock" for t_{MCLK} .

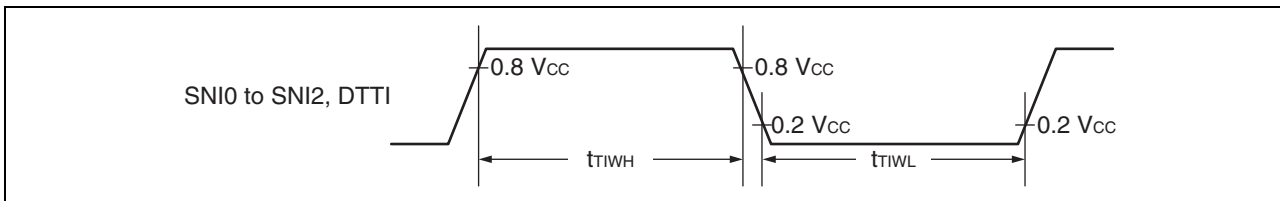




18.4.10 MPG Input Timing

(V_{CC} = 5.0 V ± 10%, V_{SS} = 0.0 V, T_A = -40°C to +85°C)

| Parameter | Symbol | Pin name | Condition | Value | | Unit | Remarks |
|-------------------|--|-----------------------|-----------|---------------------|-----|------|---------|
| | | | | Min | Max | | |
| Input pulse width | t _{TIWH} , t _{TIWL} | SNI0 to SNI2, DTTI | — | 4 t _{MCLK} | — | ns | |



18.4.11 Comparator Timing

(V_{CC} = 2.4 V to 5.5 V, V_{SS} = 0.0 V, T_A = -40°C to +85°C)

| Parameter | Pin name | Value | | | Unit | Remarks |
|-----------------------------|-------------------|-------|-----|-----------------------|------|---------------------------------------|
| | | Min | Typ | Max | | |
| Voltage range | CMP0_P, CMP0_N | 0 | — | V _{CC} - 1.3 | V | |
| Offset voltage | CMP0_P, CMP0_N | -15 | — | +15 | mV | |
| Delay time | CMP0_O | — | 650 | 1200 | ns | Overdrive 5 mV |
| | | — | 140 | 420 | ns | Overdrive 50 mV |
| Power down delay | CMP0_O | — | — | 1200 | ns | Power down recovery PD: 1 → 0 |
| Power up stabilization time | CMP0_O | — | — | 1200 | ns | Output stabilization time at power up |

18.5 A/D Converter
18.5.1 A/D Converter Electrical Characteristics
 $(V_{CC} = 2.7\text{ V to } 5.5\text{ V}, V_{SS} = 0.0\text{ V}, T_A = -40^\circ\text{C to } +85^\circ\text{C})$

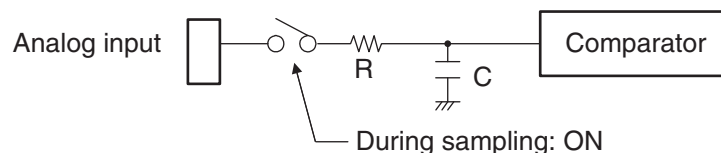
| Parameter | Symbol | Value | | | Unit | Remarks |
|-------------------------------|-----------|---------------------------|---------------------------|---------------------------|---------------|--|
| | | Min | Typ | Max | | |
| Resolution | — | — | — | 10 | bit | |
| Total error | | -3 | — | +3 | LSB | |
| Linearity error | | -2.5 | — | +2.5 | LSB | |
| Differential linearity error | | -1.9 | — | +1.9 | LSB | |
| Zero transition voltage | V_{0T} | $V_{SS} - 1.5\text{ LSB}$ | $V_{SS} + 0.5\text{ LSB}$ | $V_{SS} + 2.5\text{ LSB}$ | V | |
| Full-scale transition voltage | V_{FST} | $V_{CC} - 4.5\text{ LSB}$ | $V_{CC} - 2\text{ LSB}$ | $V_{CC} + 0.5\text{ LSB}$ | V | |
| Compare time | — | 3 | — | 10 | μs | $2.7\text{ V} \leq V_{CC} \leq 5.5\text{ V}$ |
| Sampling time | — | 0.941 | — | ∞ | μs | $2.7\text{ V} \leq V_{CC} \leq 5.5\text{ V}$, with external impedance < 3.3 k Ω and external capacitance = 10 pF |
| Analog input current | I_{AIN} | -0.3 | — | +0.3 | μA | |
| Analog input voltage | V_{AIN} | V_{SS} | — | V_{CC} | V | |

18.5.2 Notes on Using A/D Converter

- External impedance of analog input and its sampling time

The A/D converter of the CY95630H Series has a sample and hold circuit. If the external impedance is too high to keep sufficient sampling time, the analog voltage charged to the capacitor of the internal sample and hold circuit is insufficient, adversely affecting A/D conversion precision. Therefore, to satisfy the A/D conversion precision standard, considering the relationship between the external impedance and minimum sampling time, either adjust the register value and operating frequency or decrease the external impedance so that the sampling time is longer than the minimum value. In addition, if sufficient sampling time cannot be secured, connect a capacitor of about 0.1 μF to the analog input pin.

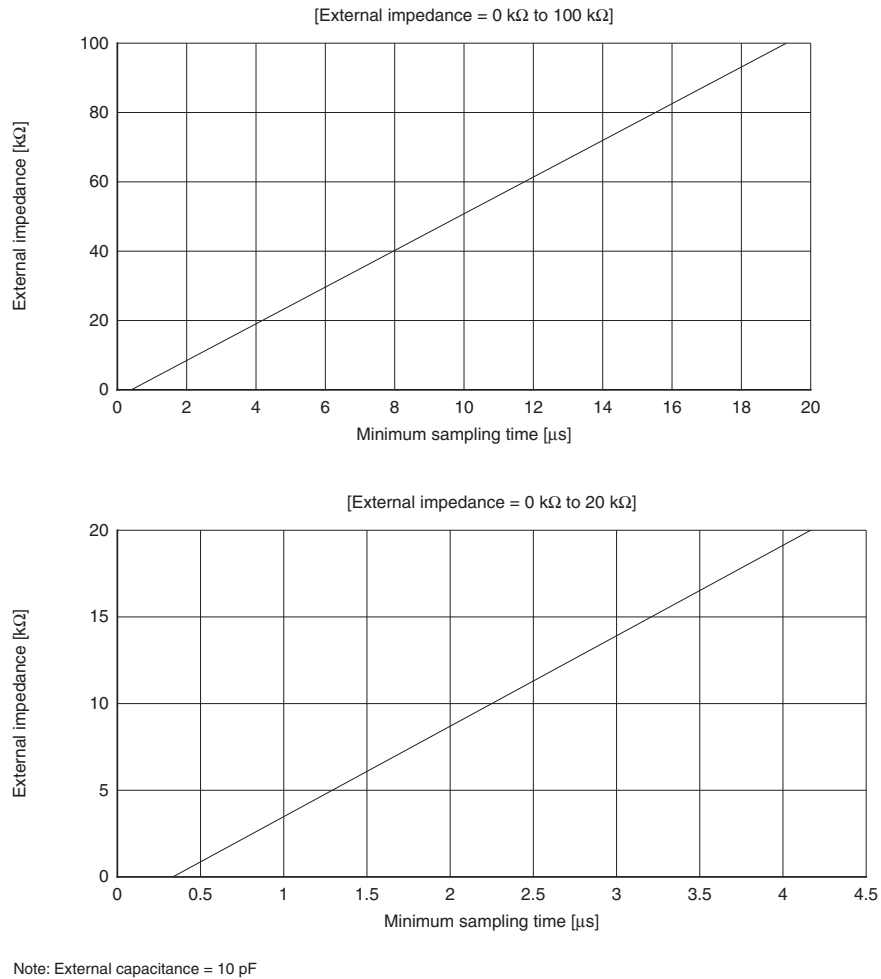
- Analog input equivalent circuit



| V_{CC} | R | C |
|--|-----------------------|----------------|
| $4.5\text{ V} \leq V_{CC} \leq 5.5\text{ V}$ | 1.45 k Ω (Max) | 14.89 pF (Max) |
| $2.7\text{ V} \leq V_{CC} < 4.5\text{ V}$ | 2.7 k Ω (Max) | 14.89 pF (Max) |

Note: The values are reference values.

- Relationship between external impedance and minimum sampling time



- A/D conversion error
As $|V_{CC} - V_{SS}|$ decreases, the A/D conversion error increases proportionately.

18.5.3 Definitions of A/D Converter Terms

- Resolution

It indicates the level of analog variation that can be distinguished by the A/D converter. When the number of bits is 10, analog voltage can be divided into $2^{10} = 1024$.

- Linearity error (unit: LSB)

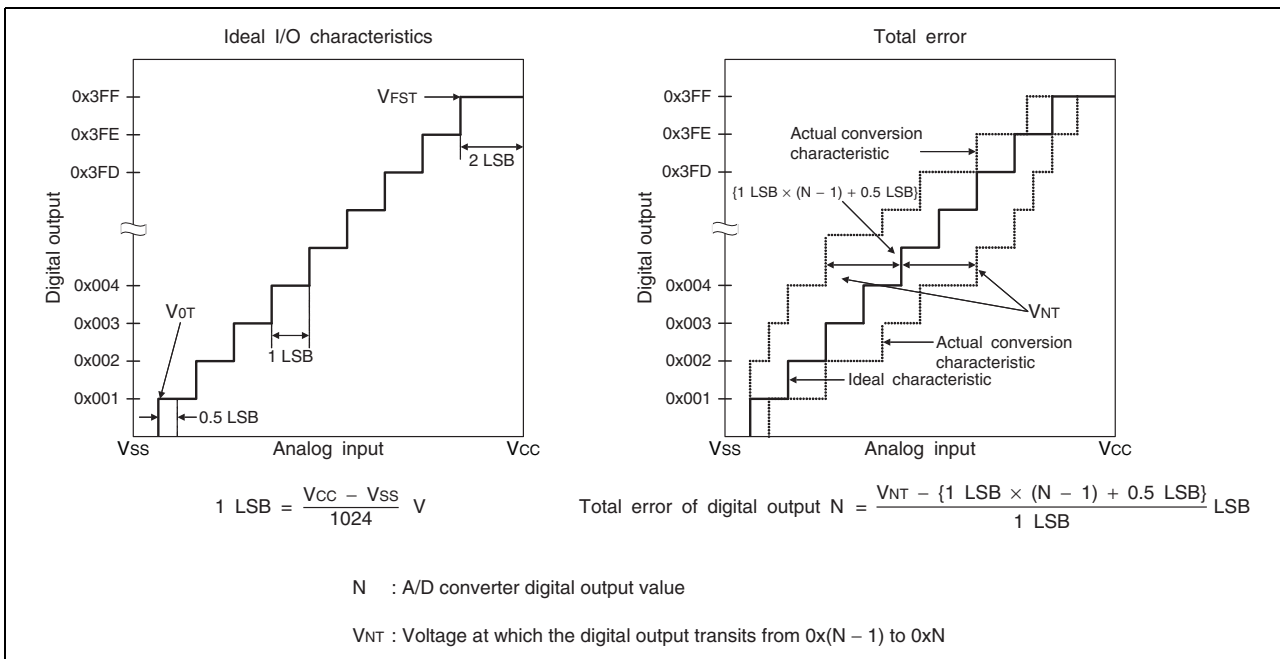
It indicates how much an actual conversion value deviates from the straight line connecting the zero transition point (“000000000”) ← → “000000001”) of a device to the full-scale transition point (“111111111” ← → “111111110”) of the same device.

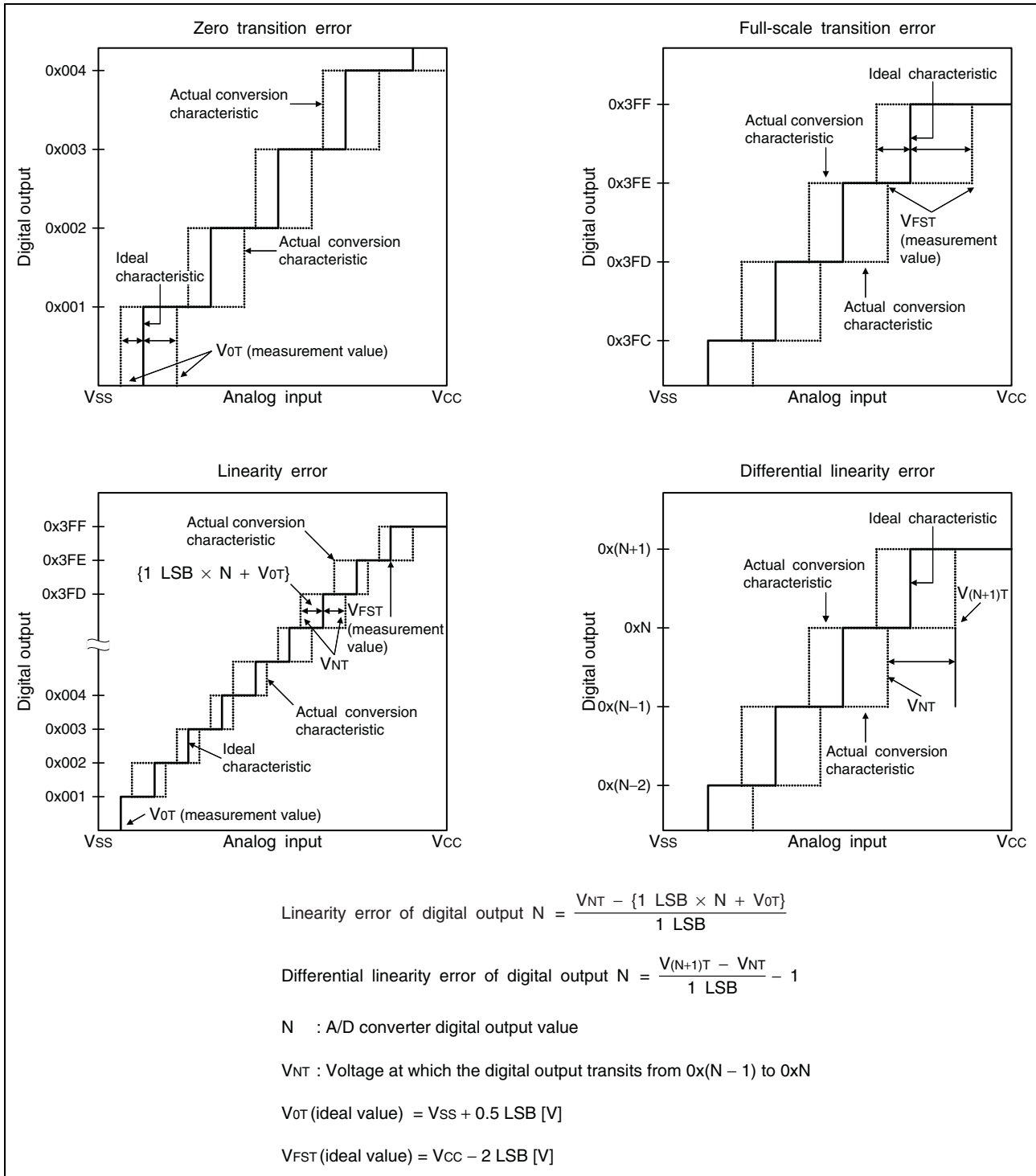
- Differential linear error (unit: LSB)

It indicates how much the input voltage required to change the output code by 1 LSB deviates from an ideal value.

- Total error (unit: LSB)

It indicates the difference between an actual value and a theoretical value. The error can be caused by a zero transition error, a full-scale transition errors, a linearity error, a quantum error, or noise.





18.6 Flash Memory Program/Erase Characteristics

| Parameter | Value | | | Unit | Remarks |
|--|------------------|-------------------|-------------------|-------|--|
| | Min | Typ | Max | | |
| Sector erase time (2 Kbyte sector) | — | 0.3 ^{*1} | 1.6 ^{*2} | s | The time of writing "0x00" prior to erasure is excluded. |
| Sector erase time (32 Kbyte sector) | — | 0.6 ^{*1} | 3.1 ^{*2} | s | The time of writing "0x00" prior to erasure is excluded. |
| Byte writing time | — | 17 | 272 | μs | System-level overhead is excluded. |
| Program/erase cycle | 100000 | — | — | cycle | |
| Power supply voltage at program/erase | 2.4 | — | 5.5 | V | |
| Flash memory data retention time | 20 ^{*3} | — | — | year | Average T _A = +85°C Number of program/erase cycles: 1000 or below |
| | 10 ^{*3} | — | — | | Average T _A = +85°C Number of program/erase cycles: 1001 to 10000 inclusive |
| | 5 ^{*3} | — | — | | Average T _A = +85°C Number of program/erase cycles: 10001 or above |

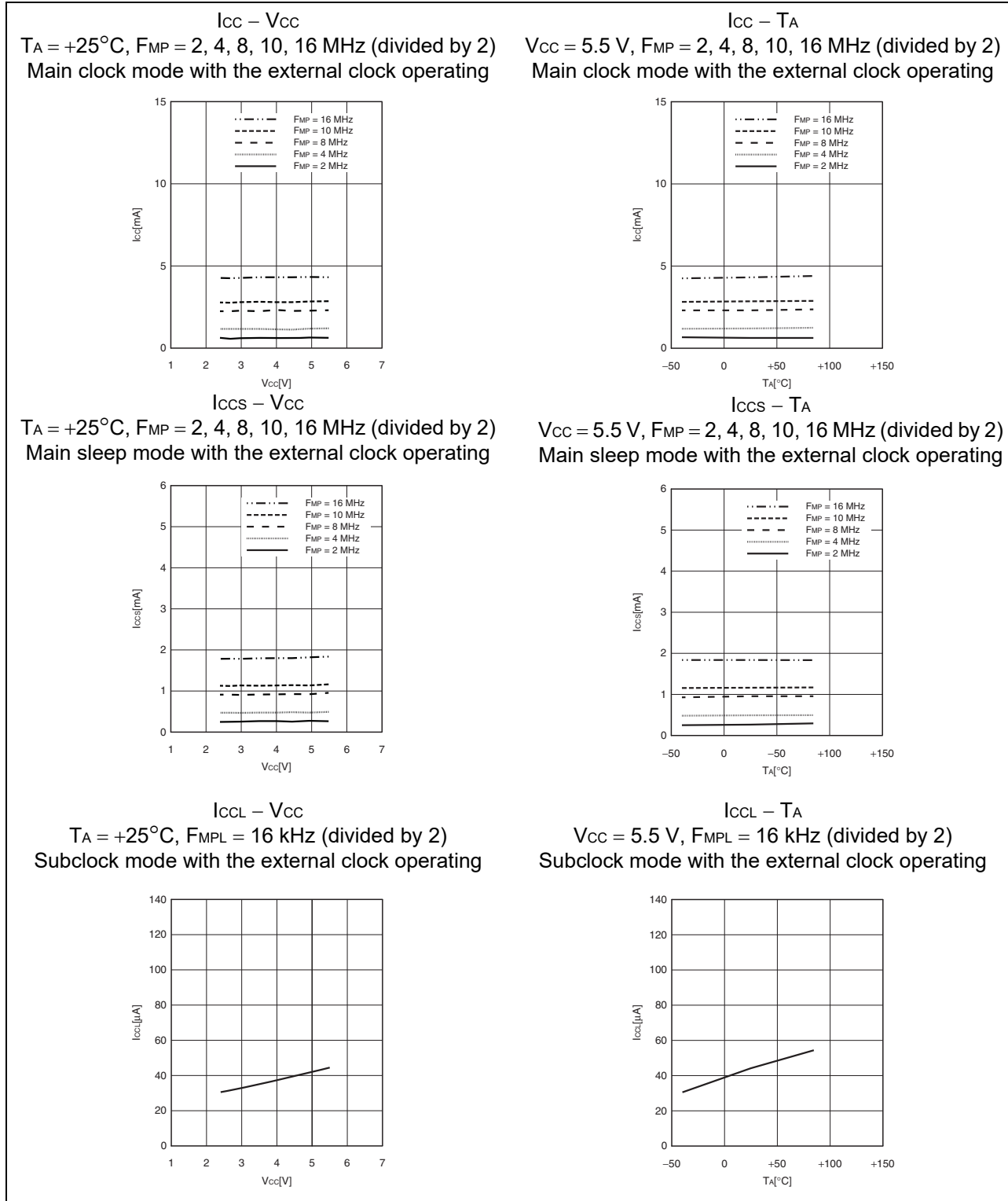
*1: V_{CC} = 5.5 V, T_A = +25°C, 0 cycle

*2: V_{CC} = 2.4 V, T_A = +85°C, 100000 cycles

*3: These values were converted from the result of a technology reliability assessment. (These values were converted from the result of a high temperature accelerated test using the Arrhenius equation with the average temperature being +85°C.)

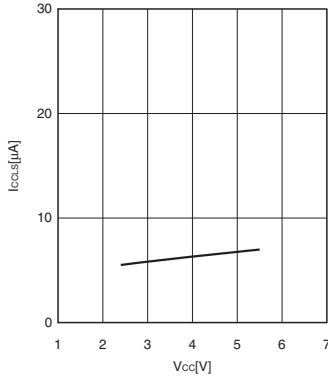
19. Sample Characteristics

- Power supply current temperature characteristics



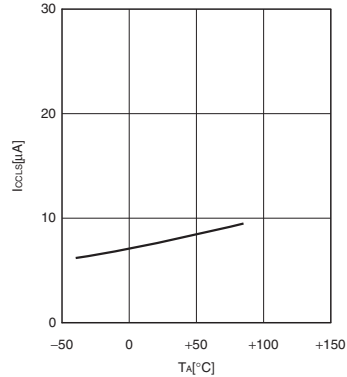
ICCLS – VCC

$T_A = +25^\circ\text{C}$, $F_{MPL} = 16\text{ kHz}$ (divided by 2)
Subsleep mode with the external clock operating



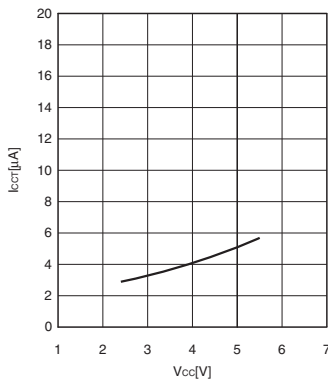
ICCLS – TA

$V_{CC} = 5.5\text{ V}$, $F_{MPL} = 16\text{ kHz}$ (divided by 2)
Subsleep mode with the external clock operating



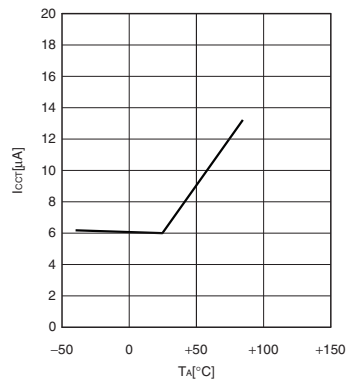
ICCT – VCC

$T_A = +25^\circ\text{C}$, $F_{MPL} = 16\text{ kHz}$ (divided by 2)
Watch mode with the external clock operating



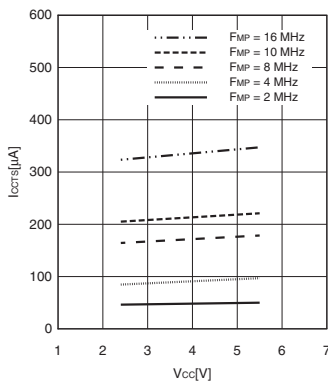
ICCT – TA

$V_{CC} = 5.5\text{ V}$, $F_{MPL} = 16\text{ kHz}$ (divided by 2)
Watch mode with the external clock operating



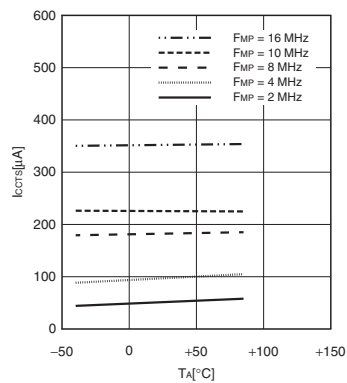
ICCTS – VCC

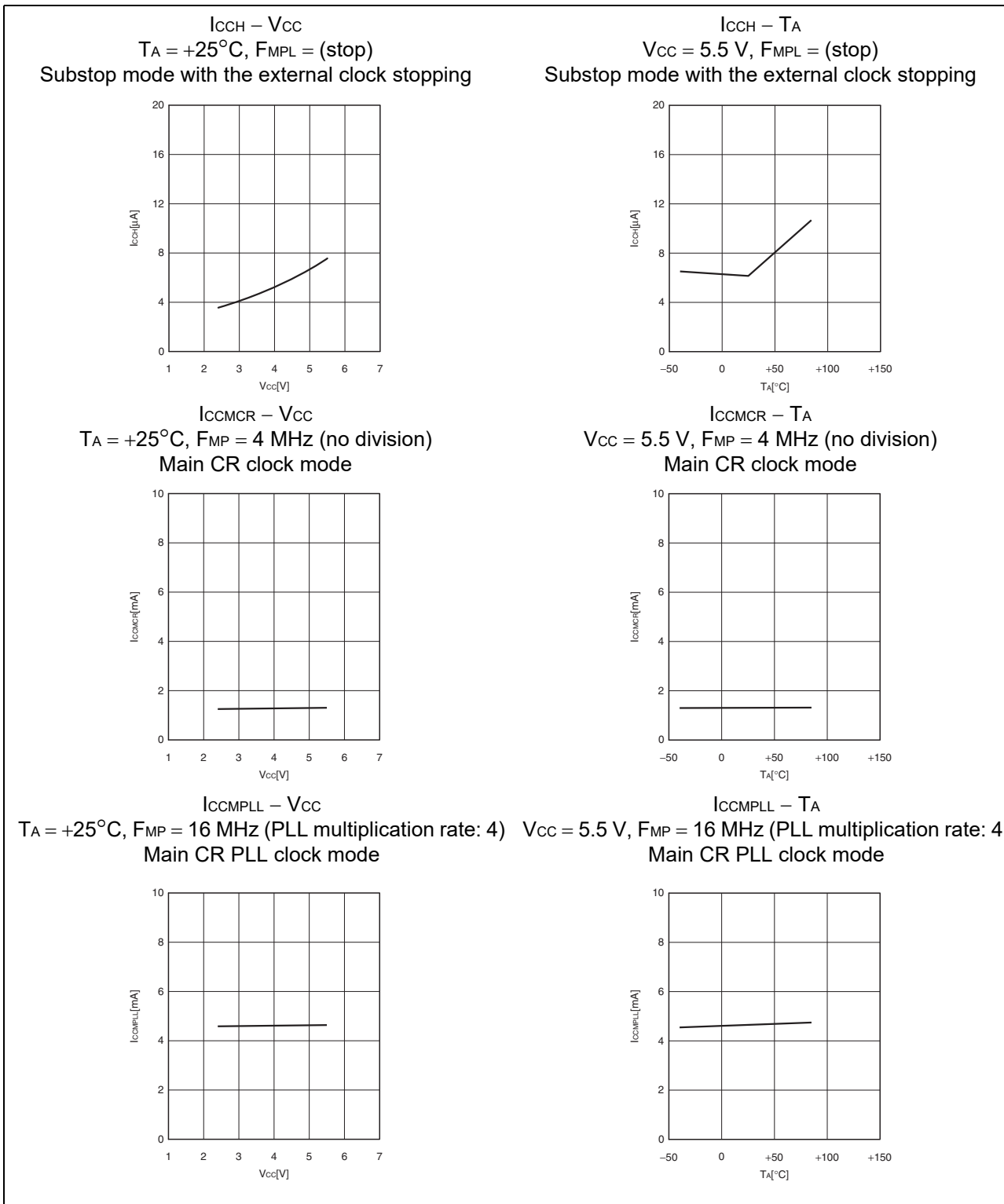
$T_A = +25^\circ\text{C}$, $F_{MP} = 2, 4, 8, 10, 16\text{ MHz}$ (divided by 2)
Time-base timer mode with the external clock operating

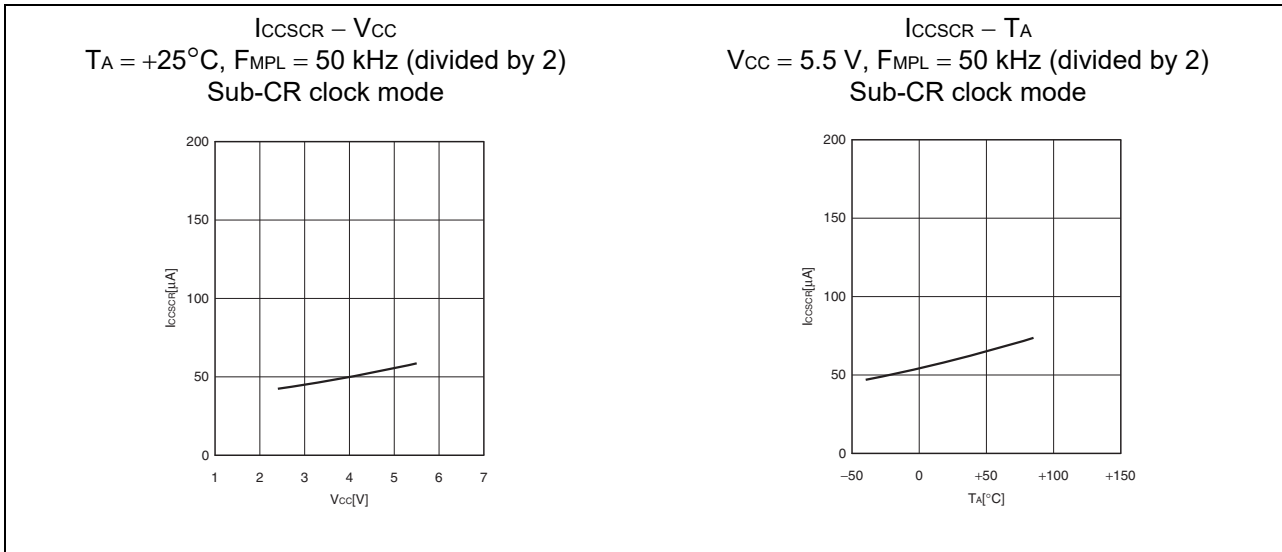


ICCTS – TA

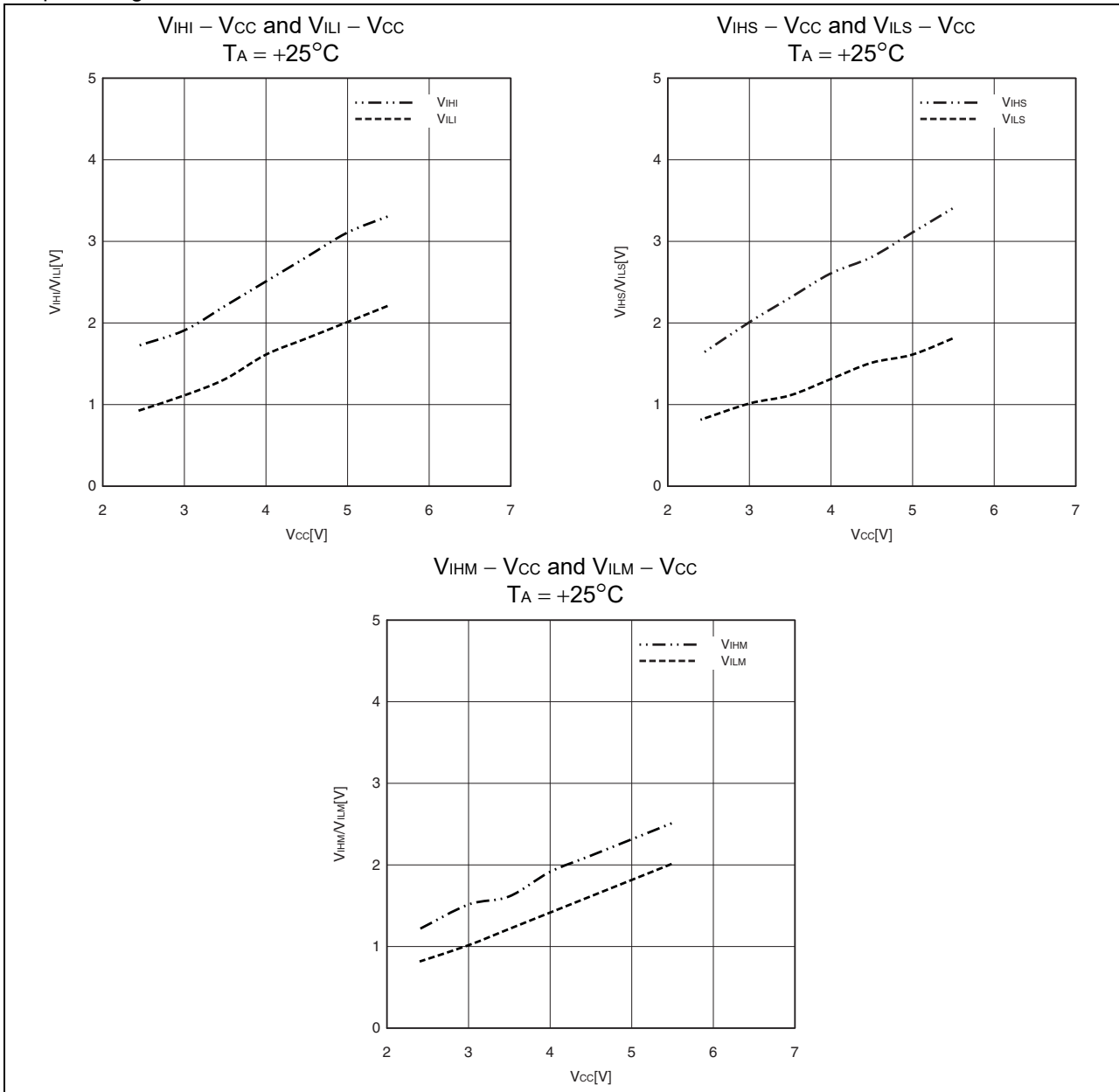
$V_{CC} = 5.5\text{ V}$, $F_{MP} = 2, 4, 8, 10, 16\text{ MHz}$ (divided by 2)
Time-base timer mode with the external clock operating



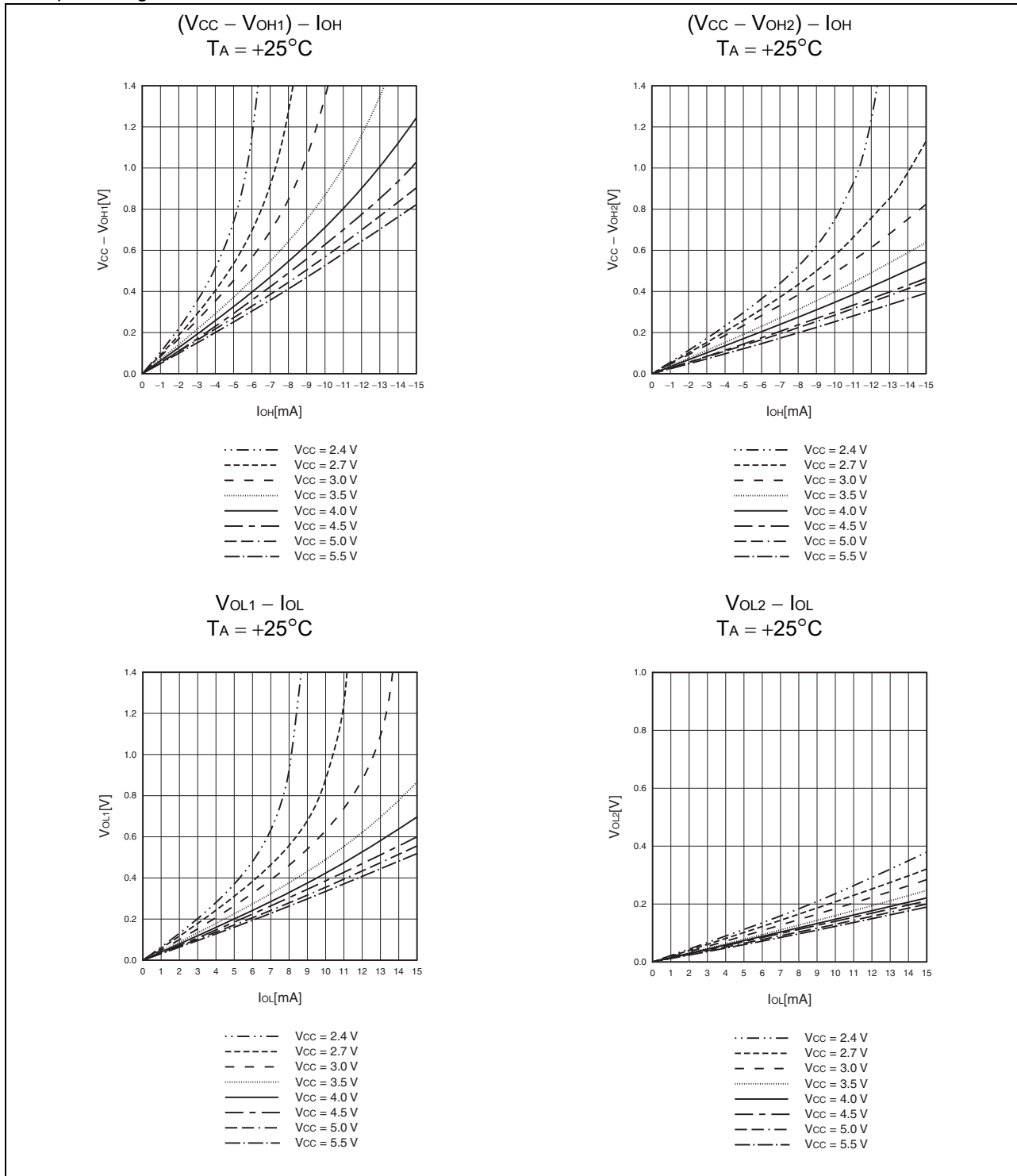




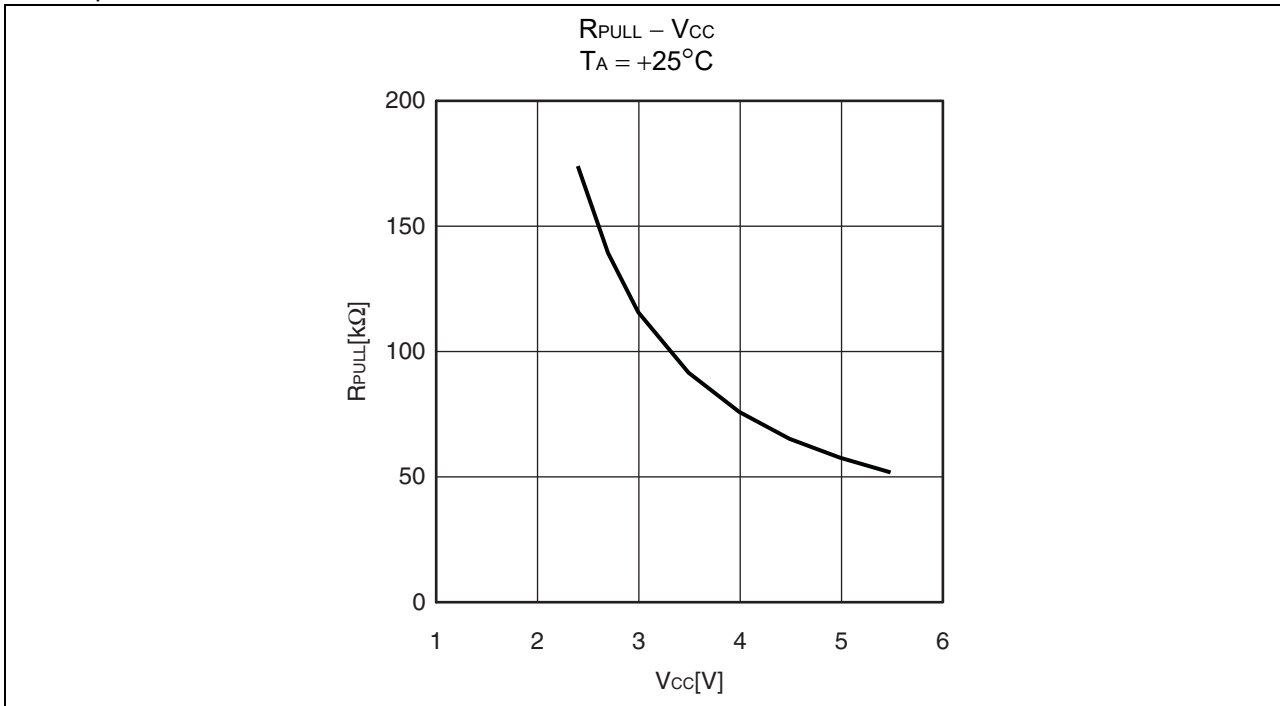
• Input voltage characteristics



• Output voltage characteristics



• Pull-up characteristics



20. Mask Options

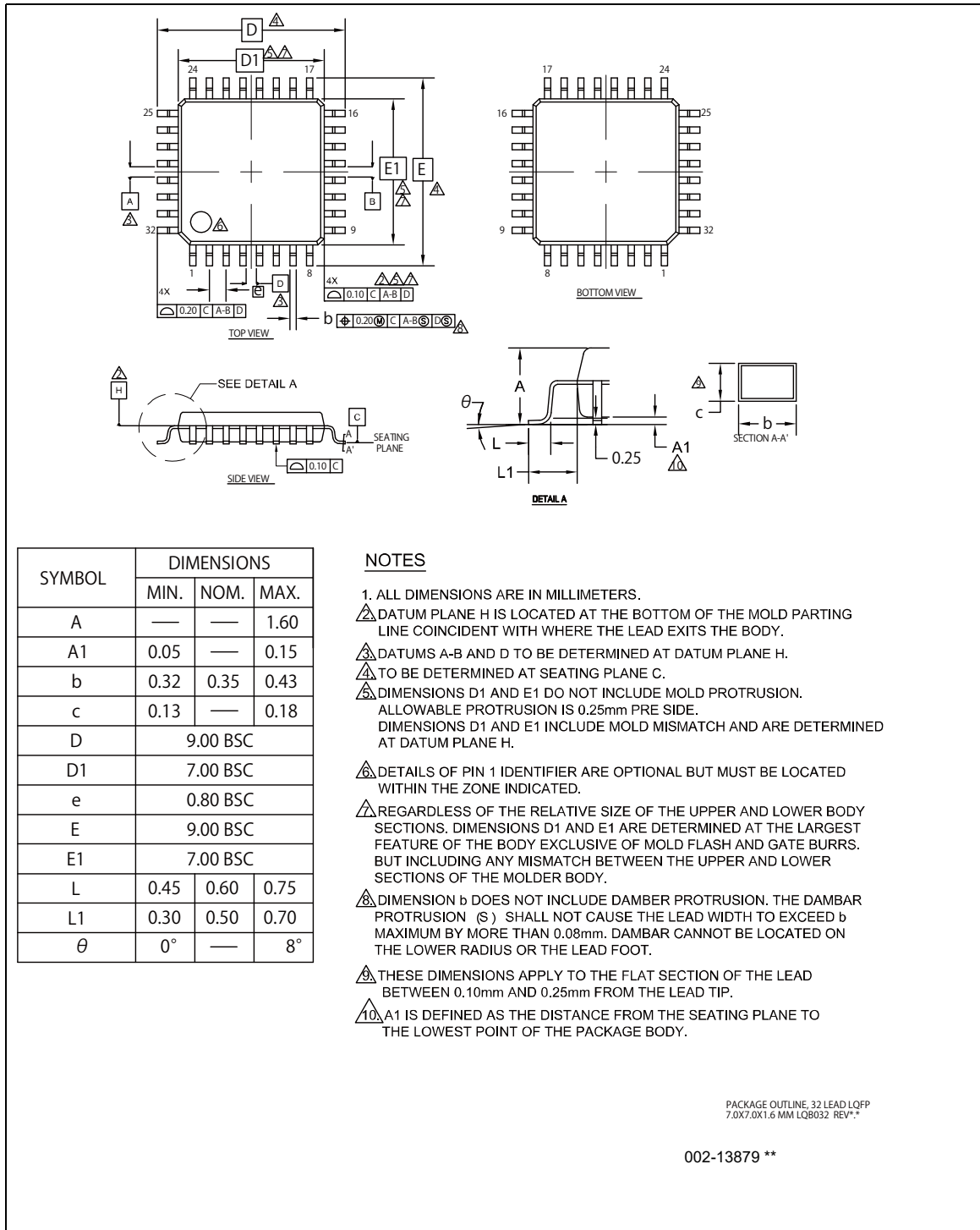
| | | | |
|------------|-----------------------------|--|--|
| No. | Part number | CY95F632H CY95F633H CY95F634H CY95F636H | CY95F632K CY95F633K CY95F634K CY95F636K |
| | Selectable/Fixed | Fixed | |
| 1 | Low-voltage detection reset | Without low-voltage detection reset | With low-voltage detection reset |
| 2 | Reset | With dedicated reset input | Without dedicated reset input |

21. Ordering Information

| Part number | Package | Packing |
|---|------------------------------|----------------|
| CY95F632KPMC-G-UNE2 CY95F633KPMC-G-UNE2 CY95F634HPMC-G-UNE2 CY95F634KPMC-G-UNE2 CY95F636KPMC-G-UNE2 | 32-pin plastic LQFP (LQB032) | Tray |
| CY95F633HPMC-G-UNERE2 | | Reel |

22. Package Dimension

| Package Type | Package Code |
|--------------|--------------|
| LQFP 32 | LQB032 |



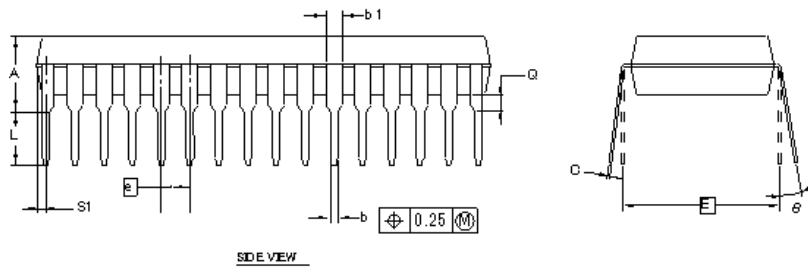
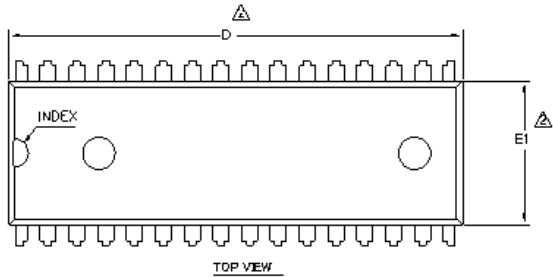
| SYMBOL | DIMENSIONS | | |
|----------|------------|------|------|
| | MIN. | NOM. | MAX. |
| A | — | — | 1.60 |
| A1 | 0.05 | — | 0.15 |
| b | 0.32 | 0.35 | 0.43 |
| c | 0.13 | — | 0.18 |
| D | 9.00 BSC | | |
| D1 | 7.00 BSC | | |
| e | 0.80 BSC | | |
| E | 9.00 BSC | | |
| E1 | 7.00 BSC | | |
| L | 0.45 | 0.60 | 0.75 |
| L1 | 0.30 | 0.50 | 0.70 |
| θ | 0° | — | 8° |

- NOTES**
- ALL DIMENSIONS ARE IN MILLIMETERS.
 - DATUM PLANE H IS LOCATED AT THE BOTTOM OF THE MOLD PARTING LINE COINCIDENT WITH WHERE THE LEAD EXITS THE BODY.
 - DATUMS A-B AND D TO BE DETERMINED AT DATUM PLANE H.
 - TO BE DETERMINED AT SEATING PLANE C.
 - DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25mm PRE SIDE. DIMENSIONS D1 AND E1 INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
 - DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED.
 - REGARDLESS OF THE RELATIVE SIZE OF THE UPPER AND LOWER BODY SECTIONS, DIMENSIONS D1 AND E1 ARE DETERMINED AT THE LARGEST FEATURE OF THE BODY EXCLUSIVE OF MOLD FLASH AND GATE BURRS, BUT INCLUDING ANY MISMATCH BETWEEN THE UPPER AND LOWER SECTIONS OF THE MOLDER BODY.
 - DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. THE DAMBAR PROTRUSION (S) SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED b MAXIMUM BY MORE THAN 0.08mm. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE LEAD FOOT.
 - THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10mm AND 0.25mm FROM THE LEAD TIP.
 - A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.

PACKAGE OUTLINE, 32 LEAD LQFP
7.0X7.0X1.6 MM LQB032, REV.*

002-13879 **

| | |
|---------------------|---------------------|
| Package Type | Package Code |
| SDIP 32 | PDS032 |



| SYMBOL | DIMENSIONS | | |
|----------|------------|-------|-------|
| | MIN. | NOM. | MAX. |
| A | 4.50 | 4.70 | 5.40 |
| L | 3.00 | 3.30 | 3.50 |
| D | 27.70 | 28.00 | 28.20 |
| E | 10.16 BSC | | |
| E1 | 8.64 | 8.89 | 9.14 |
| θ | 0° | — | 15° |
| c | 0.20 | 0.27 | 0.30 |
| b | 0.36 | 0.48 | 0.56 |
| b1 | 0.82 | 1.02 | 1.32 |
| e | 1.778 BSC | | |
| S1 | — | — | 1.27 |
| Q | 0.51 | — | — |

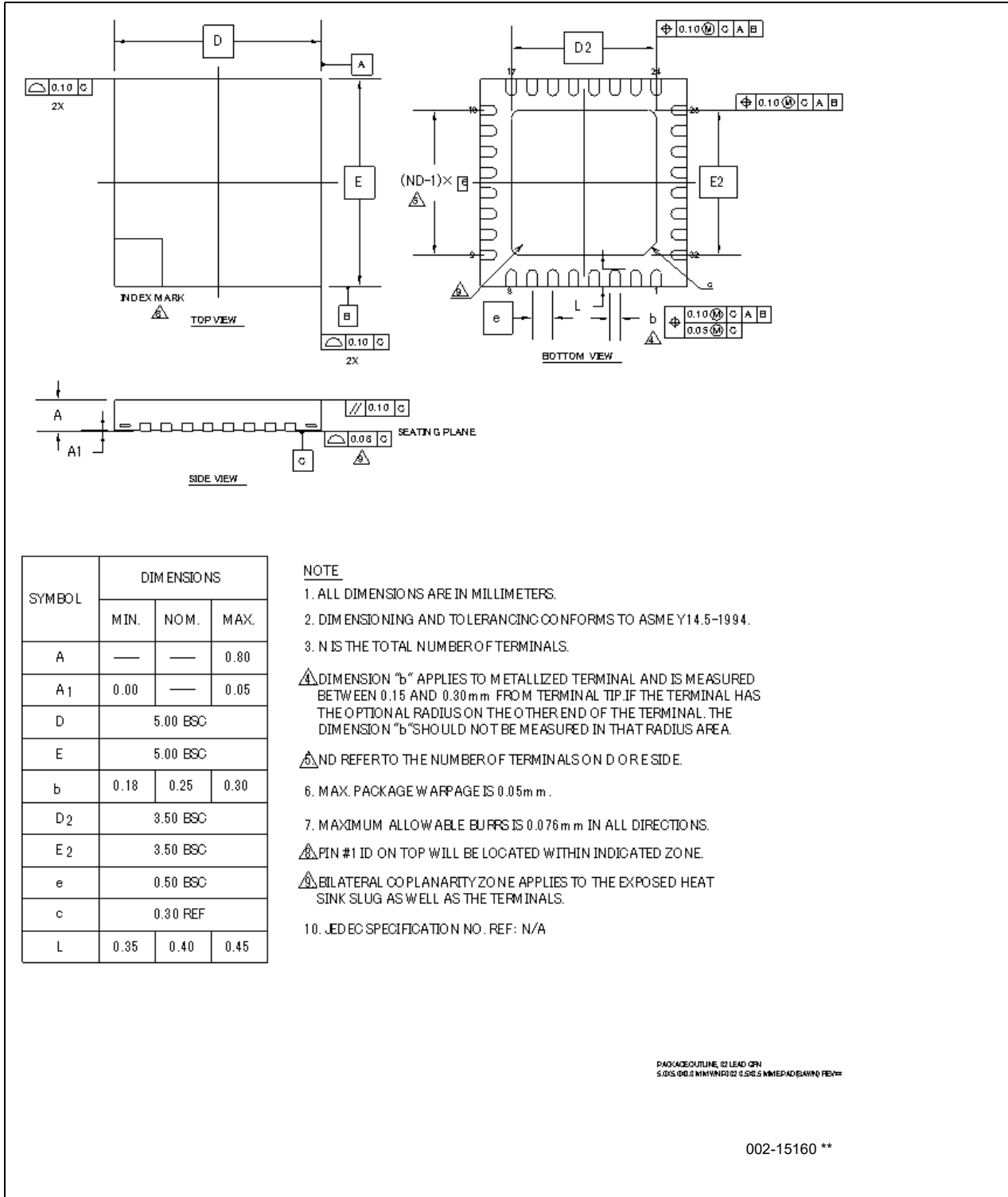
NOTES

1. ALL DIMENSIONS ARE IN MILLIMETER.
2. DIMENSIONS NOT INCLUDE RESIN REMAINING.
3. TERMINAL WIDTH AND TERMINAL THICKNESS INCLUDE PLATING THICKNESS.
4. JEDEC SPECIFICATION NO. REF : N/A

PACKAGE OUTLINE, 32 LEAD PDIP
28.00X8.89X4.19 NIM PDS032 REV**

002-16908 **

| | |
|---------------------|---------------------|
| Package Type | Package Code |
| QFN 32 | WNP032 |



| SYMBOL | DIMENSIONS | | |
|--------|------------|------|------|
| | MIN. | NOM. | MAX. |
| A | — | — | 0.80 |
| A1 | 0.00 | — | 0.05 |
| D | 5.00 BSC | | |
| E | 5.00 BSC | | |
| b | 0.18 | 0.25 | 0.30 |
| D2 | 3.50 BSC | | |
| E2 | 3.50 BSC | | |
| e | 0.50 BSC | | |
| c | 0.30 REF | | |
| L | 0.35 | 0.40 | 0.45 |

NOTE

- ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSIONING AND TOLERANCING CONFORMS TO ASME Y14.5-1994.
- N IS THE TOTAL NUMBER OF TERMINALS.
- △ DIMENSION "b" APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP IF THE TERMINAL HAS THE OPTIONAL RADIUS ON THE OTHER END OF THE TERMINAL, THE DIMENSION "b" SHOULD NOT BE MEASURED IN THAT RADIUS AREA.
- △ ND REFERS TO THE NUMBER OF TERMINALS ON D OR E SIDE.
- MAX. PACKAGE WARPAGE IS 0.05 mm.
- MAXIMUM ALLOWABLE BURRS IS 0.076 mm IN ALL DIRECTIONS.
- △ PIN #1 ID ON TOP WILL BE LOCATED WITHIN INDICATED ZONE.
- △ BILATERAL COPLANARITY ZONE APPLIES TO THE EXPOSED HEAT SINK SLUG AS WELL AS THE TERMINALS.
- JEDEC SPECIFICATION NO. REF: N/A

PACKAGE OUTLINE, 32 LEAD QFN
5.00x5.00x0.55 MM (WNP032) 3.50x3.50x0.55 MM (EAD032WNP) REF: 002-15160 **

002-15160 **

23. Major Changes In This Edition

Spanion Publication Number: DS702-00009

| Page | Section | Details |
|------|--|---|
| 22 | ■ PIN CONNECTION • C pin | Corrected the following statement. The bypass capacitor for the V _{CC} pin must have a capacitance larger than C _s . → The decoupling capacitor for the V _{CC} pin must have a capacitance equal to or larger than the capacitance of C _s . |
| 66 | ■ ELECTRICAL CHARACTERISTICS 2. Recommended Operating Conditions | Corrected the following statement in remark *2. The bypass capacitor for the V _{CC} pin must have a capacitance larger than C _s . → The decoupling capacitor for the V _{CC} pin must have a capacitance equal to or larger than the capacitance of C _s . |
| 71 | 4. AC Characteristics (1) Clock Timing | Corrected the pin names of the parameter “Input clock rising time and falling time”. X0 → X0, X0A X0, X1 → X0, X1, X0A, X1A |

NOTE: Please see “Document History” about later revised information.

Document History Page

| Document Title: CY95630H Series, New 8FX 8-bit Microcontrollers Document Number: 002-04627 | | | |
|---|---------|-----------------|--|
| Revision | ECN | Submission Date | Description of Change |
| ** | – | 06/07/2013 | Migrated to Cypress and assigned document number 002-04627. No change to document contents or format. |
| *A | 5193921 | 03/29/2016 | Updated Ordering Information: Updated part numbers. Updated to Cypress template. |
| *B | 5443796 | 02/06/2017 | Replaced “FPT-32P-M30” with “LQB032” in all instances across the document. Replaced “LCC-32P-M19” with “WNP032” in all instances across the document. Replaced “DIP-32P-M06” with “PDS032” in all instances across the document. Updated Ordering Information: Updated part numbers. |
| *C | 5746267 | 05/23/2017 | Updated Cypress Logo and Copyright. |
| *D | 5895915 | 09/27/2017 | Updated Ordering Information: Updated part numbers. Added a column “Packing” and added details in that column. |
| *E | 6599271 | 06/19/2019 | Updated Ordering Information: Updated part numbers. Updated to new template. |
| *F | 6730588 | 11/13/2019 | Updated series name and part number from prefix MB to prefix CY. |
| *G | 6748761 | 12/10/2019 | Added ordering part numbers: CY95F632KPMC-G-UNE2 CY95F633KPMC-G-UNE2 CY95F634KPMC-G-UNE2 CY95F636KPMC-G-UNE2 |

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